

Front-End electronics in particle physics

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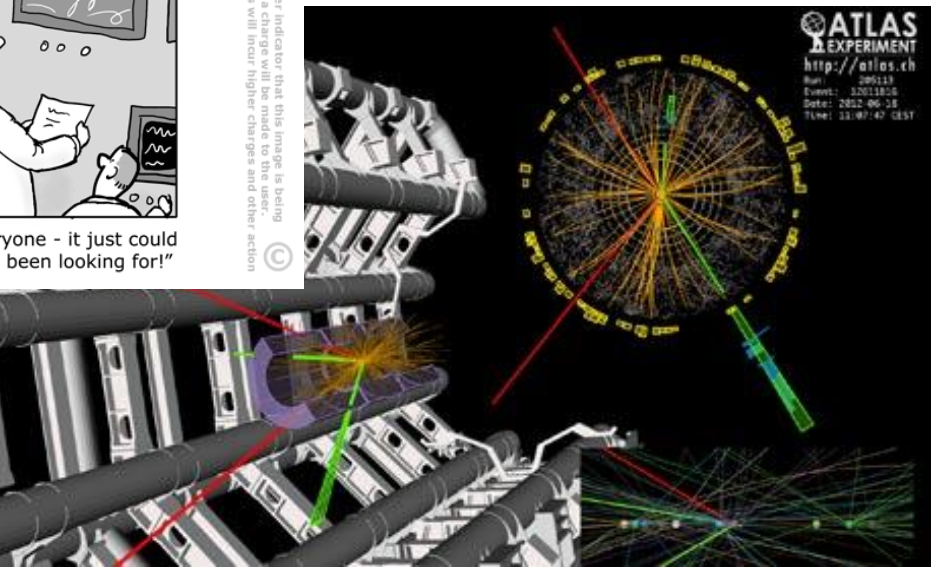
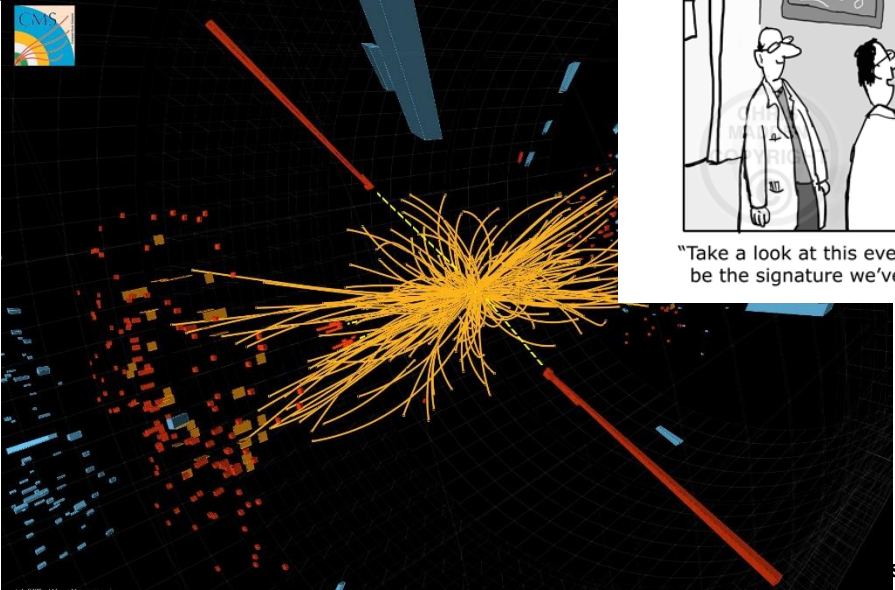
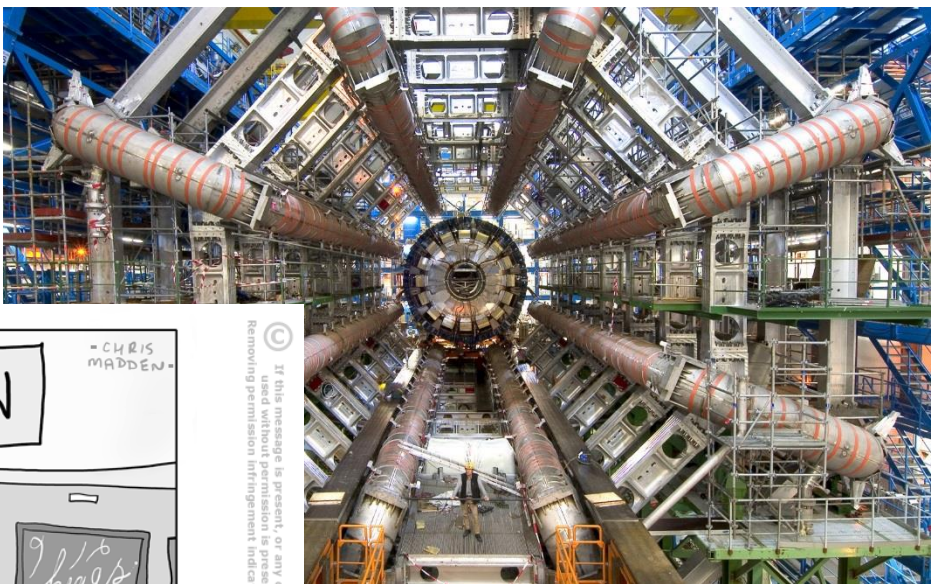
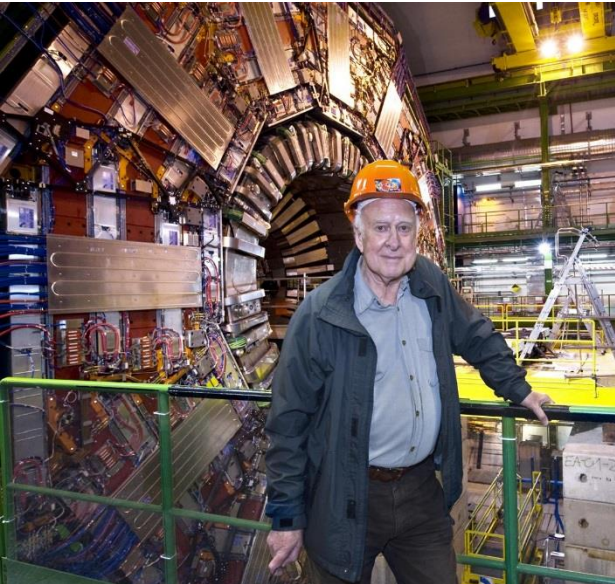
1. Low noise charge preamps : pixel readout
2. Large dynamic range : calorimeters
3. High speed designs : sipm readout
4. Trends and future

Lectures for physicists, not electronics engineers => will concentrate on front-end and performance of detector, not on detailed engineering

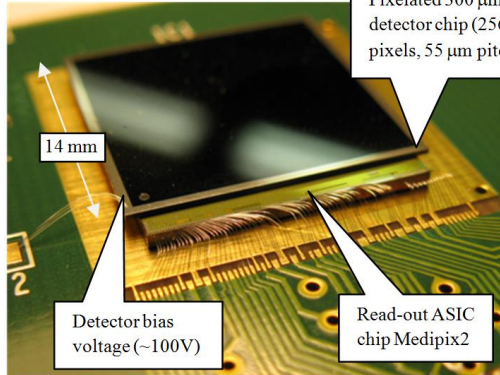
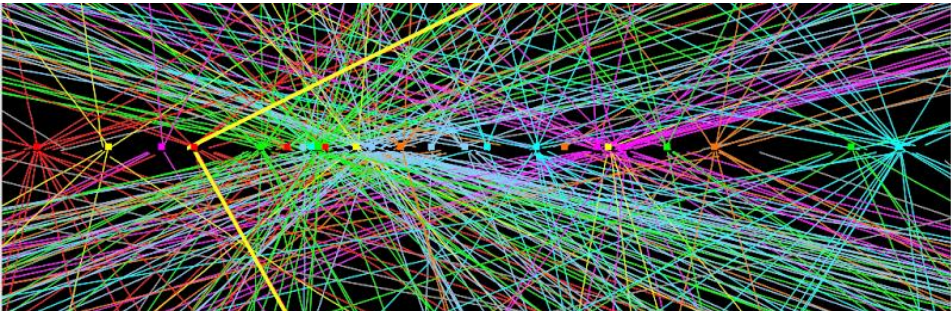
Many more slides than allocated time : don't be afraid !
I will skip many details : they are for further reference

No prerequisites needed (apart from $U = Z \cdot I$)

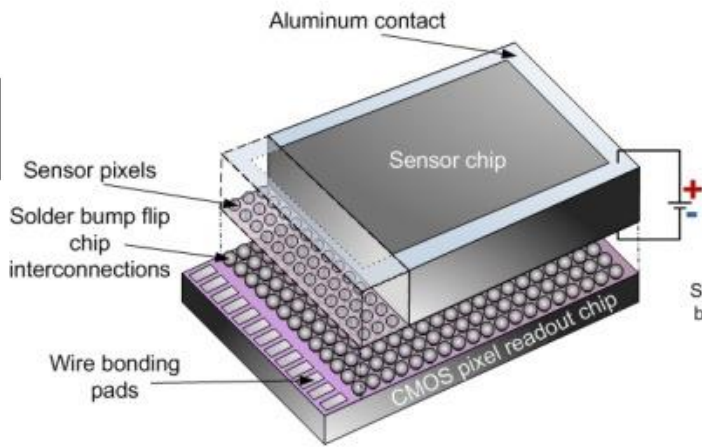
- A lot of electronics in the experiments...which impacts the detectors



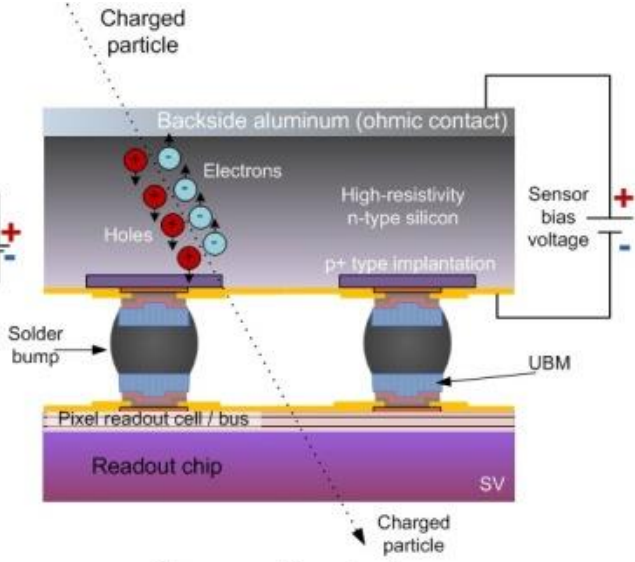
- Measurement of (charged) particle tracks
 - millions of pixels (~100 μm)
 - binary readout at 40 MHz
 - High radiation levels
 - Made possible by ASICs



Pixelated 300 μm thick Si detector chip (256 x 256 pixels, 55 μm pitch)



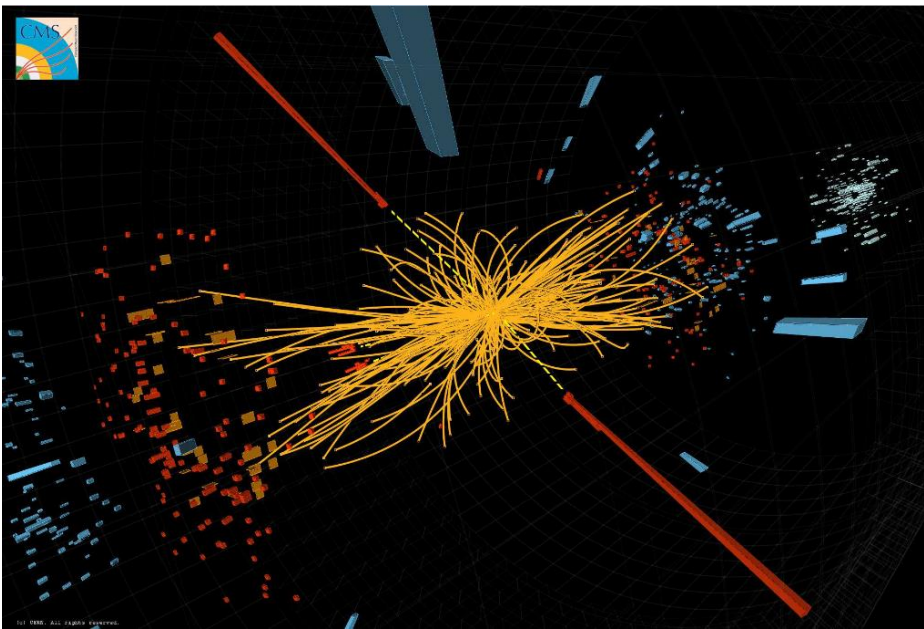
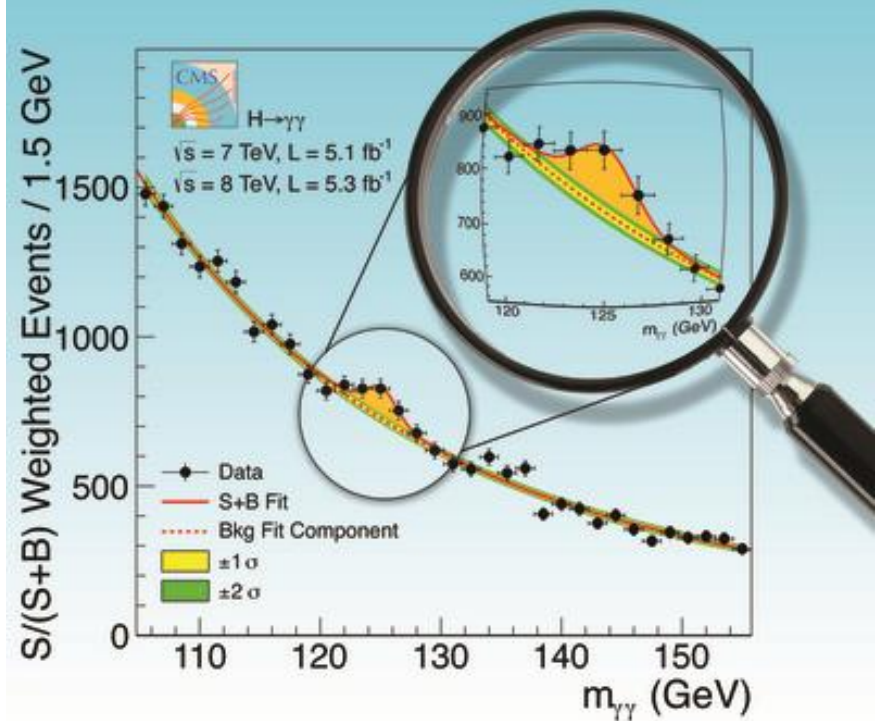
Generic pixel detector



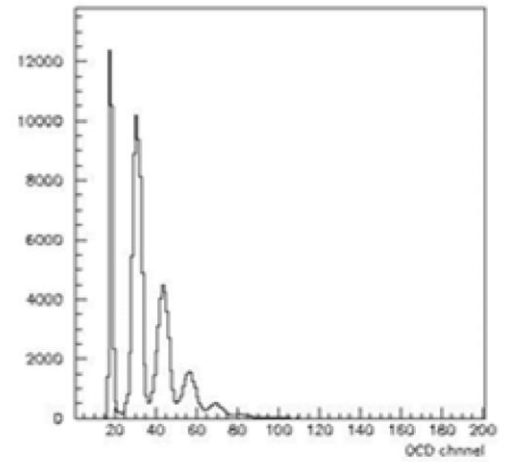
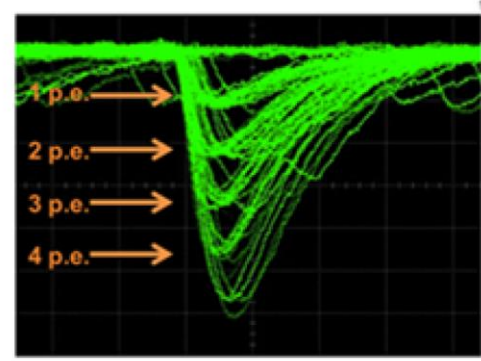
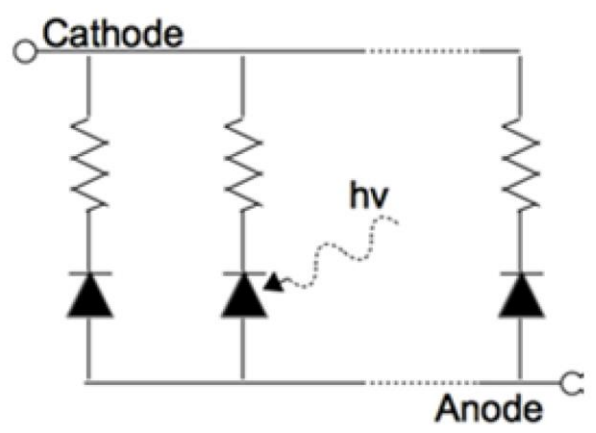
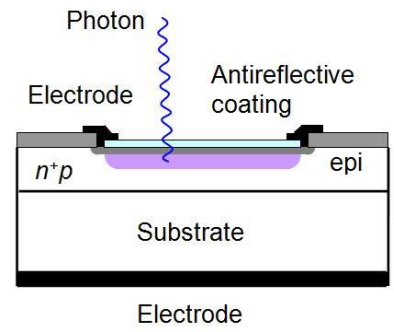
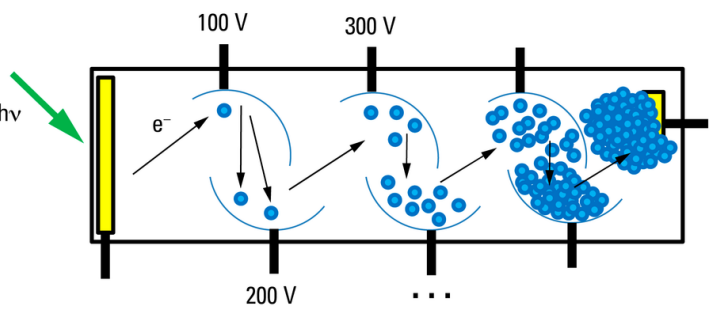
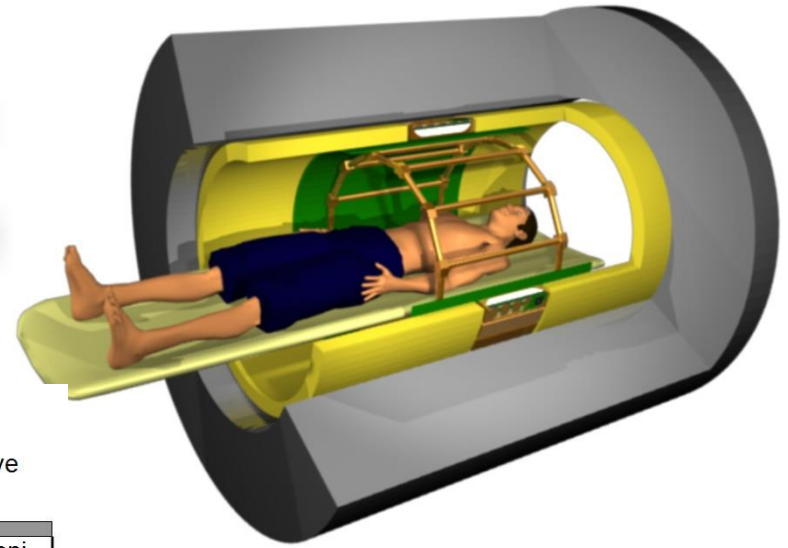
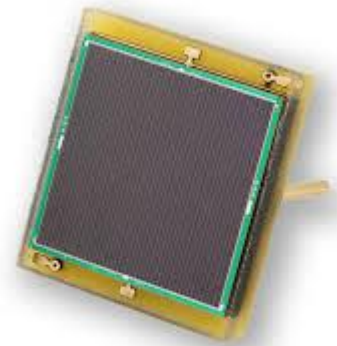
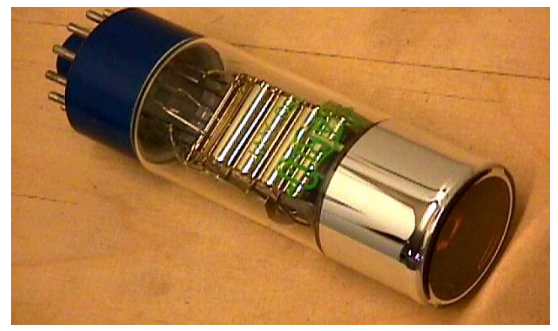
Cross-sectional cut

- Large dynamic range (10^4 - 10^5)
- High Precision $\sim 1\%$
 - Importance of low noise, uniformity, linearity...
 - Importance of calibration

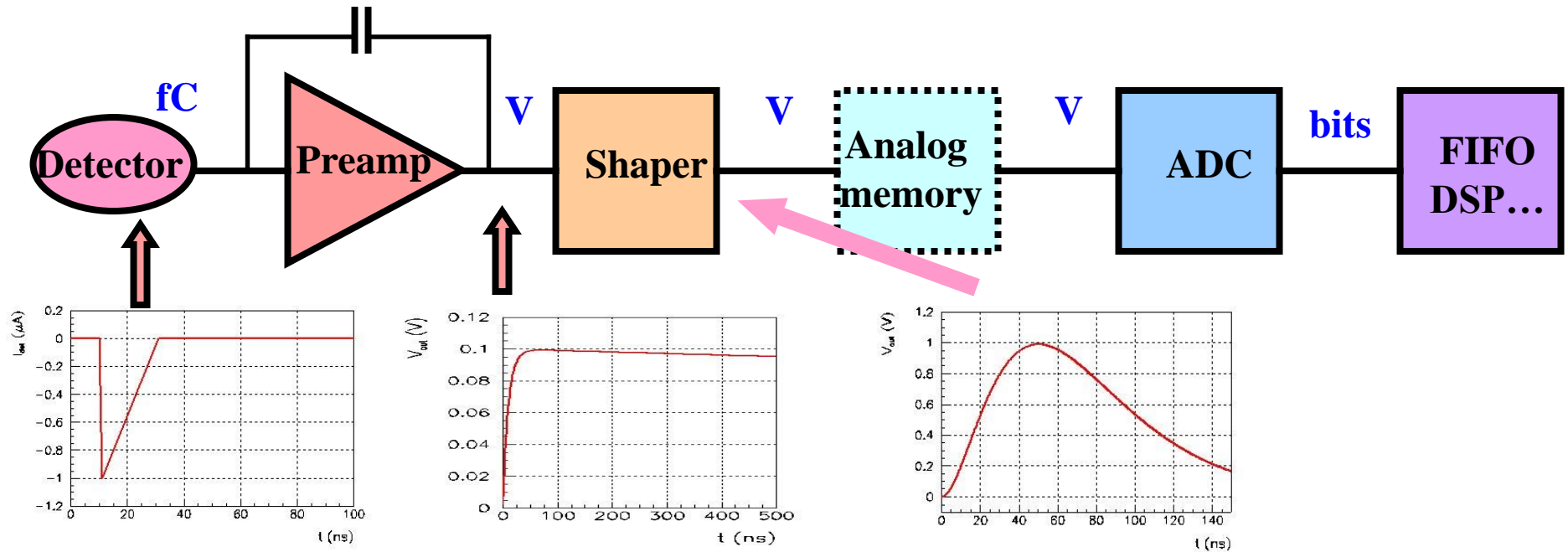
H \rightarrow $\gamma\gamma$ in CMS calorimeter



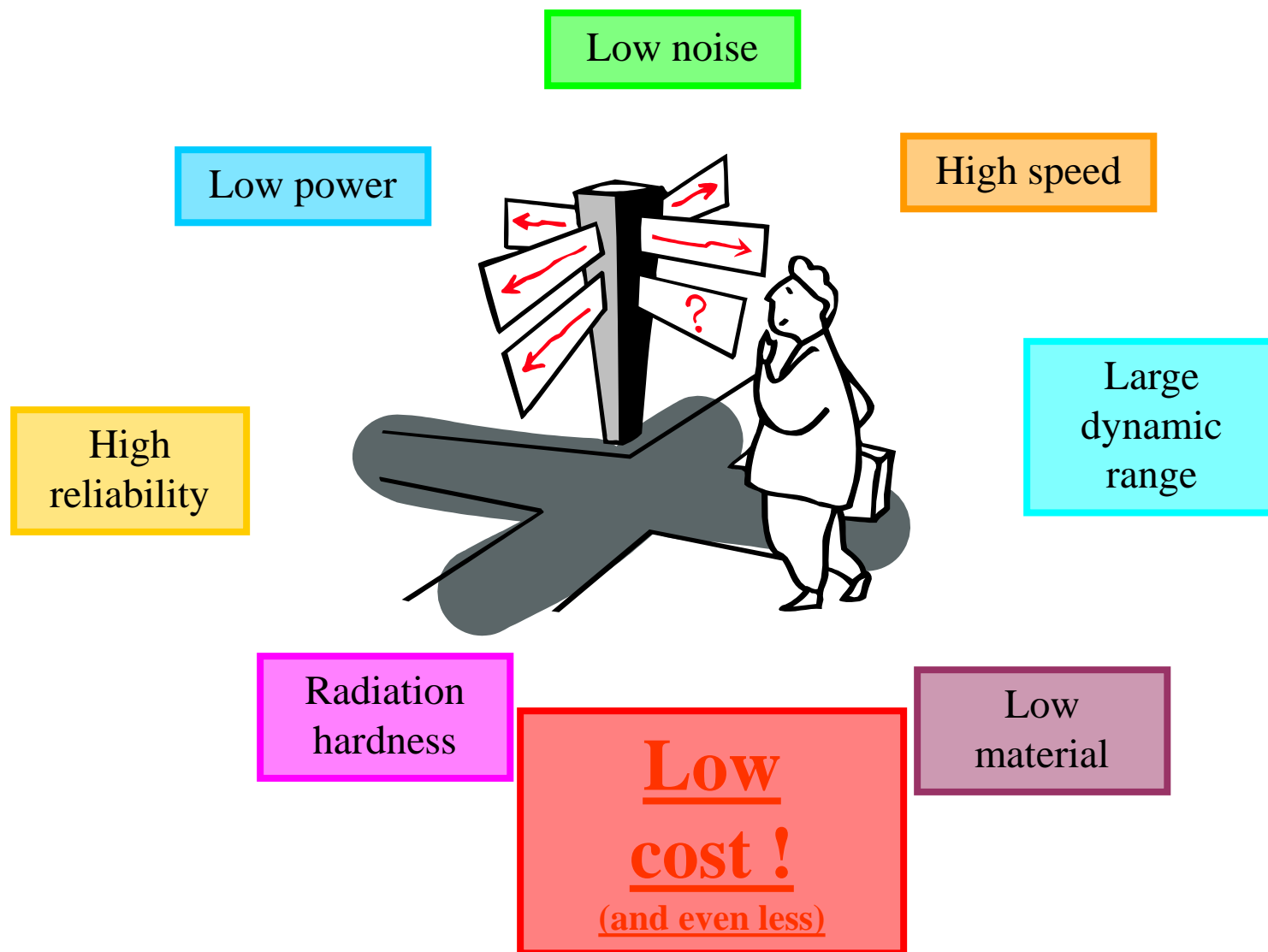
- Photomultipliers, silicon photomultipliers



- Most front-ends follow a similar architecture

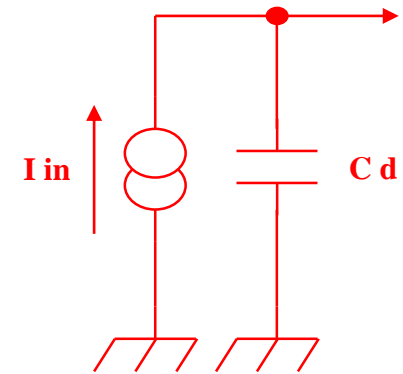


- n Very small signals (fC) -> need **amplification**
- n Measurement of **amplitude** and/or **time** (ADCs, discris, TDCs)
- n Several thousands to millions of channels
- n **Trends** : high speed, low power



Detector modelization

- Detector = capacitance C_d
 - Pixels/strips : 0.1-10 pF
 - PMs/SiPMs : 3-300 pF
 - Ionization chambers 10-1000 pF
 - Sometimes effect of transmission line
- Signal : current source
 - Pixels : $\sim 100e^-/\mu\text{m}$
 - PMs : 1 photoelectron $\rightarrow 10^5\text{-}10^7 e^-$
 - Modelized as an impulse (Dirac) :
 $i(t) = Q_0 \delta(t)$
- Missing :
 - High Voltage bias
 - Connections, grounding
 - Neighbours
 - Calibration...



Detector modelization



CMS pixel module



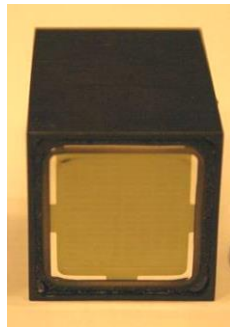
ATLAS LAr calorimeter

Vacuum Photomultipliers

$$G = 10^5 - 10^7$$

$$C_d \sim 10 \text{ pF}$$

$$L \sim 10 \text{ nH}$$

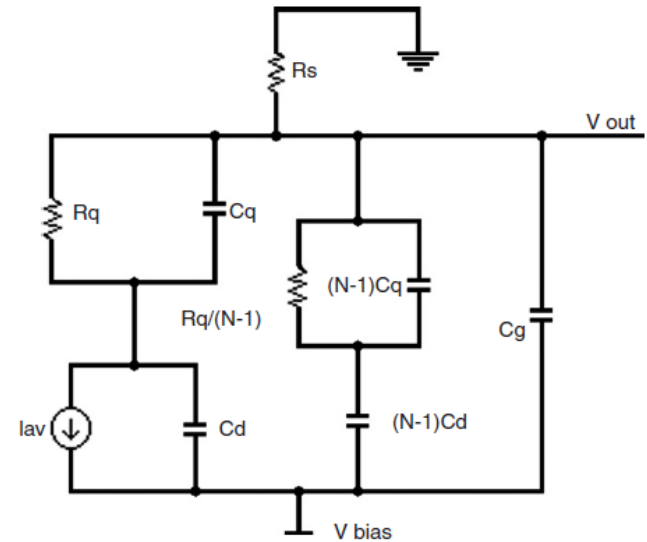
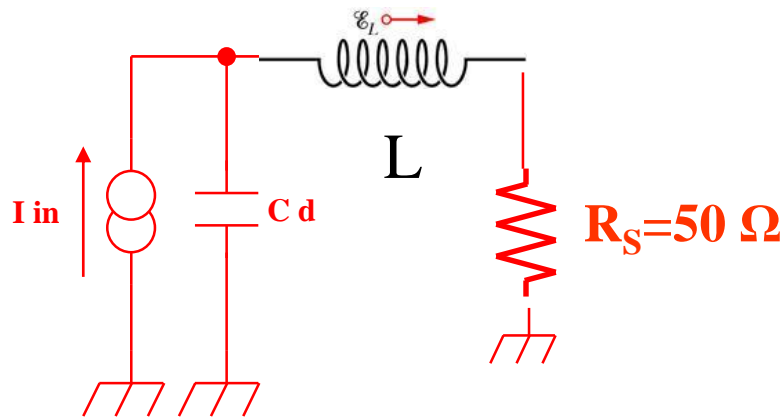
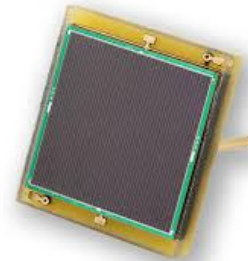


Silicon Photomultipliers

$$G = 10^5 - 10^7$$

$$C = 10 - 400 \text{ pF}$$

$$L = 1 - 10 \text{ nH}$$



Optimizing signal shape for timing

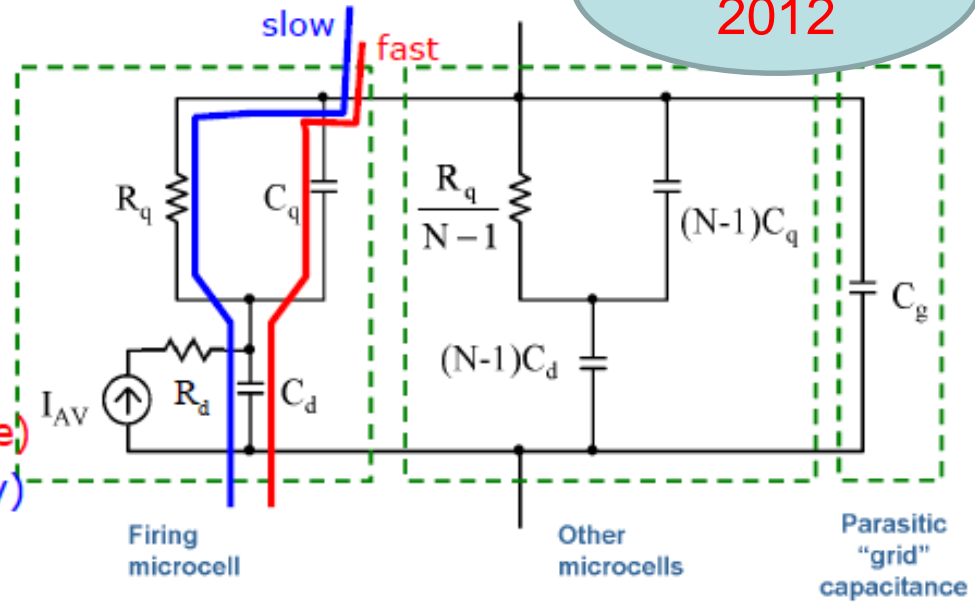
Collazuol 2012

Single cell model $\rightarrow (R_d || C_d) + (R_q || C_q)$

SiPM + load $\rightarrow (||Z_{cell}) || C_{grid} + Z_{load}$

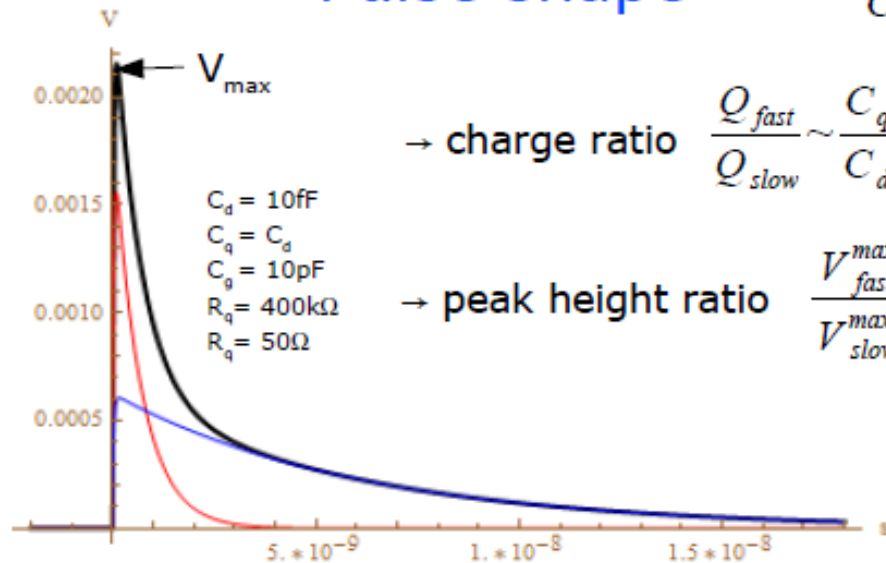
Signal = **slow** pulse ($\tau_{d(rise)}, \tau_{q-slow(fall)}$) + **fast** pulse ($\tau_{d(rise)}, \tau_{q-fast(fall)}$)

- $\tau_{d(rise)} \sim R_d(C_q + C_d)$
- $\tau_{q-fast(fall)} = R_{load} C_{tot}$ (fast; parasitic spike)
- $\tau_{q-slow(fall)} = R_q(C_q + C_d)$ (slow; cell recovery)



Pulse shape

$$V(t) \approx \frac{Q}{C_q + C_d} \left(\frac{C_q}{C_{tot}} e^{-\frac{t}{\tau_{FAST}}} + \frac{R_{load}}{R_q} \frac{C_d}{C_q + C_d} e^{-\frac{t}{\tau_{SLOW}}} \right)$$

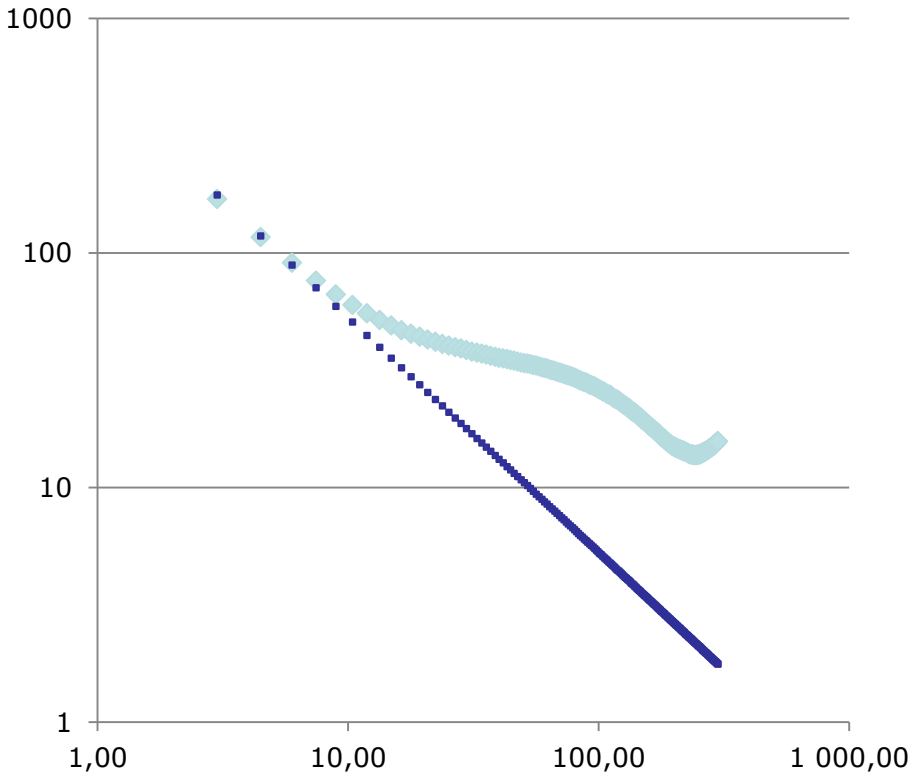
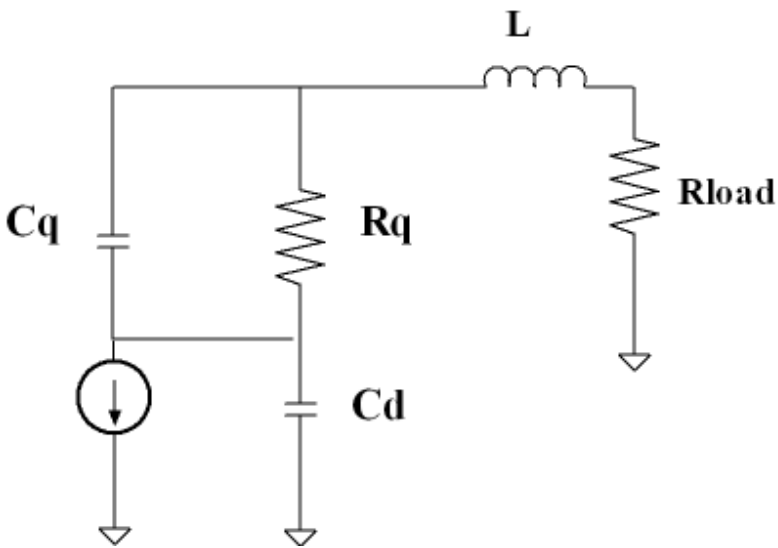


→ charge ratio $\frac{Q_{fast}}{Q_{slow}} \sim \frac{C_q}{C_d}$

→ peak height ratio $\frac{V_{fast}^{max}}{V_{slow}^{max}} \sim \frac{C_q^2 R_q}{C_d C_{tot} R_{load}}$ increasing with R_q and $1/R_{load}$ (and C_q of course)

Increasing C_q/C_d or/and R_q/R_{load}
 → spike enhancement
 → better timing

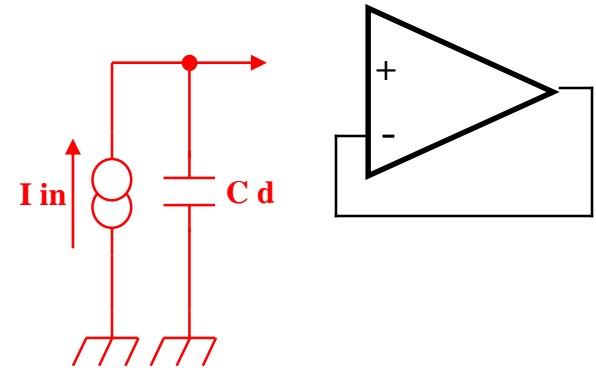
- RLC too simple, inaccurate at high frequency
- CdRqCqLR OK
 - May better explain HF noise behaviour



Measured impedance
MPPC HPK 3x3 mm
Line : C = 320 pF

- Signal

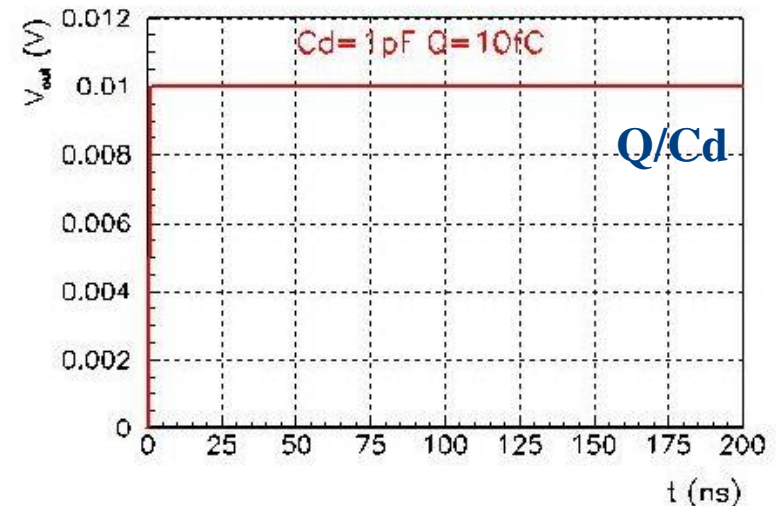
- Signal = current source
- Detector = capacitance C_d
- Quantity to measure
 - Charge => integrator needed
 - Time => discriminator + TDC



- Integrating on C_d

- Simple : $V = Q/C_d$
- « Gain » : $1/C_d$: 1 pF -> 1 mV/fC
- Need a follower to buffer the voltage... => parasitic capacitance
- Gain loss, possible non-linearities
- crosstalk
- Need to empty C_d ...

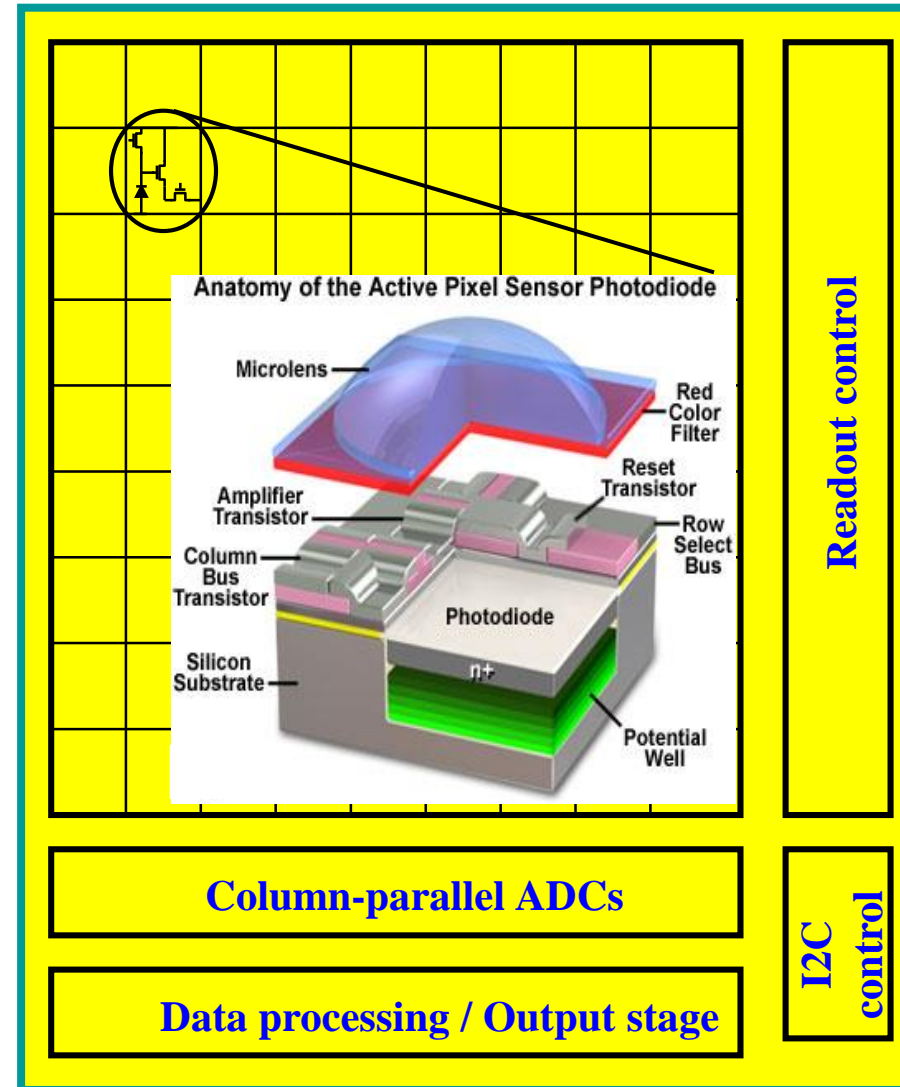
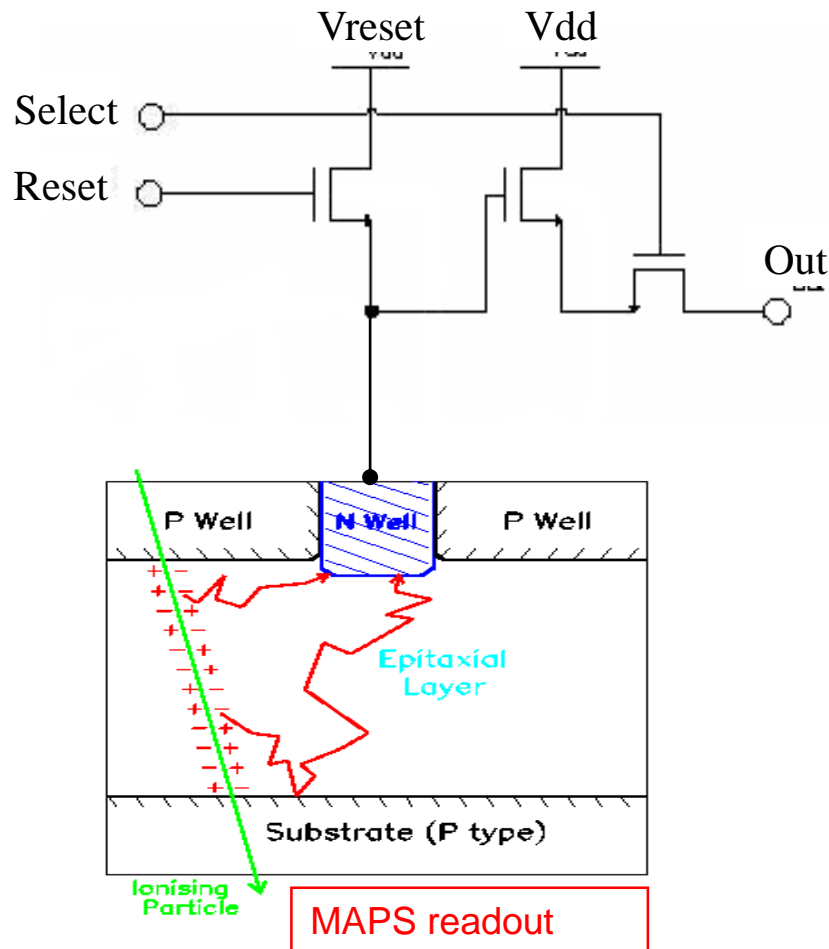
Voltage readout



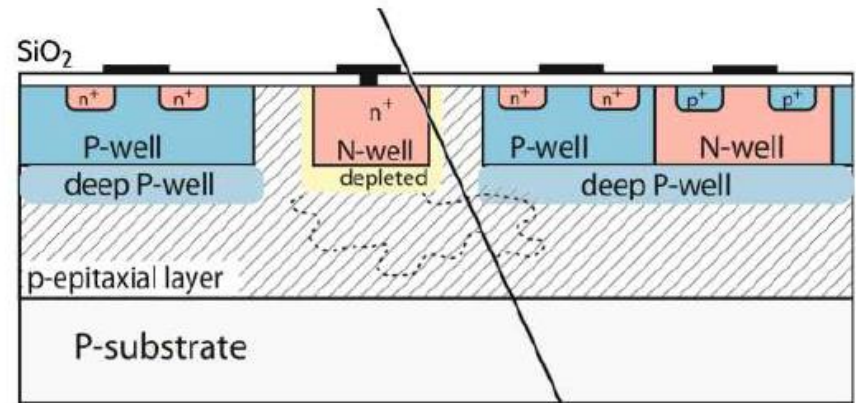
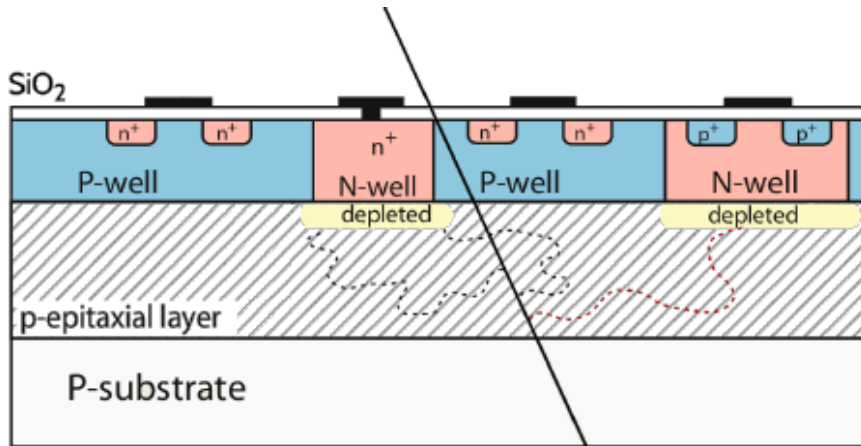
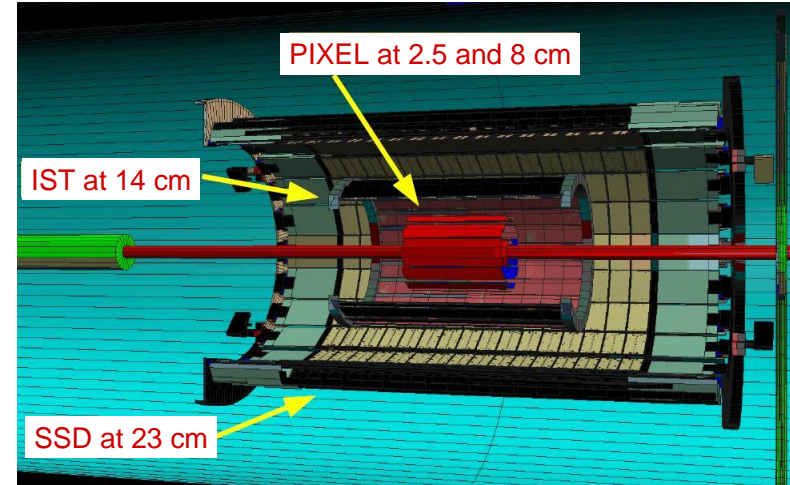
Impulse response

Example : Monolithic active pixels

- Epitaxial layer forms sensitive volume (2-20 μm)
- Charge collection by diffusion
- Read $\sim 100\text{ e}^-$ on $\text{Cd} \sim 10\text{fF}$ = few mV

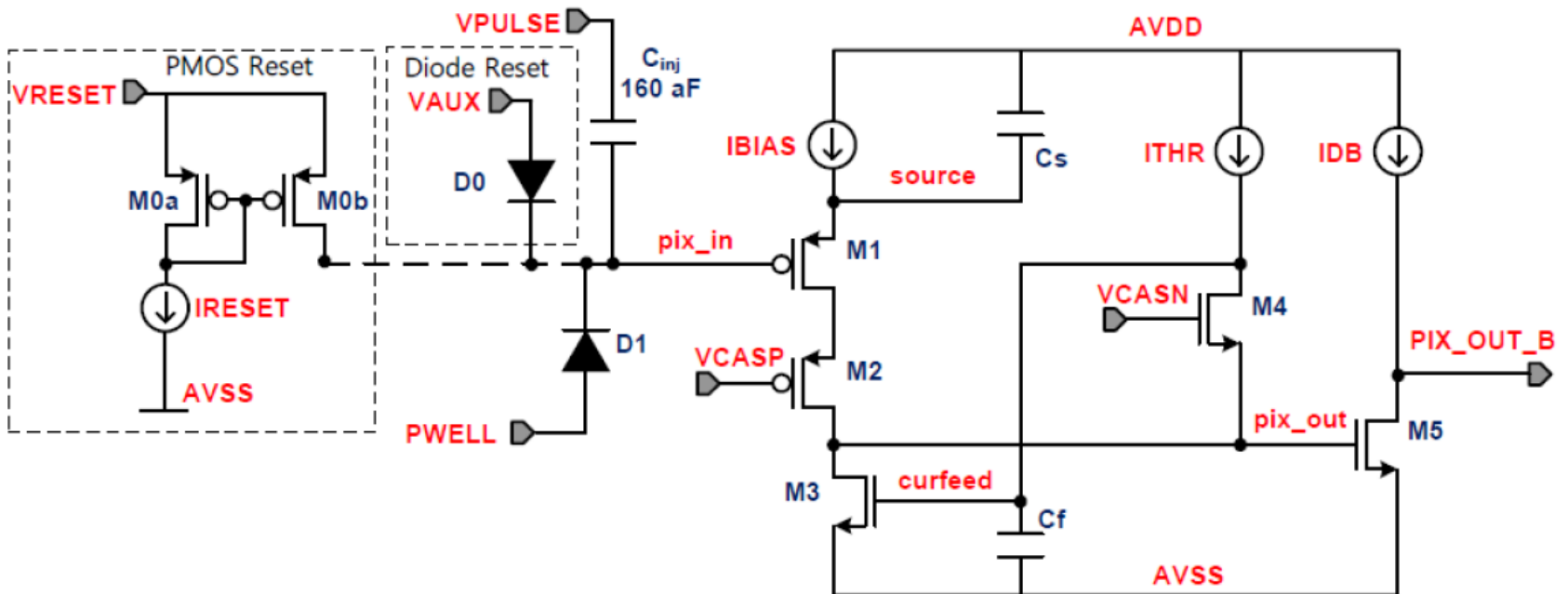
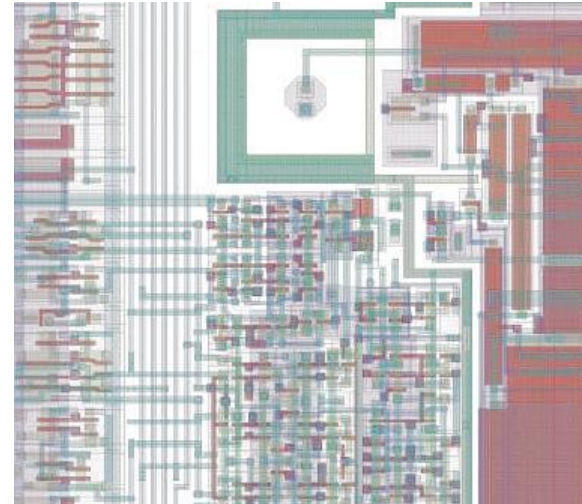


- MIMOSTAR [IPHC strasbourg et al.]
 - First use in HEP : STAR detector 2014
 - 2 cm² ASIC with 21x21 um pixels
- ALPIDE for ALICE upgrade [CERN et al.]
 - Several process and design improvements
 - Deep pwell to allow CMOS
 - In-pixel preamp and comparator
 - P = 40 nW/pixel (5 mW/cm²)

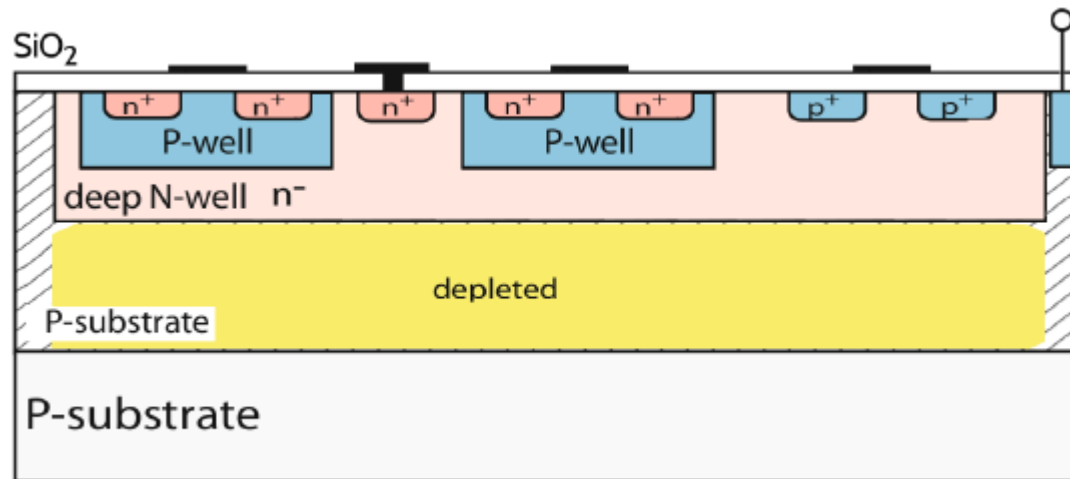


© C. Sauer Heidelberg

- Far from the 3T design...



- Going to HV-MAPS [I. Peric U. Bonn]
 - HV CMOS process => partial/full sensor depletion
 - Collection by drift and not diffusion => fast signal ~ns
 - Better radiation tolerance
 - Nanosecond timing capability
 - Proposed for ATLAS upgrade and $\mu 3e$

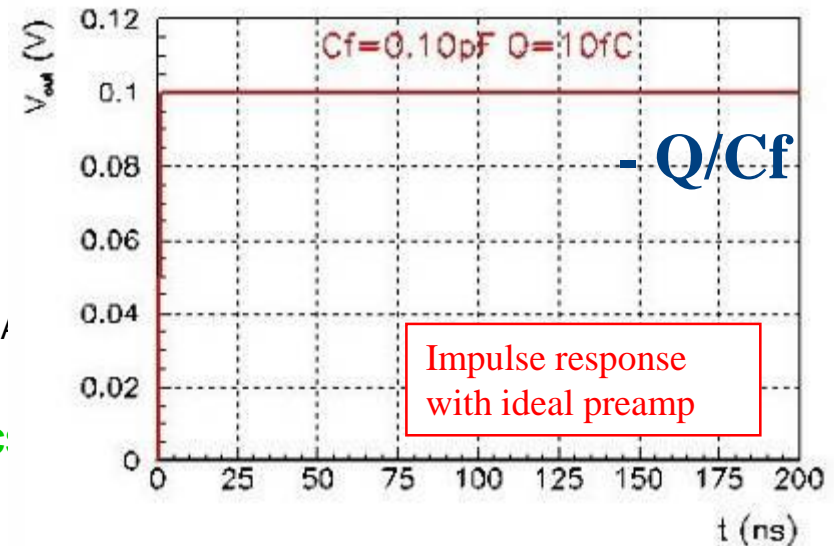
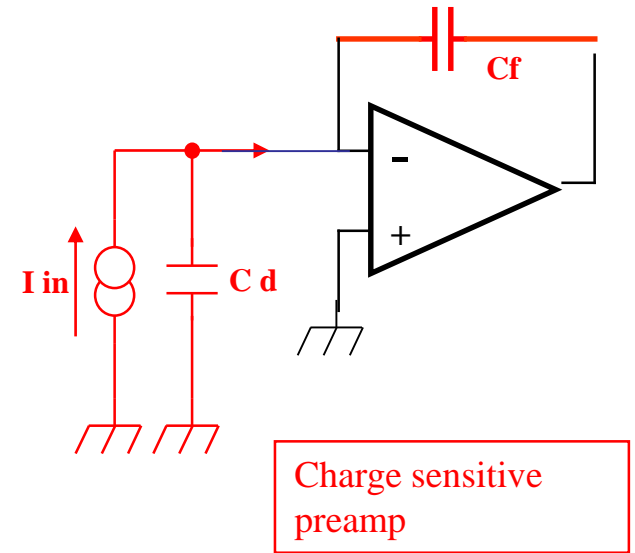


Ideal charge preamplifier

- ideal opamp in transimpedance ($C_f \ll C_d$)
 - Shunt-shunt feedback : low Z_{in} , low Z_{out}
 - $i_{in}(\omega) = j\omega C_d V_{in}(\omega) + j\omega C_f (V_{in}(\omega) - V_{out}(\omega))$
 - $V_{out}(\omega) = -G V_{in}(\omega)$ (opamp gain)
 - $\Rightarrow V_{out}(\omega)/i_{in}(\omega) = -1/j\omega C_f (1 + C_d / GC_f)$
 - Ideal opamp : $G \rightarrow \infty$
 - $V_{out}(\omega)/i_{in}(\omega) = -1/j\omega C_f$
 - Integrator : $v_{out}(t) = -1/C_f \int i_{in}(t)dt$

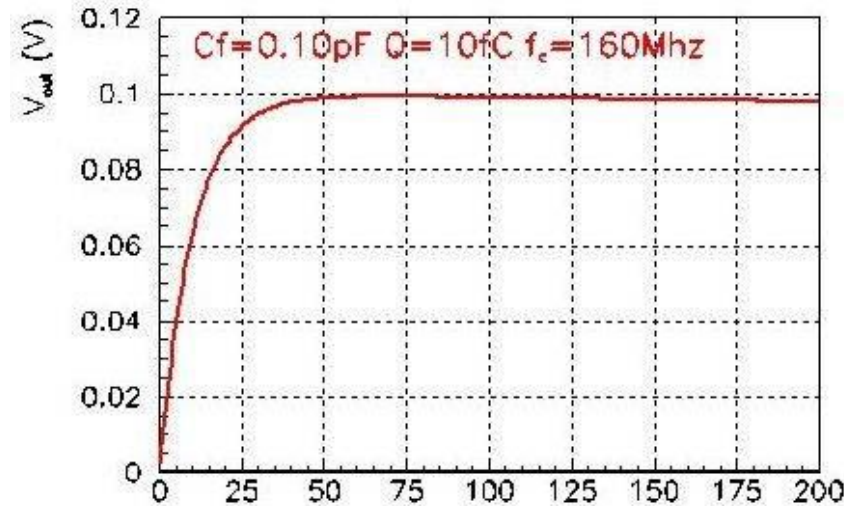
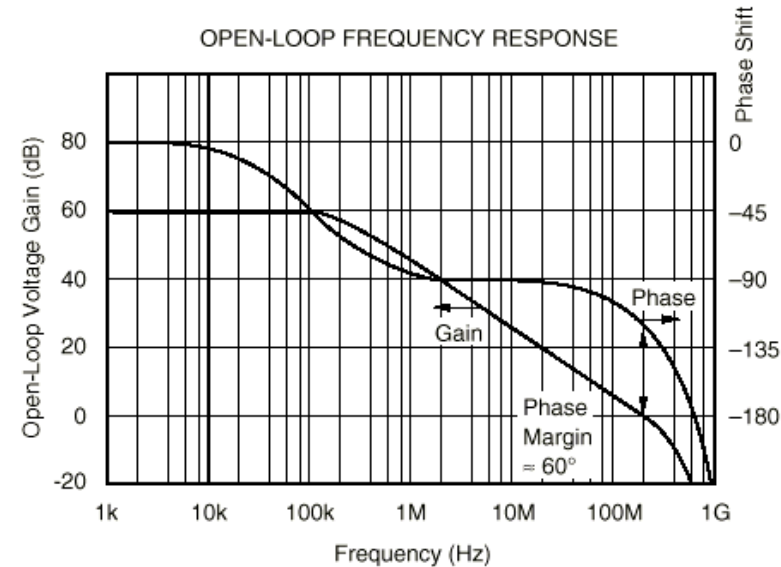
$$v_{out}(t) = -Q/C_f$$

- Integration on C_f
 - Simple : $V = -Q/C_f$
 - Unsensitive to preamp capacitance C_P ,
 - Turns a short signal into a long one
 - The front-end of 90% of particle physic:
 - But always built with custom circuits...



Preamp speed

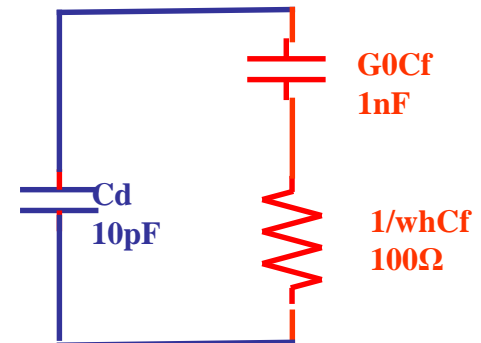
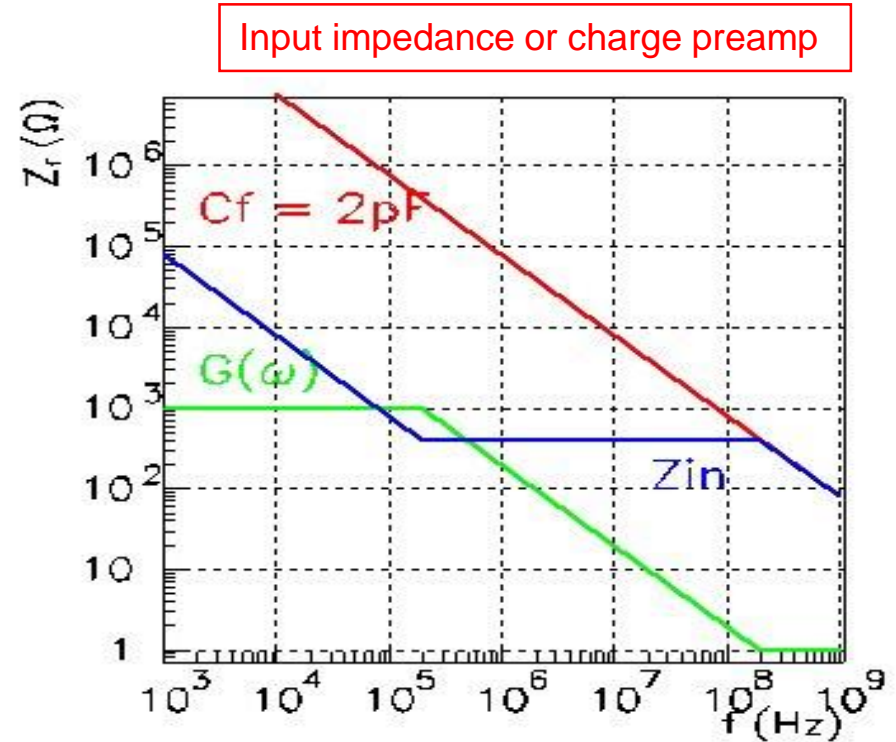
- Finite opamp gain
 - $V_{out}(\omega)/i_{in}(\omega) = -Z_f / (1 + C_d / G_0 C_f)$
 - Small signal loss in $C_d/G_0 C_f \ll 1$
(ballistic deficit)
- Finite opamp bandwidth
 - First order open-loop gain
 - $G(\omega) = G_0/(1 + j \omega/\omega_0)$
 - G_0 : low frequency gain
 - $G_0\omega_0$: gain bandwidth product
 - $V_{out}(\omega)/i_{in}(\omega) = - 1/j\omega C_f (1+j\omega C_d/G_0\omega_0 C_f)$
- Preamp risetime
 - Time constant : τ (*tau*)
 - $\tau = C_d/G_0\omega_0 C_f$
 - Rise-time : $t_{10-90\%} = 2.2 \tau$
 - Rise-time optimised with $w_{C \text{ or } C_f}$



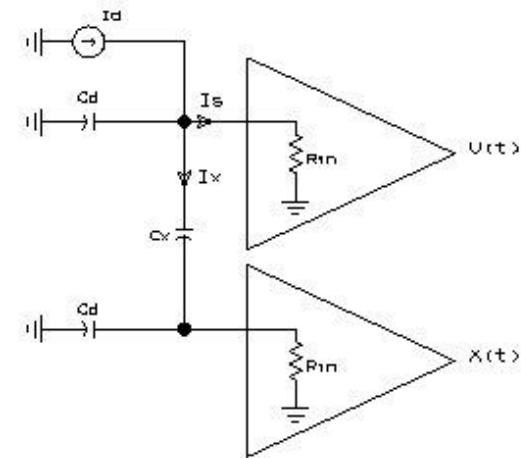
Impulse response with non-ideal preamp

Charge preamp seen from the input

- Input impedance with ideal opamp
 - $Z_{in} = Z_f / G+1$
 - $Z_{in} \rightarrow 0$ for ideal opamp
 - « Virtual ground » : $V_{in} = 0$
 - Minimizes sensitivity to detector impedance
 - Minimizes crosstalk
- Input impedance with real opamp
 - $Z_{in} = 1/j\omega G_0 C_f + 1/ G_0 \omega_0 C_f$
 - Resistive term : $R_{in} = 1/ G_0 \omega_0 C_f$
 - Exemple : $\omega_C = 10^{10}$ rad/s $C_f = 1$ pF $\Rightarrow R_{in} \sim 100 \Omega$
 - Determines the input time constant :
 - $t = R_{eq} C_d$
 - Good stability= (...!)
 - Equivalent circuit :

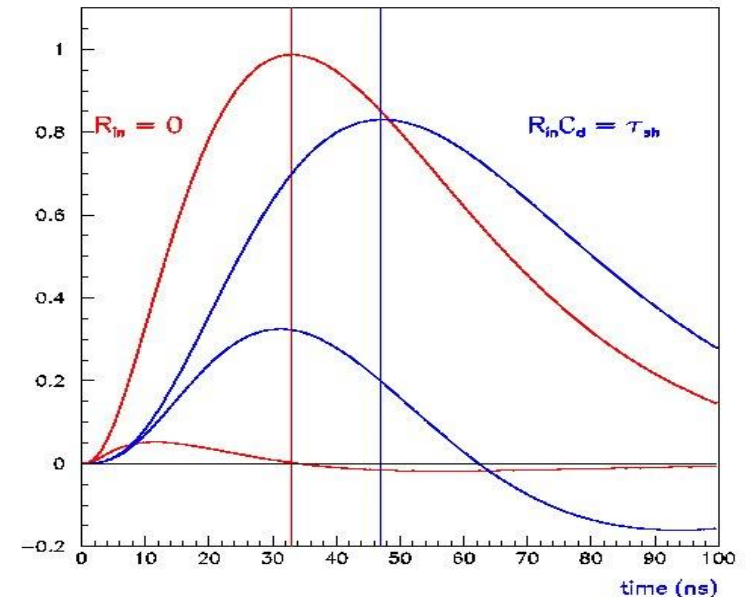


- Capacitive coupling between neighbours
 - Crosstalk signal is **differentiated and with same polarity**
 - Small contribution at signal peak
 - Proportionnal to C_x/C_d and preamp input impedance
 - Slowed derivative if $R_{in}C_d \sim t_p \Rightarrow$ non-zero at peak

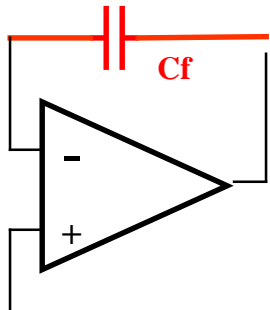


Crosstalk electrical modelization

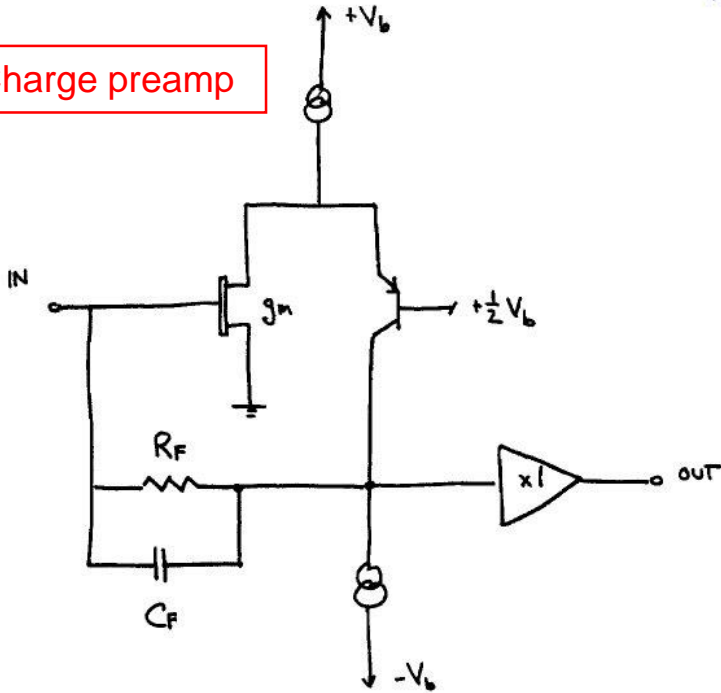
- Long distance crosstalk
 - Inductive/resistive common ground return
 - References impedance
 - Connectors : mutual inductance



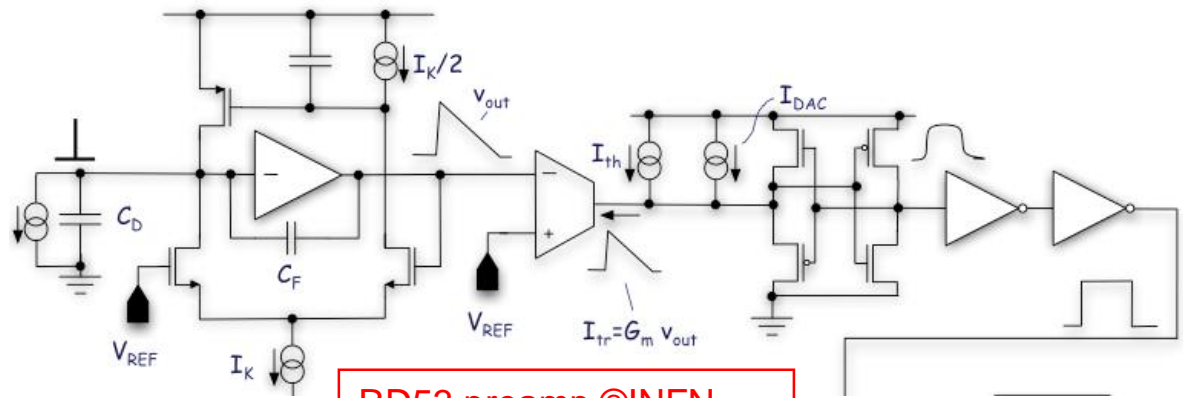
- More details after the section on noise



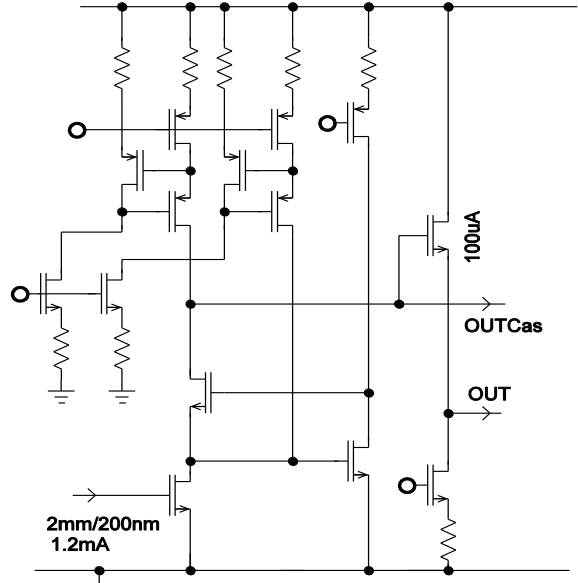
Charge preamp



Charge preamp ©Radeka 68

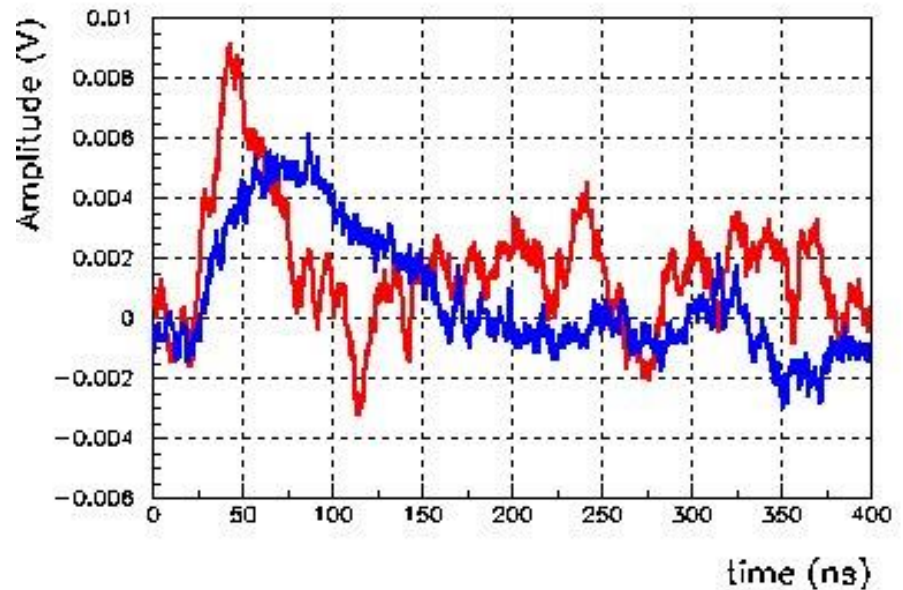


RD53 preamp ©INFN



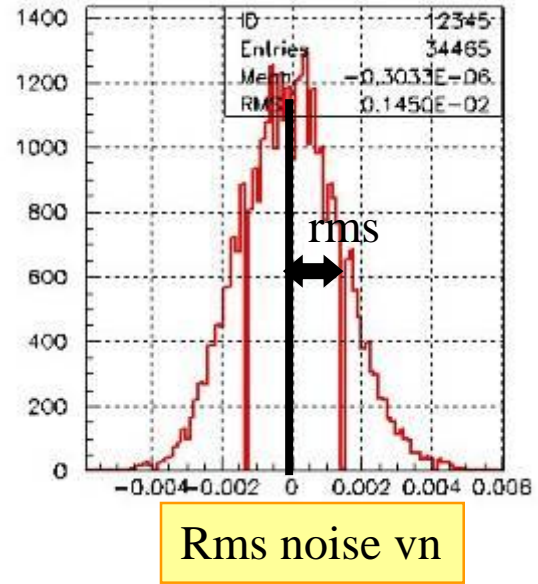
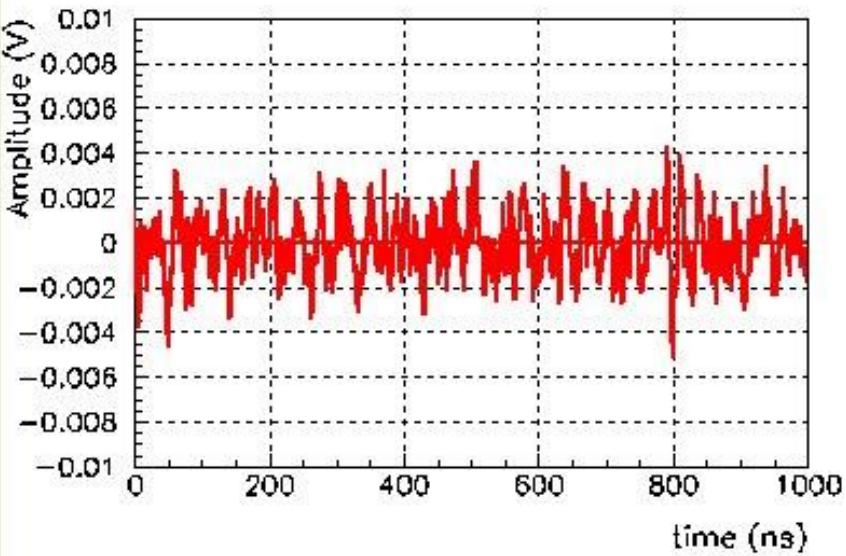
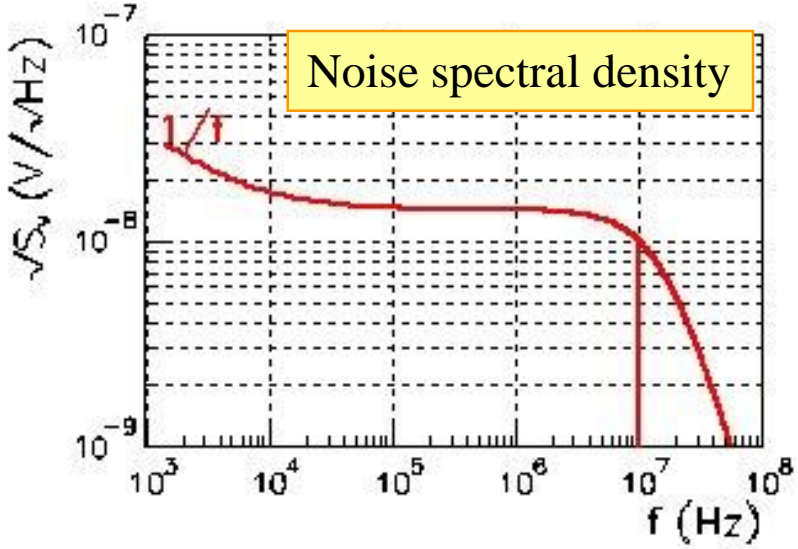
HGCAL preamp ©J. Kaplon

- Definition of Noise
 - Random fluctuation superposed to interesting signal
 - Statistical treatment
- Three types of noise
 - Fundamental noise (Thermal noise, shot noise)
 - Excess noise ($1/f$...)
 - Parasitics -> EMC/EMI (pickup noise, ground loops...)



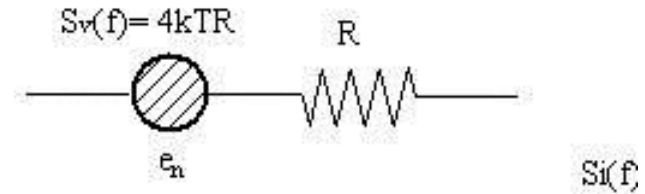
- Modelization
 - Noise generators : $e_n, i_n,$
 - Noise spectral density of e_n & i_n : $S_v(f)$
 - $S_v(f) = | F(e_n) |^2$ (V^2/Hz)

- Rms noise V_n
 - $V_n^2 = \int e_n^2(t) dt = \int S_v(f) df$
 - White noise (e_n) : $v_n = e_n \sqrt{\frac{1}{2}\pi f_{-3dB}}$

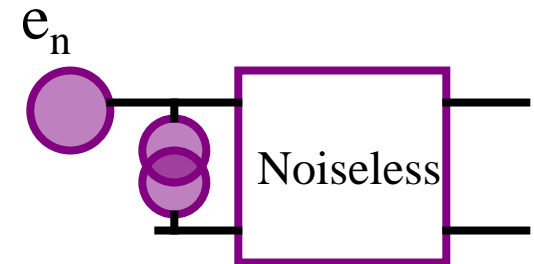
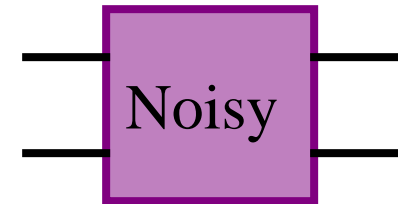


Calculating electronics noise

- Fundamental noise
 - Thermal noise (**resistors**) : $S_v(f) = 4kTR$
 - Shot noise (**junctions**) : $S_i(f) = 2qI$



- Noise referred to the input
 - All noise generators can be referred to the input as **2** noise generators :
 - A voltage one e_n in series : **series noise**
 - A current one i_n in parallel : **parallel noise**
 - Two generators : no more, no less...



■ **To take into account the Source impedance**

■ **Golden rule :**

- **Always calculate the signal before the noise**
what counts is the signal to noise ratio

Noise generators referred to the input

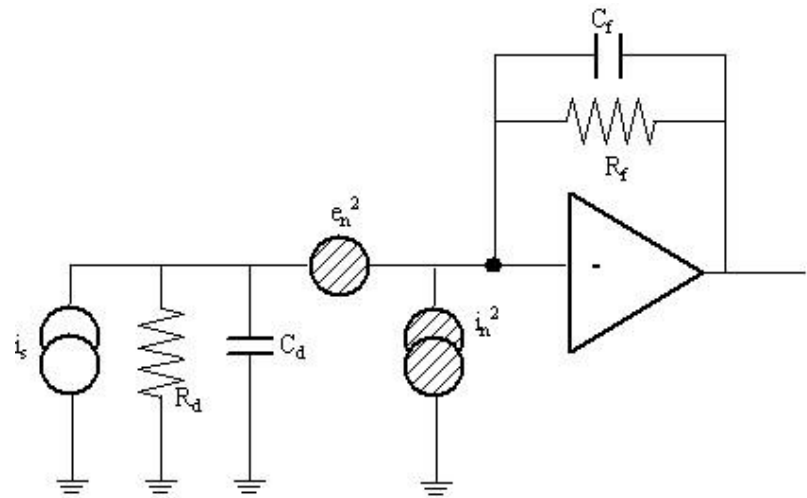
Noise in transimpedance amplifiers

- 2 noise generators at the input
 - Parallel noise : (i_n^2) (leakage)
 - Series noise : (e_n^2) (preamp)

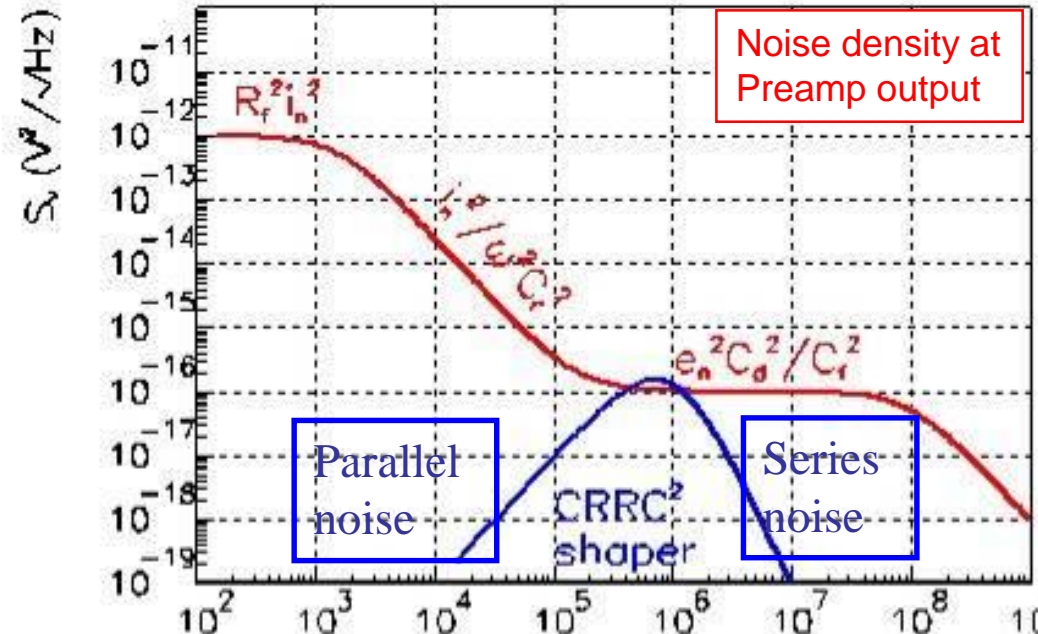
- Output noise spectral density :
 - $S_v(\omega) = (i_n^2 + e_n^2/|Z_d|^2) * |Z_f|^2$

- For charge preamps
 - $S_v(\omega) = i_n^2 / \omega^2 C_f^2 + e_n^2 C_d^2 / C_f^2$
 - Parallel noise in $1/\omega^2$
 - Series noise is flat, with a « noise gain » of C_d/C_f

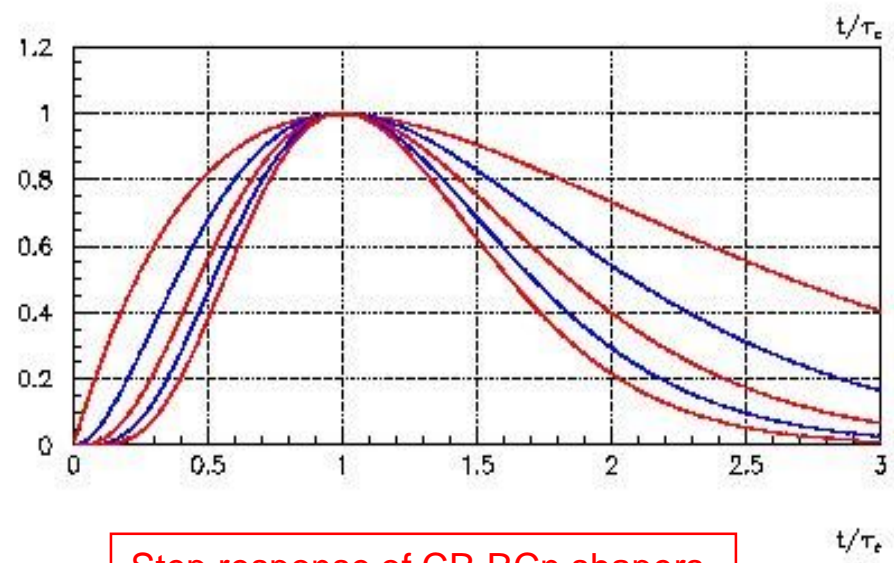
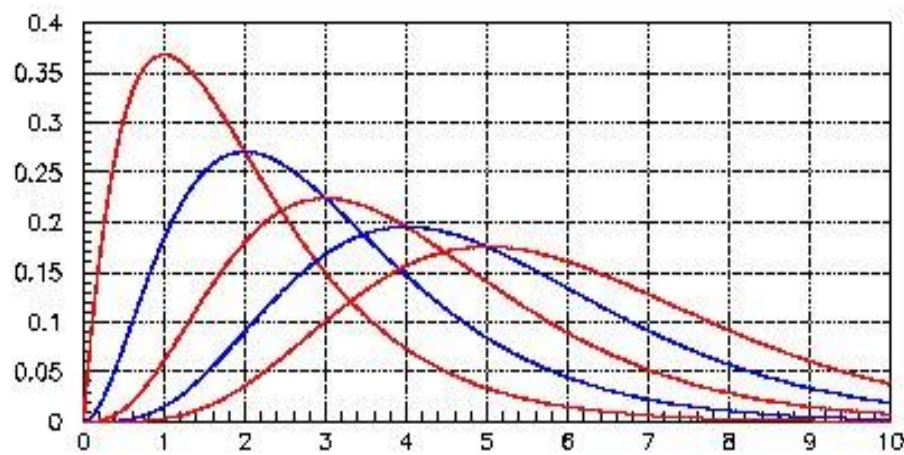
- rms noise V_n
 - $V_n^2 = \int S_v(\omega) d\omega / 2\pi \rightarrow \infty$
 - Benefit of shaping ...



Noise generators in charge preamp

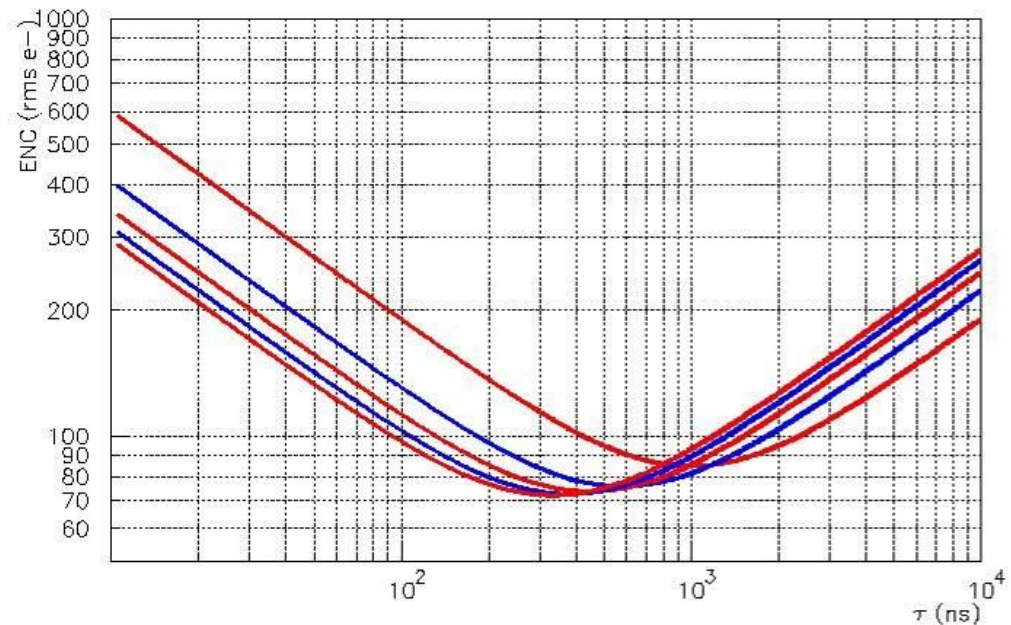


- Noise reduction by optimising useful bandwidth
 - Low-pass filters (**RCⁿ**) to cut-off high frequency noise
 - High-pass filter (**CR**) to cut-off parallel noise
 - -> pass-band filter **CRRCⁿ**
- Equivalent Noise Charge : **ENC**
 - Noise referred to the input in electrons
 - $ENC = I_a(n) e_n C_t \sqrt{T} \oplus I_b(n) i_n^* \sqrt{T}$
 - Series noise in $1/\sqrt{T}$
 - Parallel noise in \sqrt{T}
 - 1/f noise independant of T
 - Optimum shaping time $\tau_{opt} = \tau_c / \sqrt{2n-1}$



Step response of CR RCⁿ shapers

- Peaking time t_p (5-100%)
 - ENC(t_p) independent of n
 - Also includes preamp risetime
- Complex shapers are getting **obsolete** :
 - Power of **digital filtering**
 - Analog filter = CRRC ou CRRC²
 - antialiasing



ENC vs tau for CR RCⁿ shapers

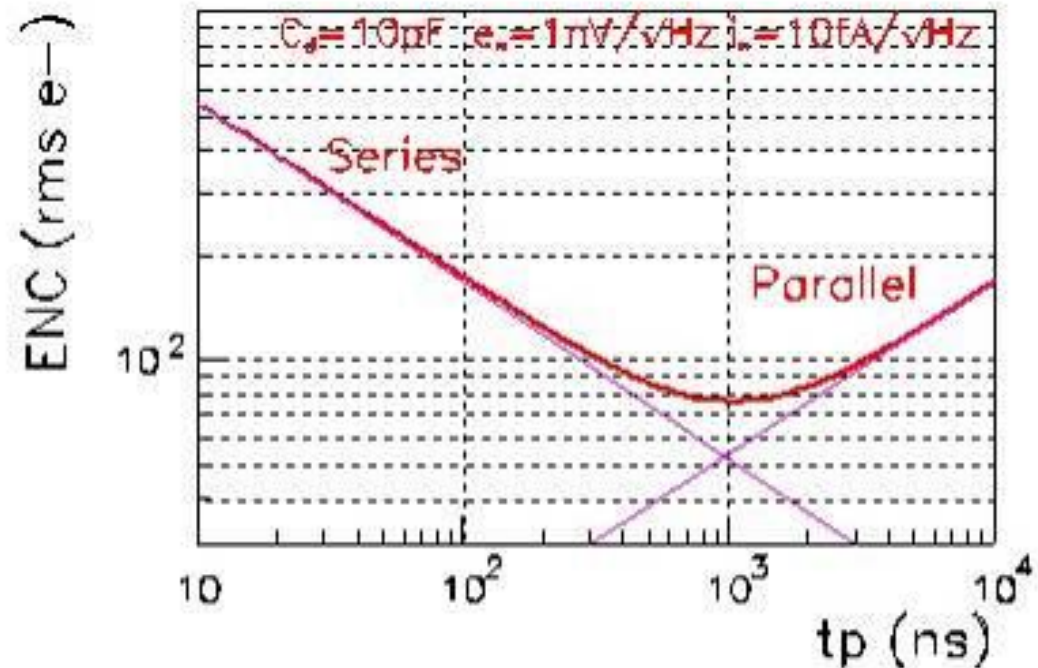
- A useful formula : **ENC (e⁻ rms) after a CRRC² shaper :**

$$\text{ENC} = 174 e_n C_{\text{tot}} / \sqrt{t_p} (\delta) \oplus 166 i_n \sqrt{t_p} (\delta)$$

- e_n in nV/ $\sqrt{\text{Hz}}$, i_n in pA/ $\sqrt{\text{Hz}}$ are the **preamp** noise spectral densities
- C_{tot} (in pF) is dominated by the detector (C_d) + input preamp capacitance (C_{PA})
- t_p (in ns) is the shaper peaking time (5-100%)

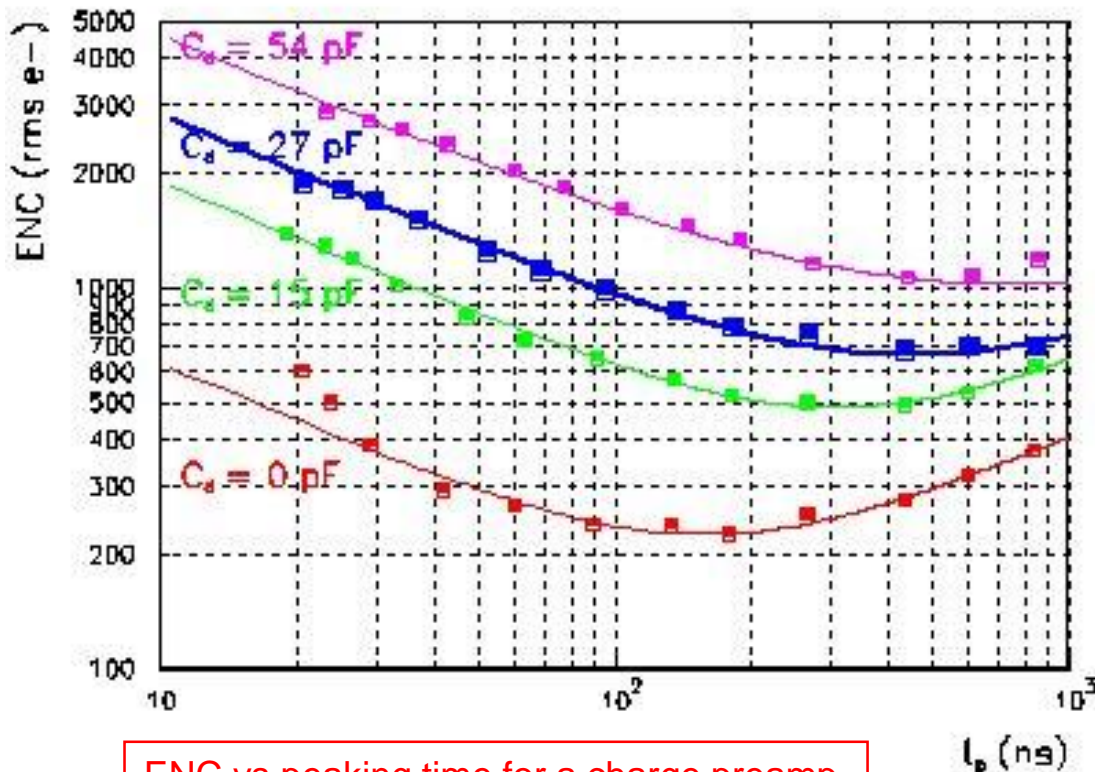
■ Noise minimization

- Minimize source capacitance
- Operate at optimum shaping time
- Preamp series noise (e_n) best with high transconductance (g_m) in input transistor
=> large current, optimal size

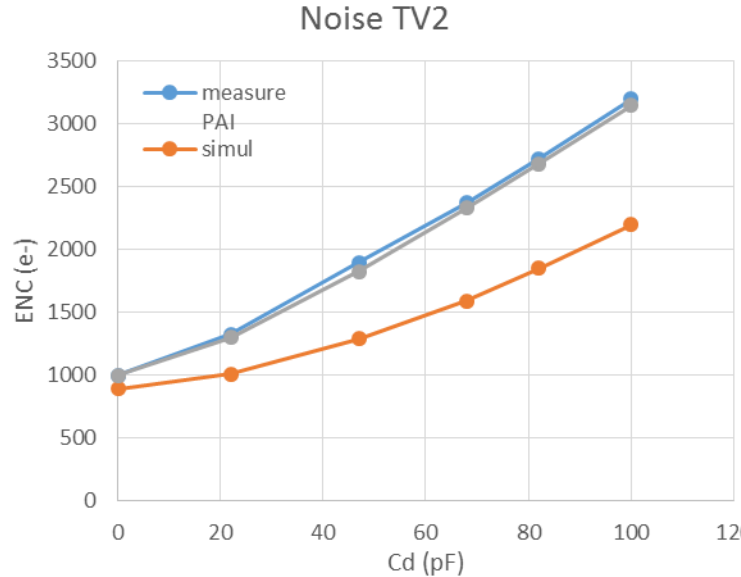


Example of ENC measurement

- 2000/0.35 PMOS 0.35 μ m SiGe $I_d=500 \mu$ A
 - Series : $e_n = 1.4 \text{ nV}/\sqrt{\text{Hz}}$, $C_{PA} = 7 \text{ pF}$, **1/f noise : 12 e-/pF**, Parallel : $i_n = 40 \text{ fA}/\sqrt{\text{Hz}}$
 - Series noise e_n and Preamp capacitance extraction fitting ENC(Cd)
 - NB : linear fit wrong for e_n and C_{PA} , use quadratic fit :
 - $\text{ENC}^2(\text{Cd}) = 3^{e4} e_n^2 (\text{Cd} + C_{pa})^2 / t_p + 3^{e4} i_n^2 t_p + 2^{\text{nd}} \text{ stage}$
 - $\text{ENC}^2(\text{Cd}) - \text{ENC}^2(0) = 3^{e4} e_n^2 / t_p (\text{Cd}^2 + 2 \text{Cd} * C_{pa}) = \alpha \text{Cd}^2 + \beta \text{Cd} \Rightarrow C_{pa} = \beta / 2\alpha$

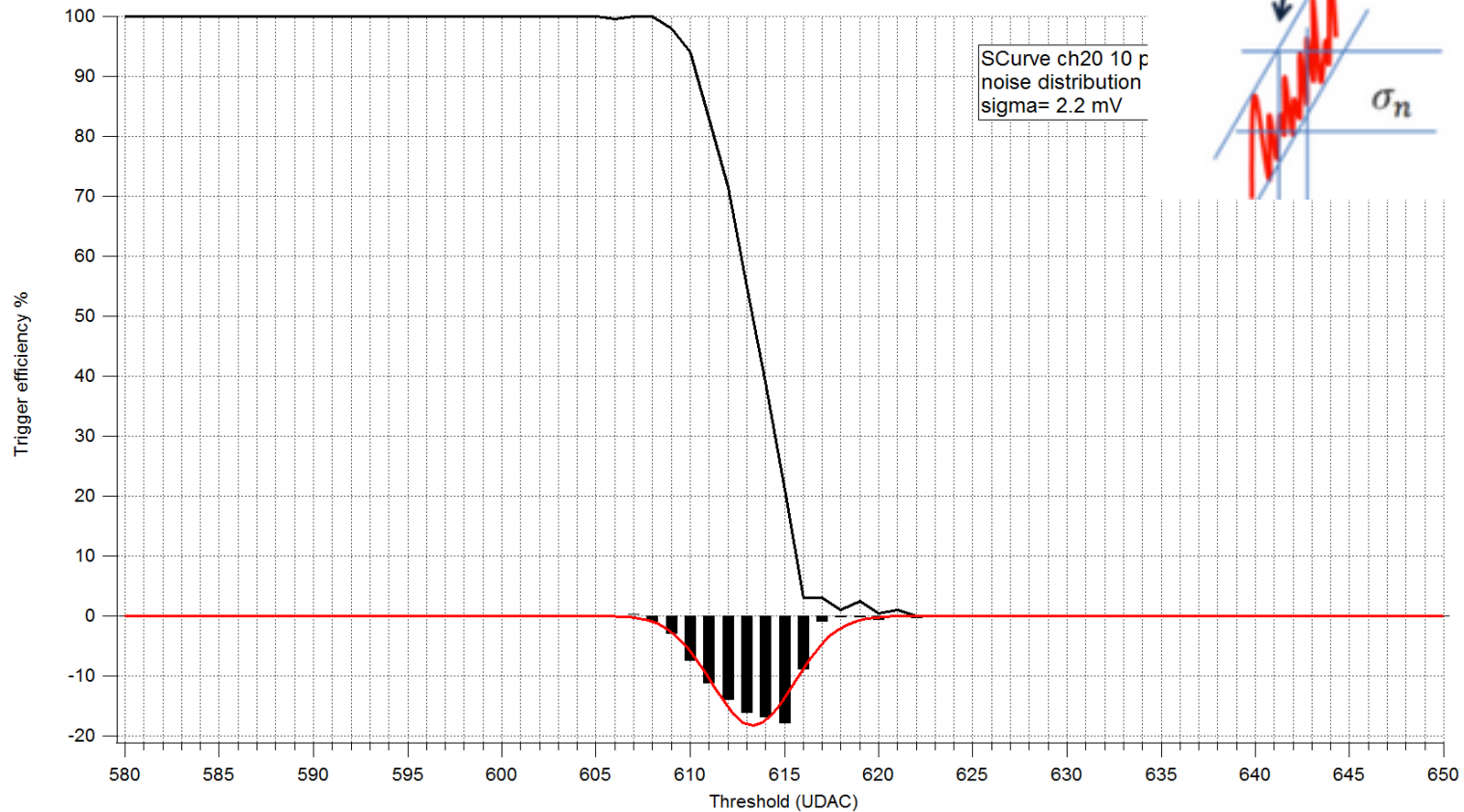
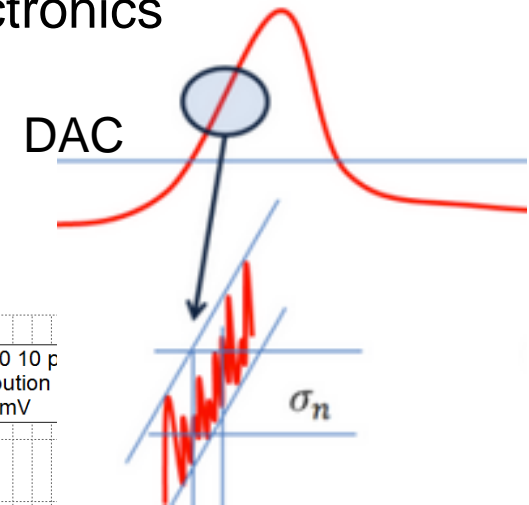


ENC vs peaking time for a charge preamp

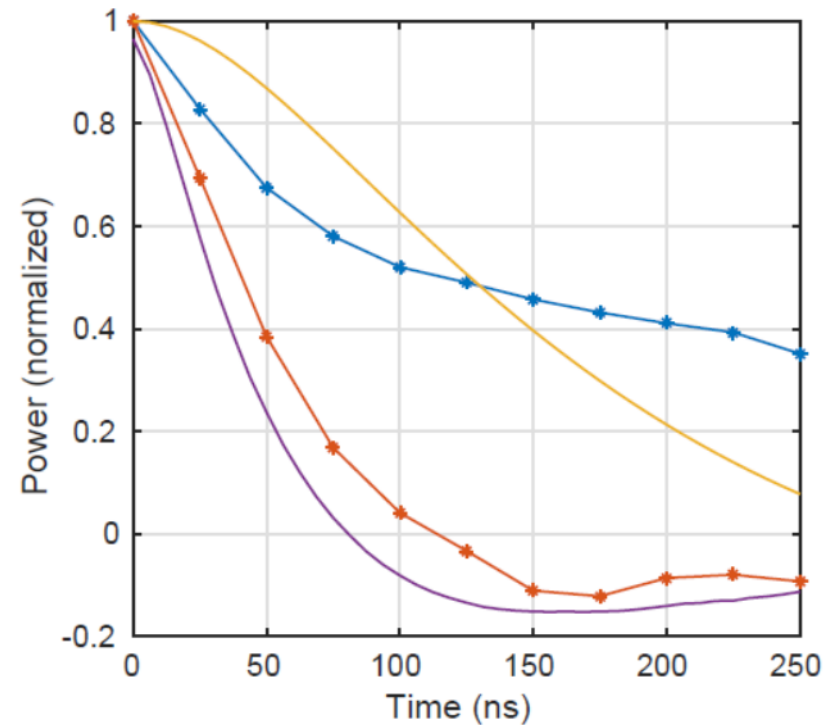
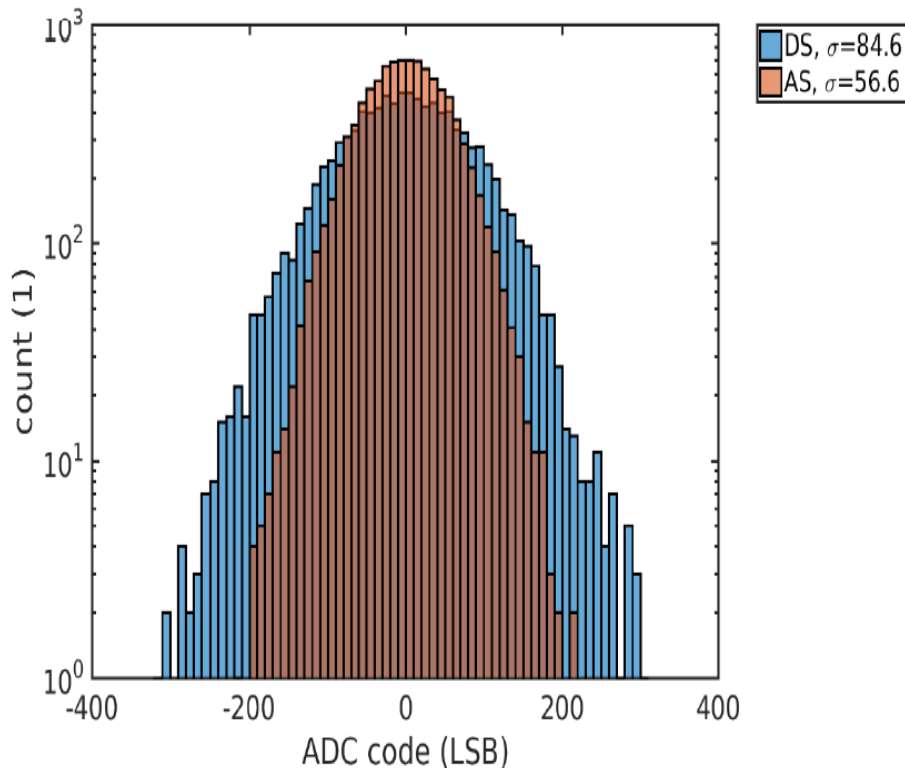


ENC vs Capacitance (other preamp)

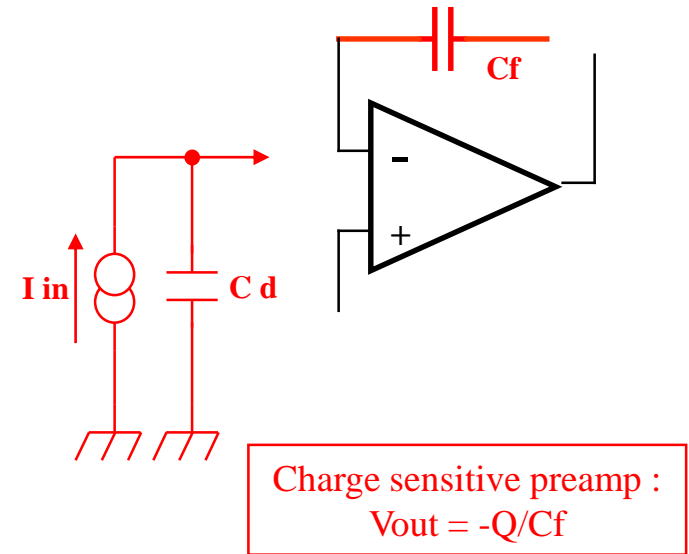
- Preamp + discriminator front-end = tracker electronics
- scanning the DAC produces « s-curves »
- Derivative gives the noise



- A constant concern in calorimetry
 - Coherent noise extracted by comparing direct and alternate sums on n channels
 $(n=64) : DS = \sum ped[i] ; AS = \sum (-1)^i ped[i]$
 - Incoherent noise $IN = rms(AS) / \sqrt{n}$
 - Coherent noise : $CN = \sqrt{var(DS) - var(AS)} / n$
- **Need to show that $CN / IN \sim 10\%$ can be obtained at system level**

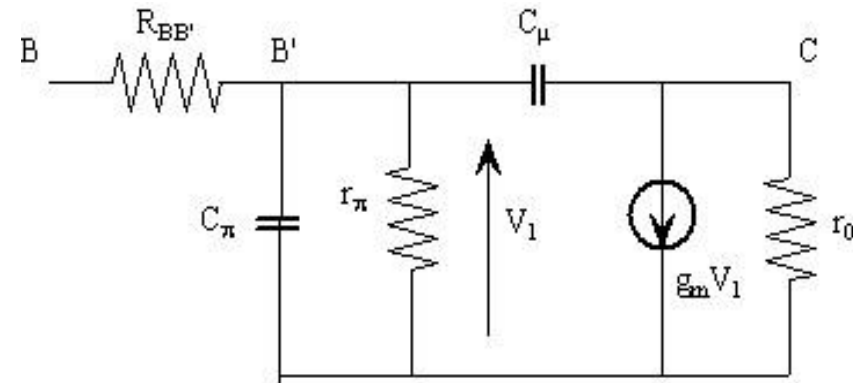


- Importance of front-end on electronics on physics performance
- Benefits of charge preamplifiers : low noise, low crosstalk
 - The front-end of 90% of particle physics detectors...
 - But always built with custom circuits...



Summary of transistor level design

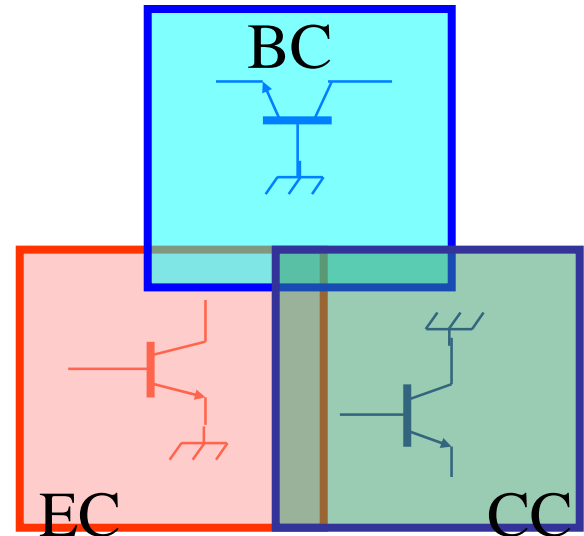
- Performant design is at transistor level
- Simple models
 - hybrid π model
 - Similar for bipolar and MOS
 - Essential for design



High frequency hybrid model of bipolar

■ Three basic configurations

- Common emitter (CE) = V to I (transconductance)
- Common collector (CC) = V to V (voltage buffer)
- Common base (BC) = I to I (current conveyor)
- See backup slides

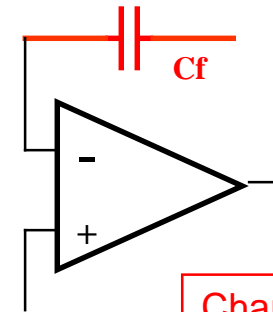


The *Art* of electronics design

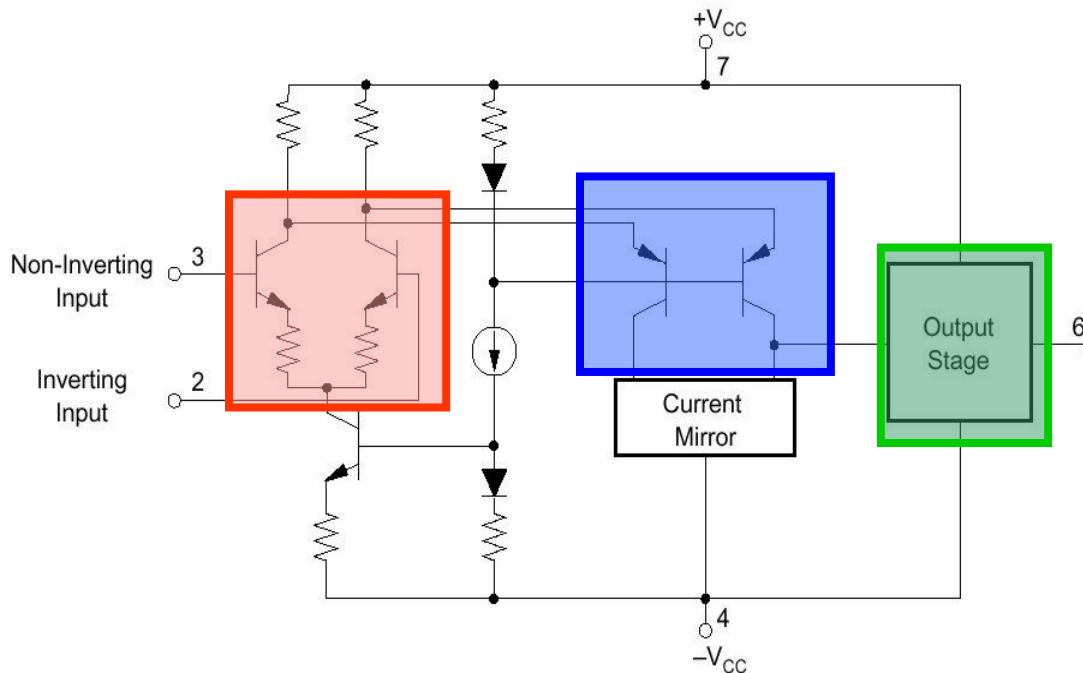
- Numerous « composites »
 - Darlington, Paraphase, Cascode, Mirrors...

Designing a charge preamp...

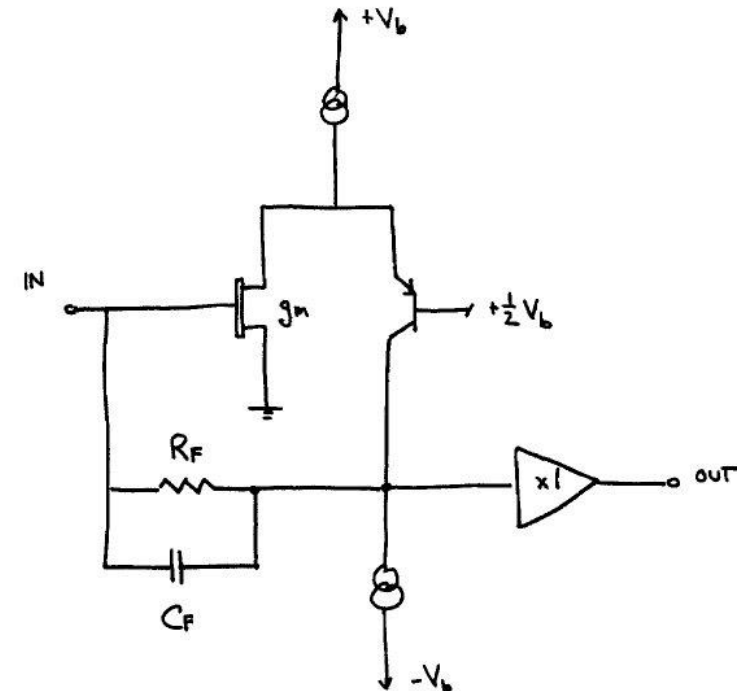
- From the schematic of principle
 - Using of a fast opamp (OP620)
 - Removing unnecessary components...
 - Similar to the traditional schematic «Radeka 68 »
 - Optimising transistors and currents



Charge preamp



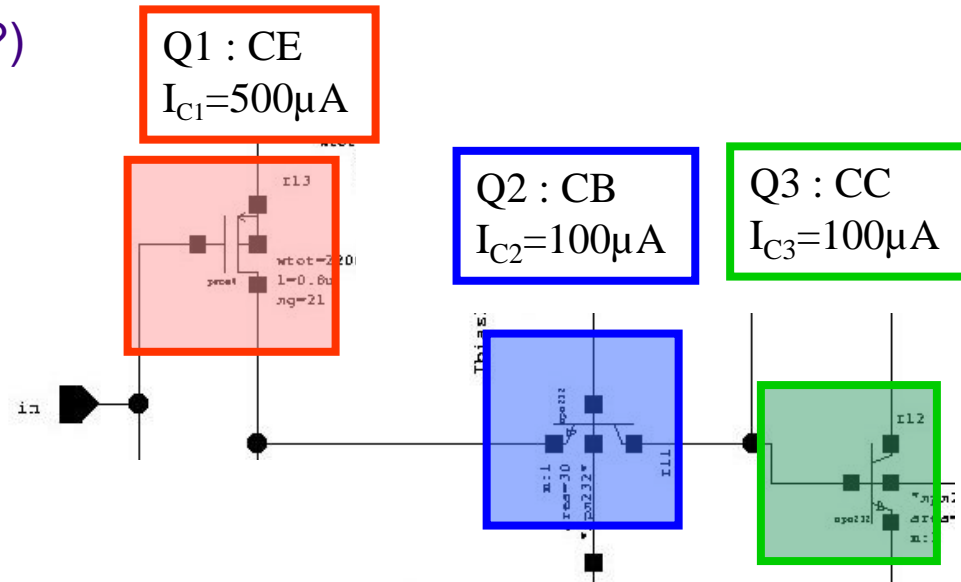
Schematic of a OP620 opamp ©BurrBrown



Charge preamp ©Radeka 68

Example : designing a charge preamp (2)

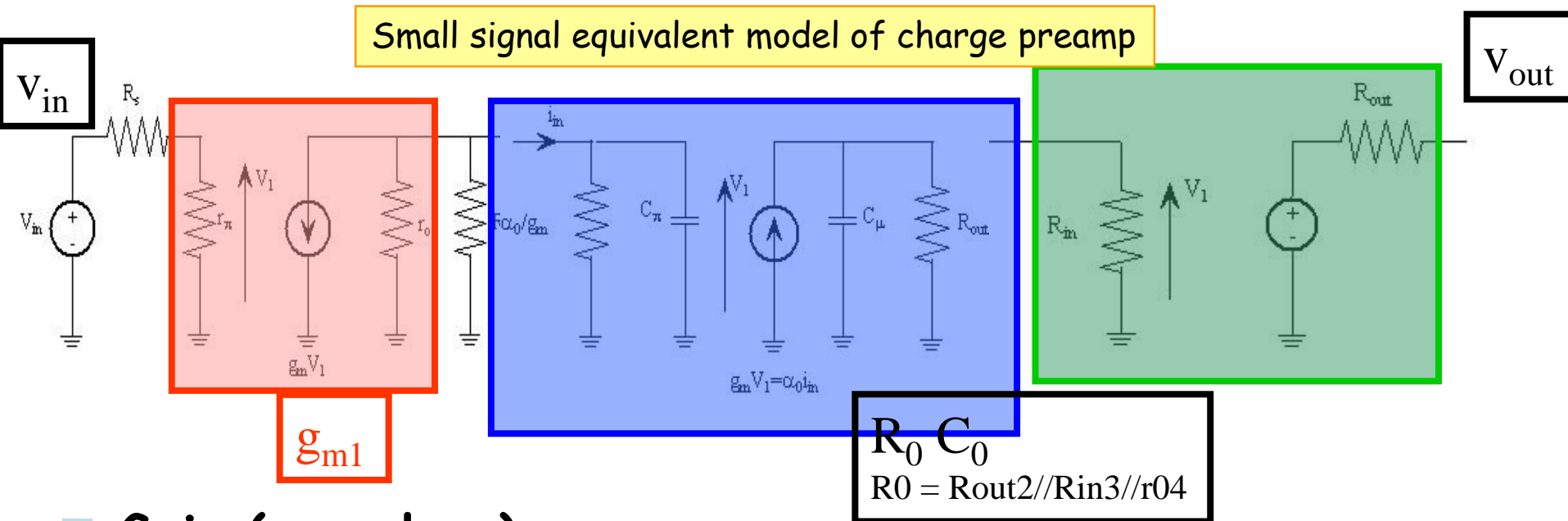
- Simplified schematic
- Optimising components
 - What transistors (PMOS, NPN ?)
 - What bias current ?
 - What transistor size ?
 - What is the noise contribution of each component ?
 - how to minimize it ?
 - What parameters determine the stability ?
 - What is the saturation behaviour
 - How vary signal and noise with input capacitance ?
 - How to maximise the output voltage swing ?
 - What is the sensitivity to power supplies, temperature...



Simplified schematic of Charge preamp

Example : designing a charge preamp (3)

- Small signal equivalent model
 - Transistors are replaced by hybrid π model
 - Allows to calculate open loop gain



■ Gain (open loop) :

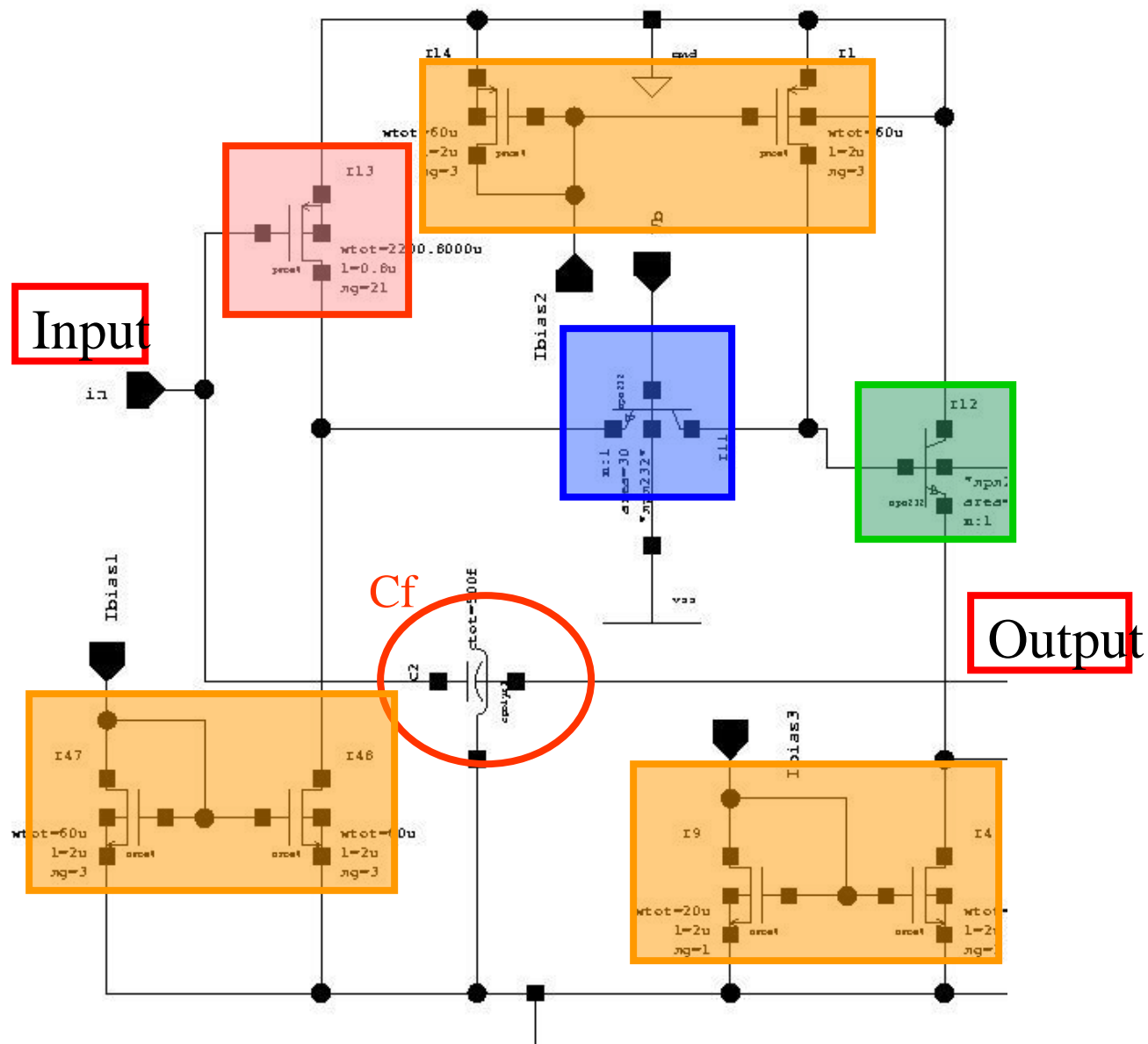
$$v_{out}/v_{in} = -g_{m1} R_0 / (1 + j\omega R_0 C_0)$$

- Ex : $g_{m1} = 20 \text{ mA/V}$, $R_0 = 500 \text{ k}\Omega$, $C_0 = 1 \text{ pF} \Rightarrow G_0 = 10^4$ $\omega_0 = 210^6$ $G_0 \omega_0 = 2 \cdot 10^{10} = 3 \text{ GHz}!$

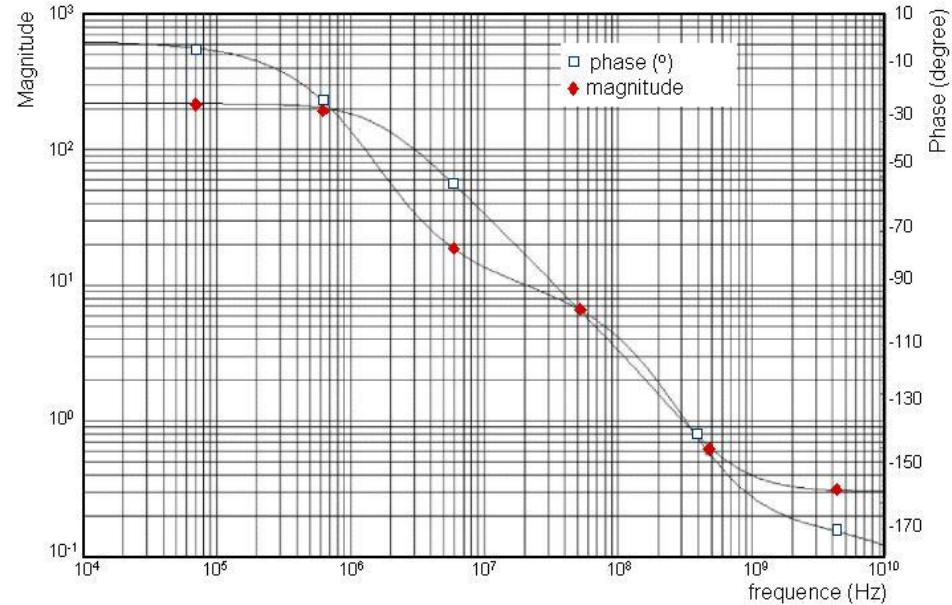
Example : designing a charge preamp (4)



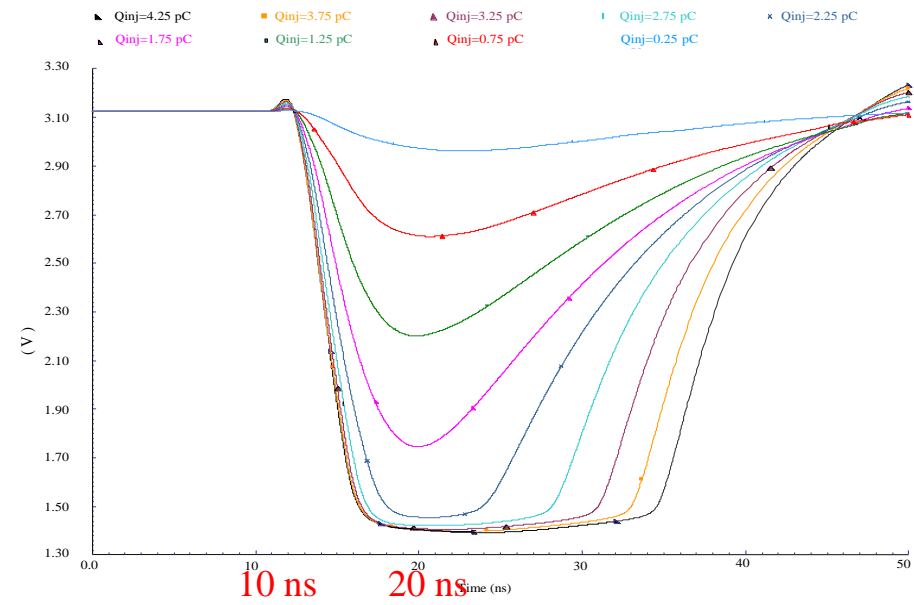
- Complete schematic
 - Adding bias elements



- Complete simulation
 - Checking hand calculations against 2nd order effects
 - Testing extreme process parameters (« corner simulations »)
 - Testing robustness (to power supplies, temperature...)

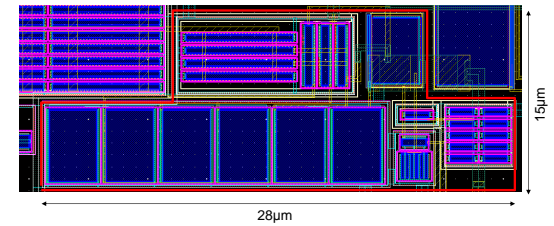


Simulated open loop gain

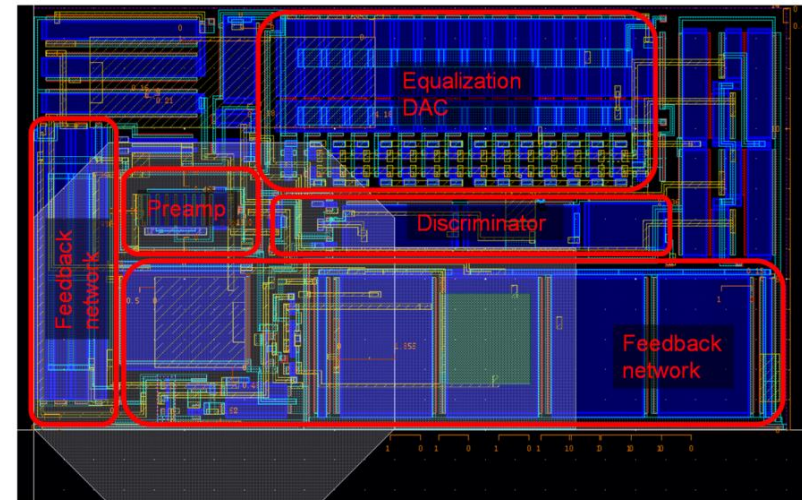


Saturation behaviour

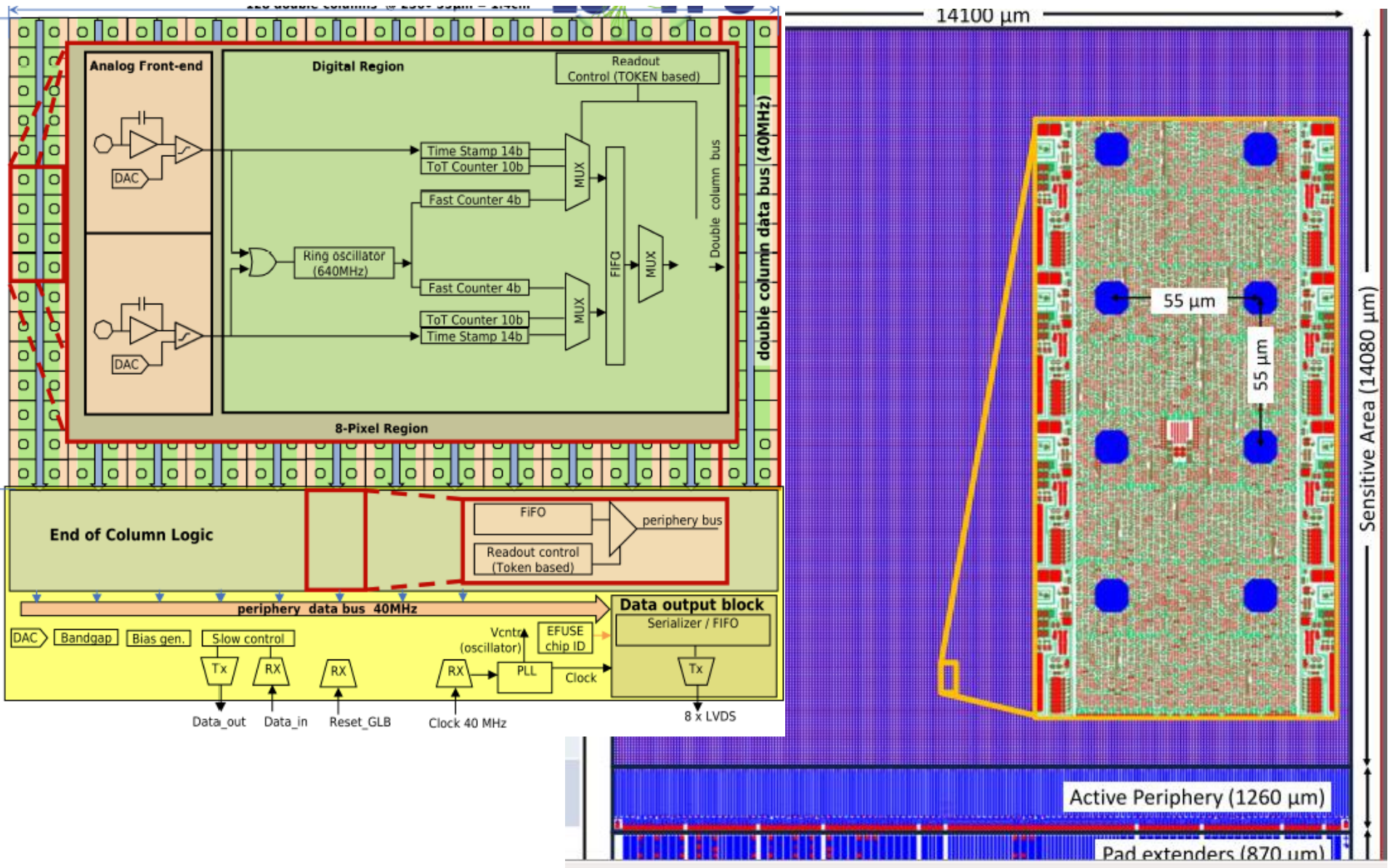
- Layout
 - Each component is drawn
 - They are interconnected by metal layers
- Checks
 - DRC : checking drawing rules (isolation, minimal dimensions...)
 - ERC : extracting the corresponding electrical schematic
 - LVS (layout vs schematic) : comparing extracted schematic and original design
 - Simulating extracted schematic with parasitic elements
- Generating GDS2 file
 - Fabrication masks : « reticule »



Charge preamp in 65nm
Clicpix P. Valerio (CERN 2013)



From preamp to chip : Timepix 3...



```
process(Rstb, Clk)
begin
  if Rstb ='0' then
    Q <= '0';
  elsif rising_edge Clk then
    Q <= D;
  end if;
end process;
```

Architecture Design

High Level Synthesis

Synthesis

Verification

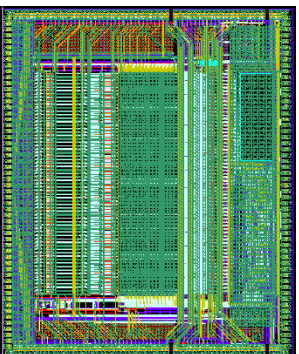
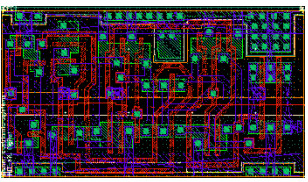
Placement

Extraction and Timing Verification

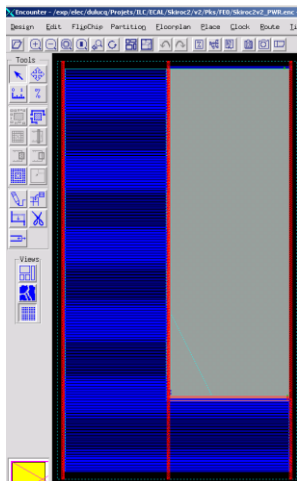
Routing

GDSII

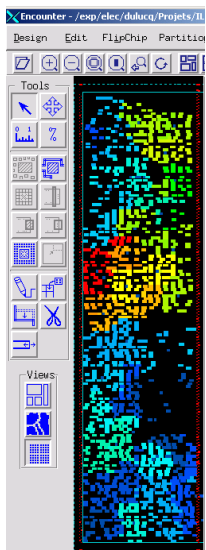
Manufacturing



Skiroc2 power planning



Skiroc2 clock tree



IO Pad Placement

Power planning
(Stripes & rings)

Global Placement

DFT (scan chains)

Clock Tree Synthesis

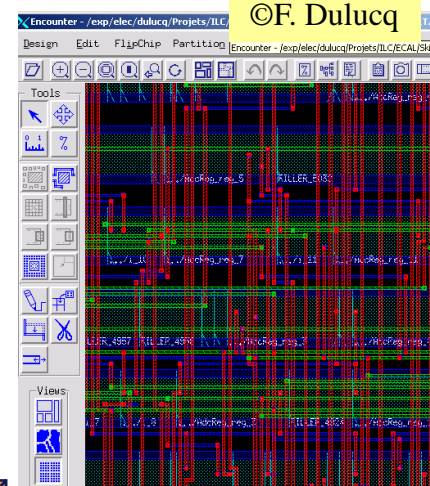
Global Routing

LVS / DRC
Specific Analysis (IR, Antennas)

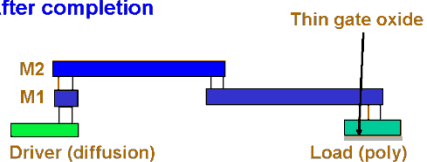
GDS2

(M1, M2, M3) =
(blue, red, green)

Extraction and
Delay Calc. Timing
Verification

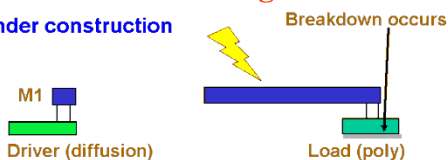


(a) After completion



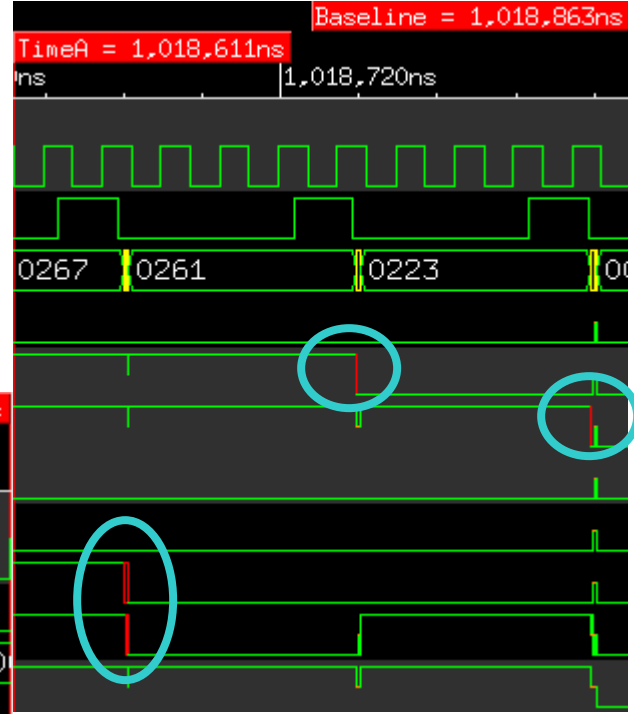
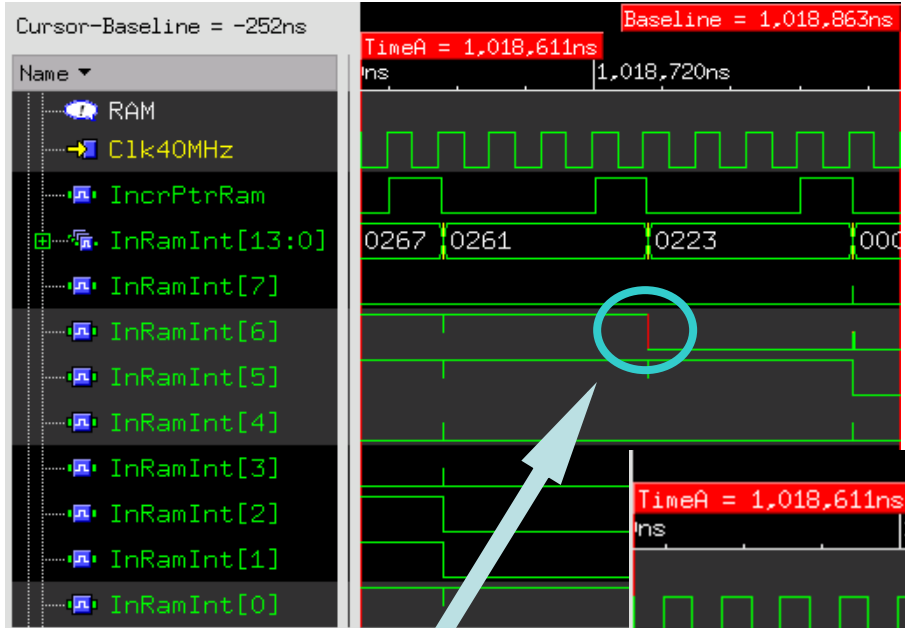
Antennas fixing

(b) Under construction



MIN PVT (1.6 ; 3.6V ; -50°C)

MAX PVT (1.4 ; 3V ; 125°C)

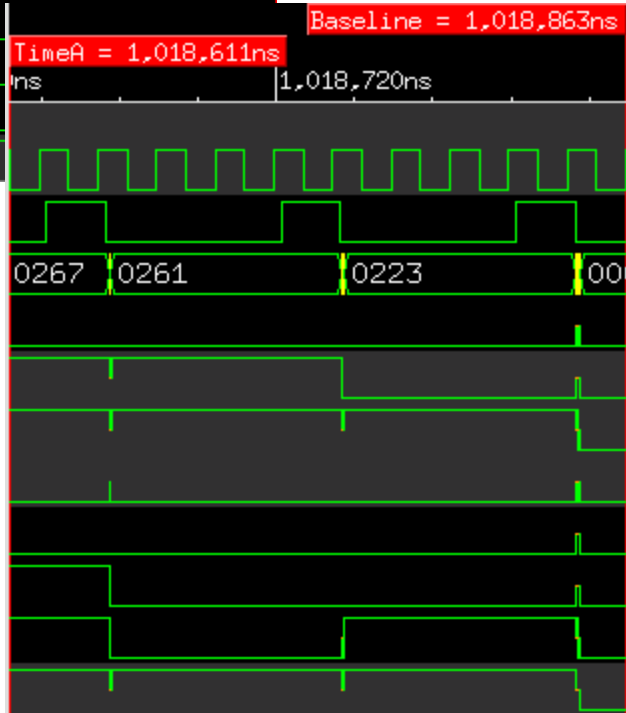


1 violations

4 violations

TYP PVT (1 ; 3.3V ; 25°C)

0 violations

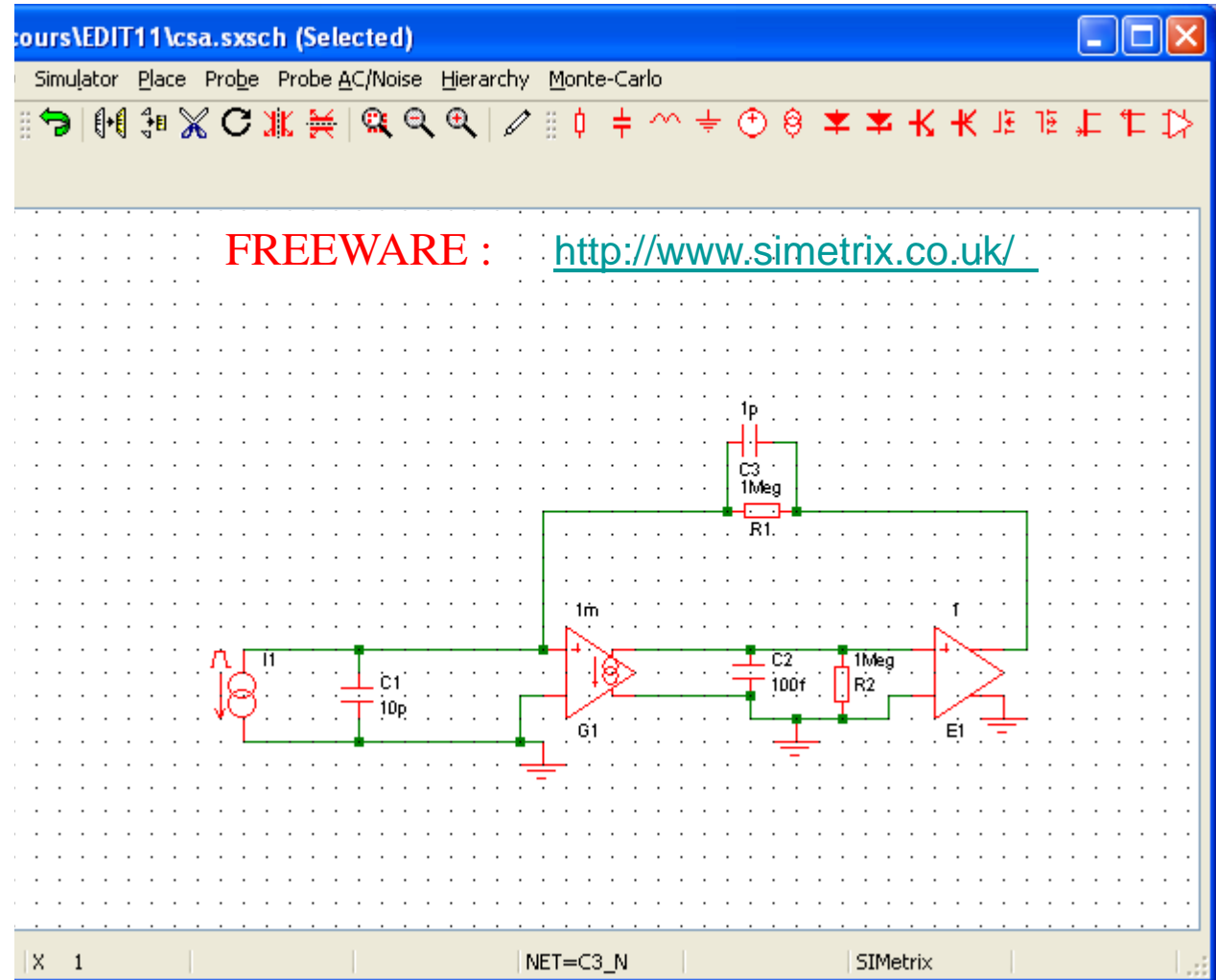


- Coexistence analog-digital
 - Capacitive, inductive and common-impedance couplings
 - A full lecture !
 - A good summary : there is no such thing as « ground », pay attention to current return



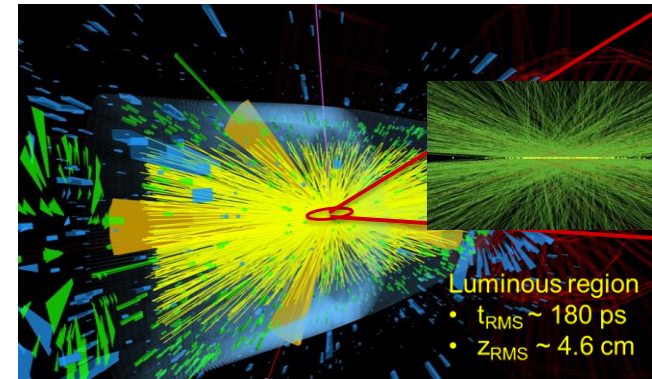
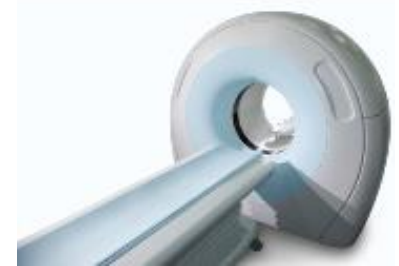
Example : bandwidth and EMC of simple charge preamp

- Simulate impulse response
- Frequency response
- Input impedance
- Ballistic deficit
- Effect of amplifier gain
- Effect of resistive feedback
- Test pulse injection
- Effect of input capacitance
- **Parasitic inductance**
- **Capacitive crosstalk**
- **Resistive/Inductive ground return**



Need for timing

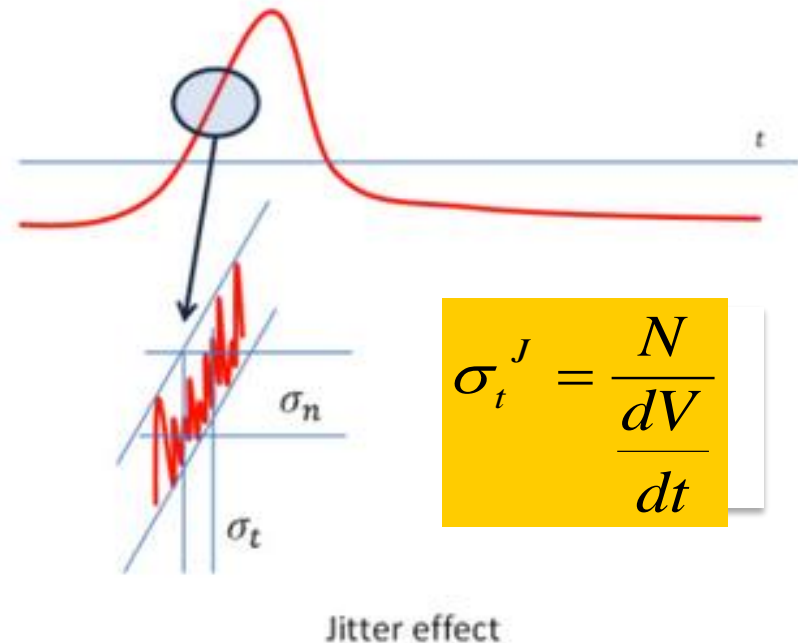
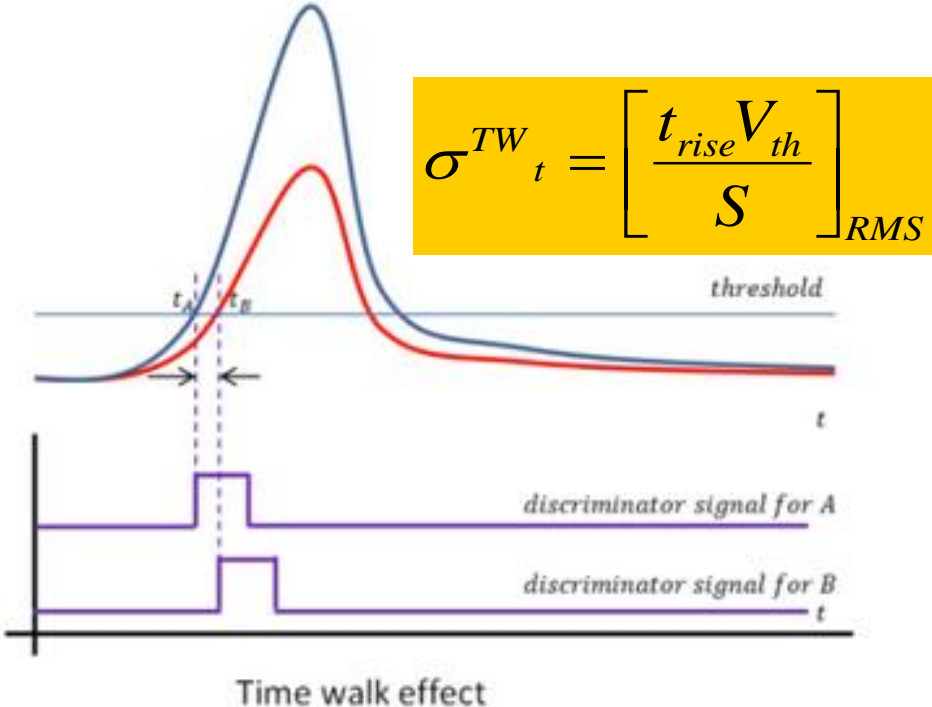
- Time resolution $< 50\text{ps}$ required by many experiments/applications keeping low power, large dynamic range
- **PET/ Time of Flight** measurements (SiPM)
 - Dynamic range : 1 pe (100fC) up to 3000 pe (300 pC)
 - Time resolution $< 100\text{ps}$
- **CMS High Granularity CALorimeter:** (Si pin diodes)
 - Large dynamic range : few fC up to $\sim 10\text{ pC}$
 - Calorimetry \Rightarrow Precision /linearity $< 1\%$
 - Fast timing ability $\sim 50\text{ps}$ (for $> 10\text{ mips}$ desirable)
 - Peaking time 15-20 ns (minimize noise, minimise Out of Time pileup)
 - Power on detector $< \sim 10\text{ mW/channel}$ all included
- **ATLAS High Granularity Timing Detector (LGAD)**
 - Time performance $\sim 30\text{ ps}$: To reject Time Pile up events \Rightarrow better particle identification



Time walk and time jitter

Time walk: the voltage value V_0 is reached at different time for signal of different amplitudes

Jitter: the noise is summed to the signal, causing amplitude variations



Due to the physics of signal formation

Mostly due to electronic noise

$$\sigma_t^2 = \left(\frac{t_{rise}}{S/N} \right)^2 + \left(\left[\frac{t_{rise} V_{th}}{S} \right]_{RMS} \right)^2 + \left(\frac{TDC_{bin}}{\sqrt{12}} \right)^2$$

Jitter

Time Walk

TDC

© N. Cartiglia Trento workshop 2016

<https://indico.cern.ch/event/485239/overview/>

- Jitter due to electronics noise:

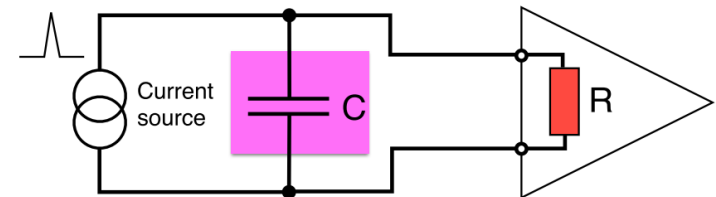
$$\sigma_t^J = \frac{N}{\frac{dV}{dt}}$$

- also presented as $j = tr / (S/N)$
- dV/dt prop to BW, N prop to \sqrt{BW} \Rightarrow jitter prop to $1/\sqrt{BW}$

\Rightarrow « the faster the amplifier the better the jitter ? »

\Rightarrow « High speed preamps need to be low impedance (50 Ω or less) »

NB : $tr = t_{10-90\%} = 2.2 \tau$.
 $f_{-3dB} = 1/2\pi\tau = 0.35 / t_{10-90}$
 $f_{-3dB} = 1 \text{ GHz} \leftrightarrow t_{10-90\%} = 300 \text{ ps}$
 $1 \text{ ps} = 300 \mu\text{m in vacuum}$



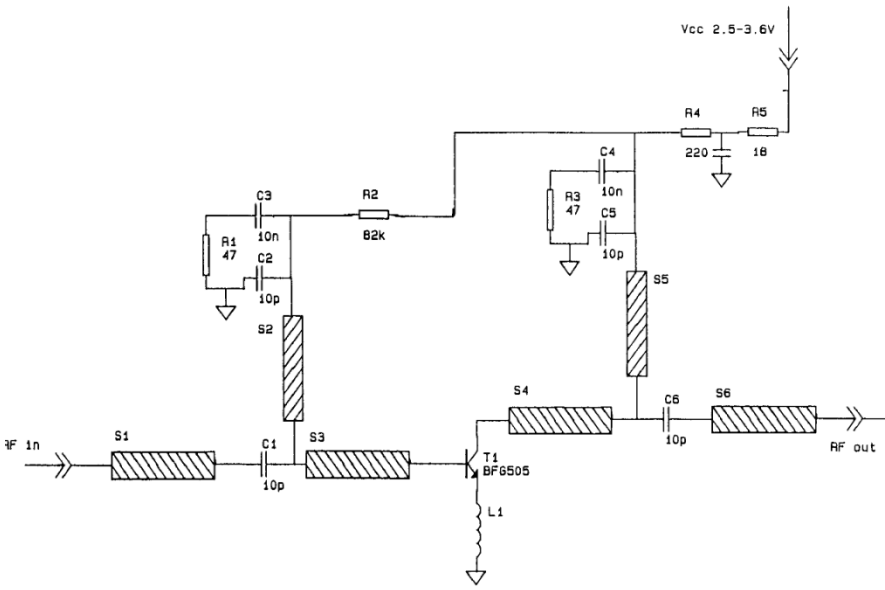
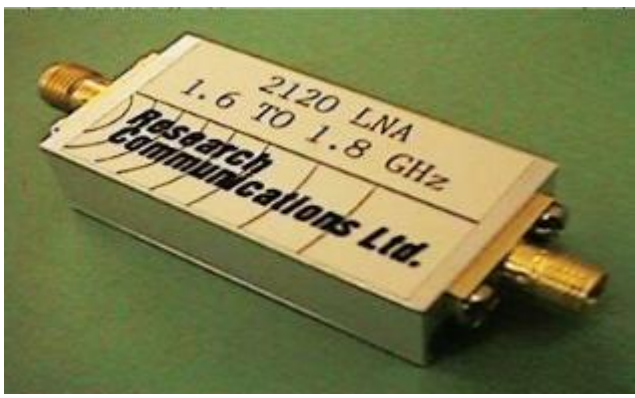


Figure 3

6 MHz RF
-10 dB
Input
75
100
100
T1
.1
470 uH
5
21
4K7
68
Q1
1K
100
100
75
100
-10 dB
Output

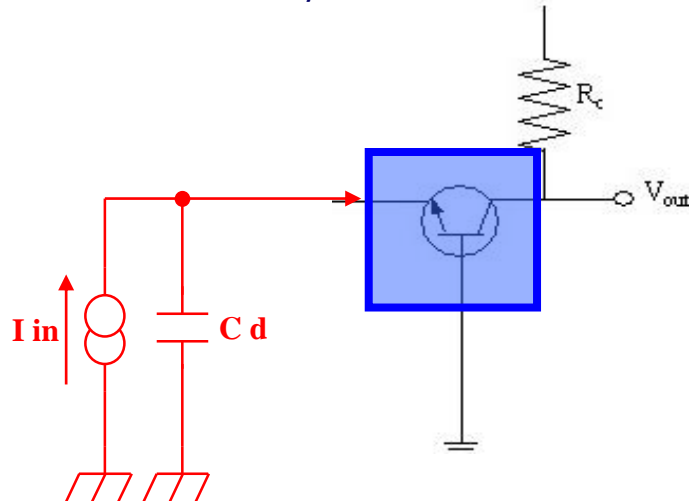
10.7 dB gain

T1 = 26% FT50-61 Ferrite tap @ 5t

- Open loop configurations : current conveyors, RF amplifiers
- Usually designed at transistor level MOS or SiGe

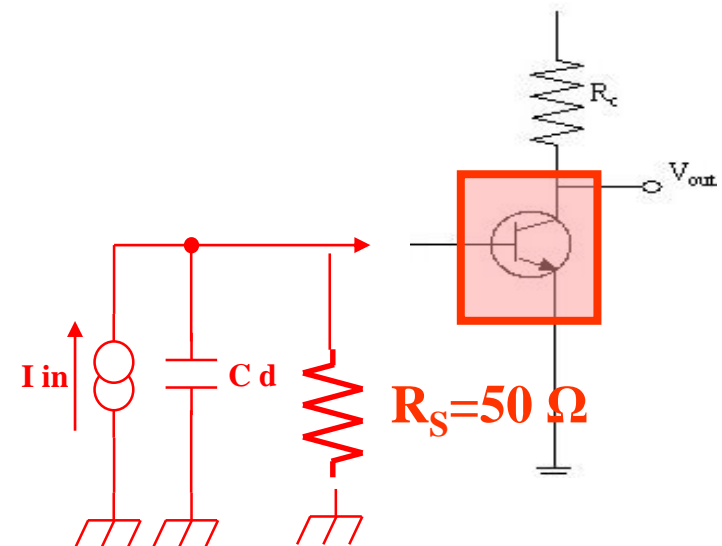
- **Current conveyors**

- **Small Z_{in}** : current sensitive input
- **Large Z_{out}** : current driven output
- Unity gain current conveyor
- E.g. : (super) common-base configuration
- Low input impedance : $R_{in} = 1/g_m$
- Transimpedance : R_c
- Bandwidth : $1/2\pi R_c C_u > 1 \text{ GHz}$



- **RF amplifiers**

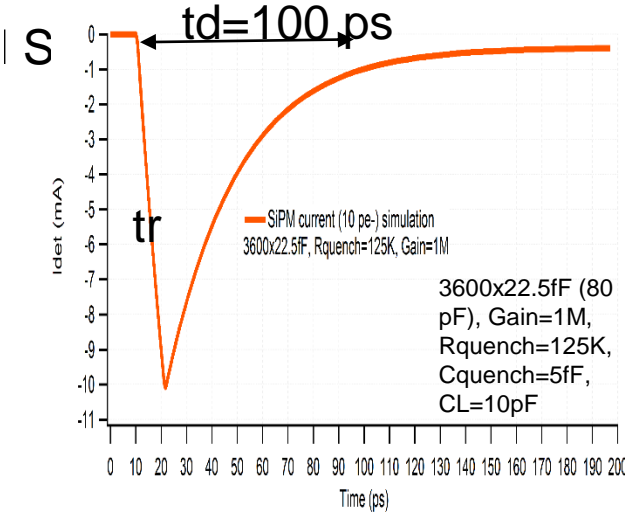
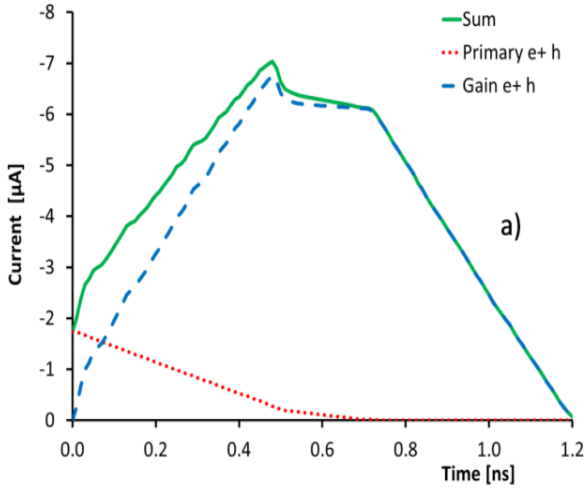
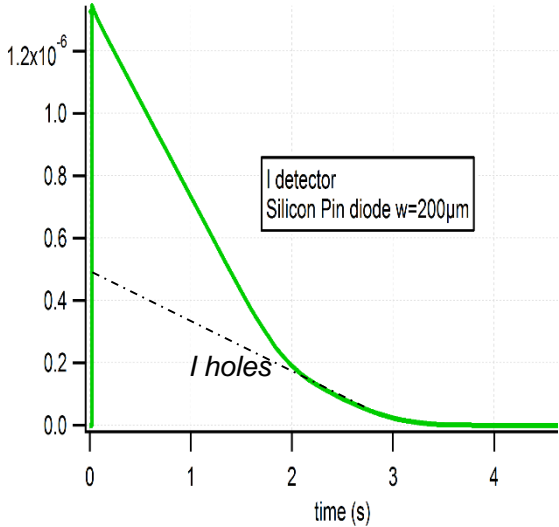
- **Large Z_{in}** : voltage sensitive input
- **Large Z_{out}** : current driven output
- Current conversion with resistor R_S
- E.g. common-emitter configuration
- Transimpedance : $-g_m R_c R_S$
- Bandwidth : $1/2\pi R_S C_t$



- PN diode $w = 200\mu\text{m}$
- Very short rise time : $t_r \sim 10\text{ps}$
- Relatively long «drift time» : $t_d \sim 2\text{ns}$

- LGAD sensor $w = 50\mu\text{m}$
- rise time : $t_r \sim 500\text{ps}$
- Decay time» : $t_d \sim 700\text{ps}$

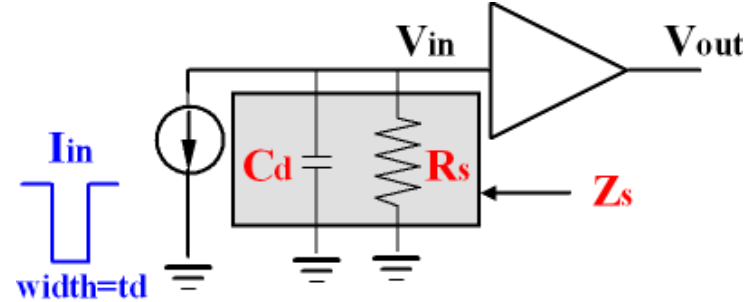
- SiPM detector (10pe-)
- very short rise time : $t_r \sim 10\text{ps}$
- Short duration : $t_d \sim 100\text{ps}$,



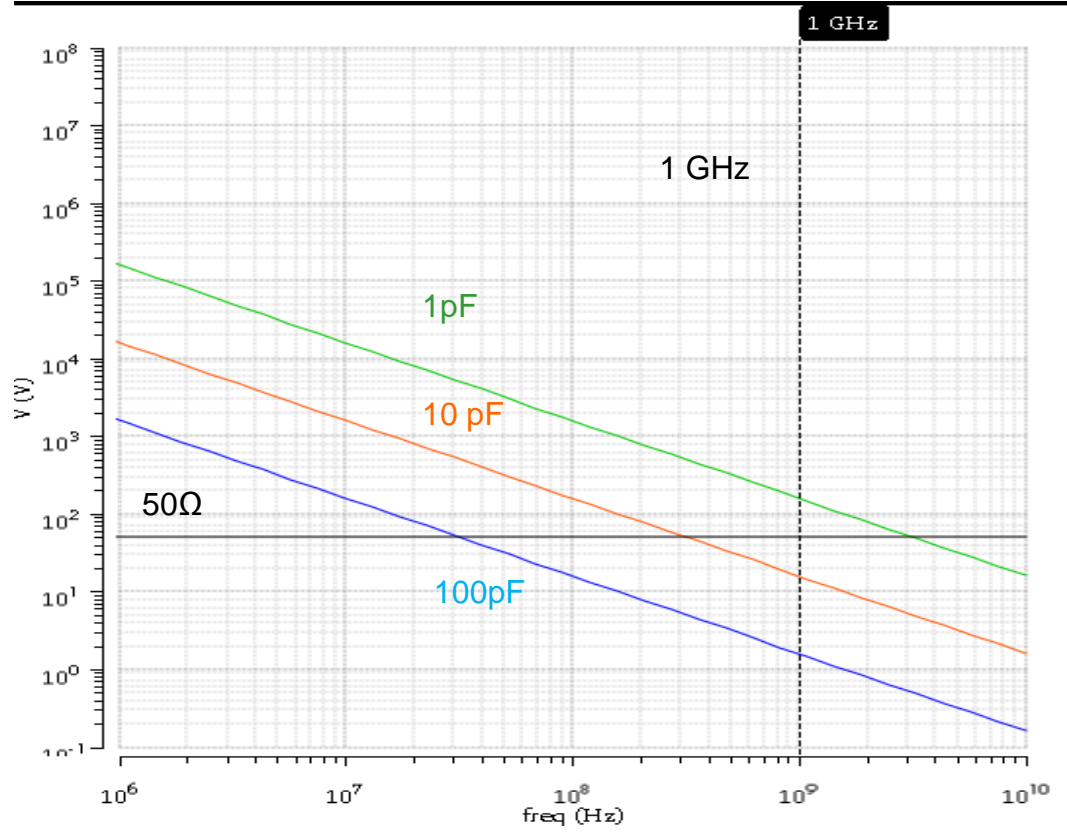
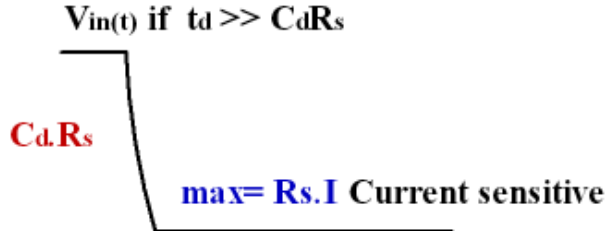
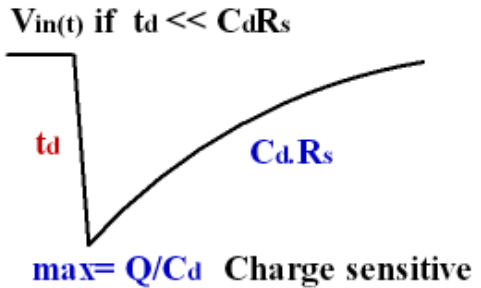
© Harmut Sadrozinski (Santa Cruz) “the beautiful risetime of the detector is spoilt by the electronics”

Detector impedance and input voltage

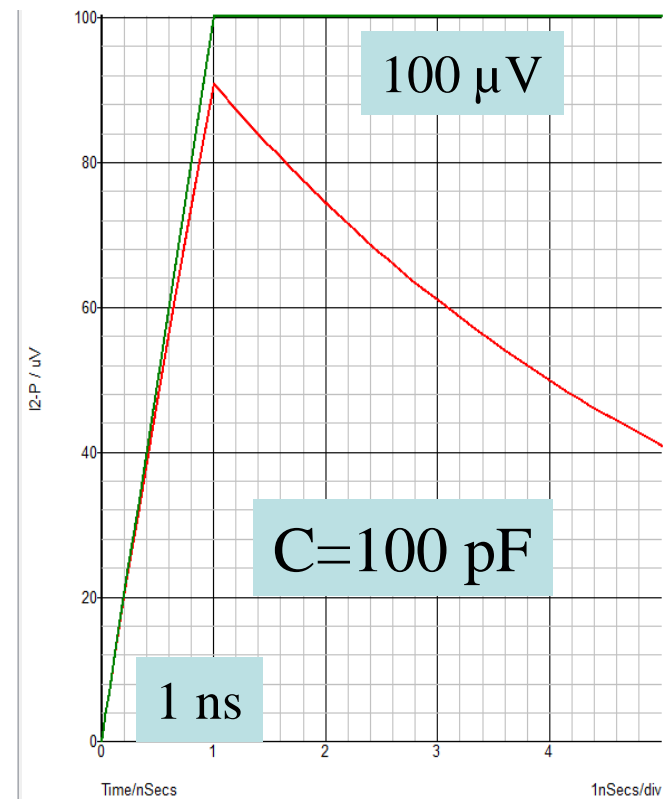
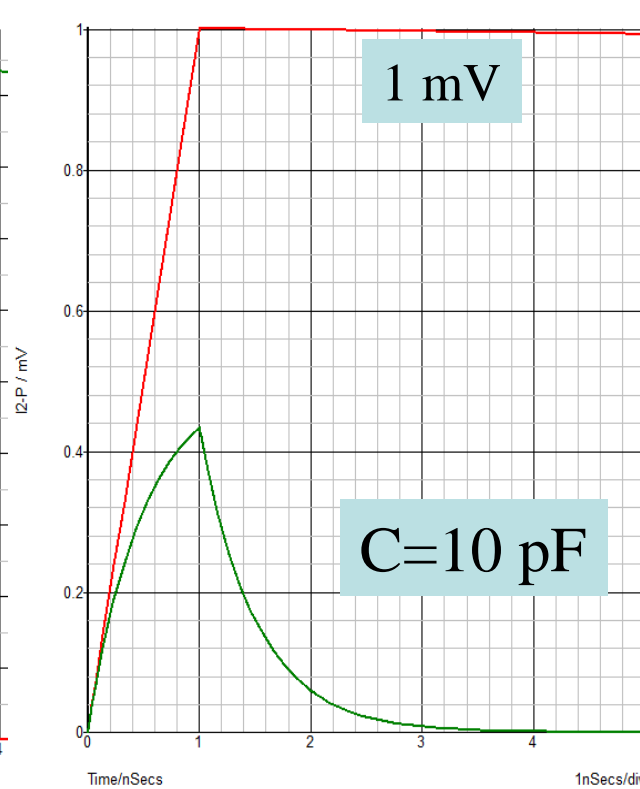
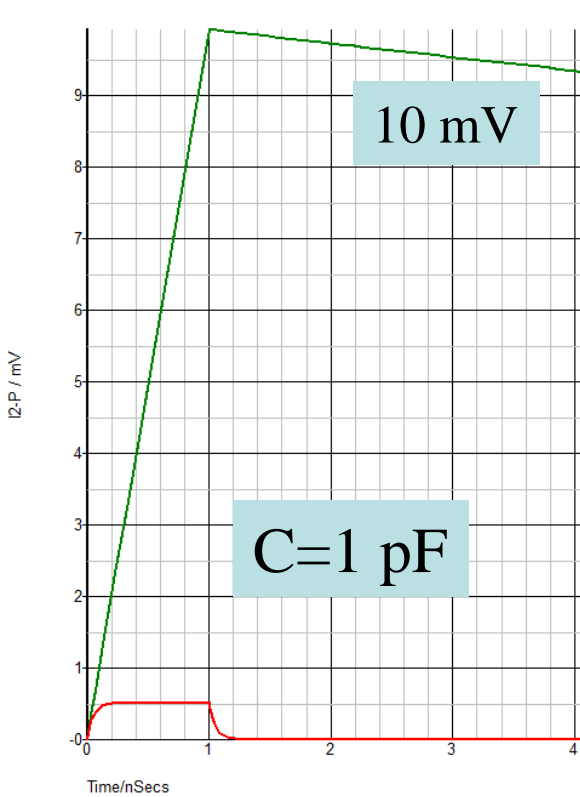
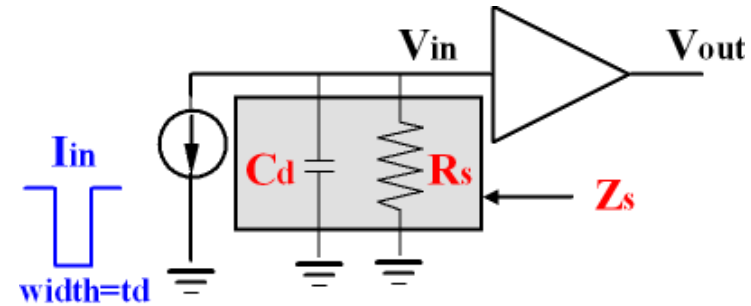
- 1 GHz, C_d =few tens of pF, input signal width <1ns
- $C_d > 1$ pF, Z_s @1GHz dominated by C_d
- Rise time: $t_r = t_d$ when $t_d \ll R_S C_d$ and $t_r = R_S C_d$ when $t_d \gg R_S C_d$



At HF : difficult to beat the capacitance
=> signal integrated on C_d

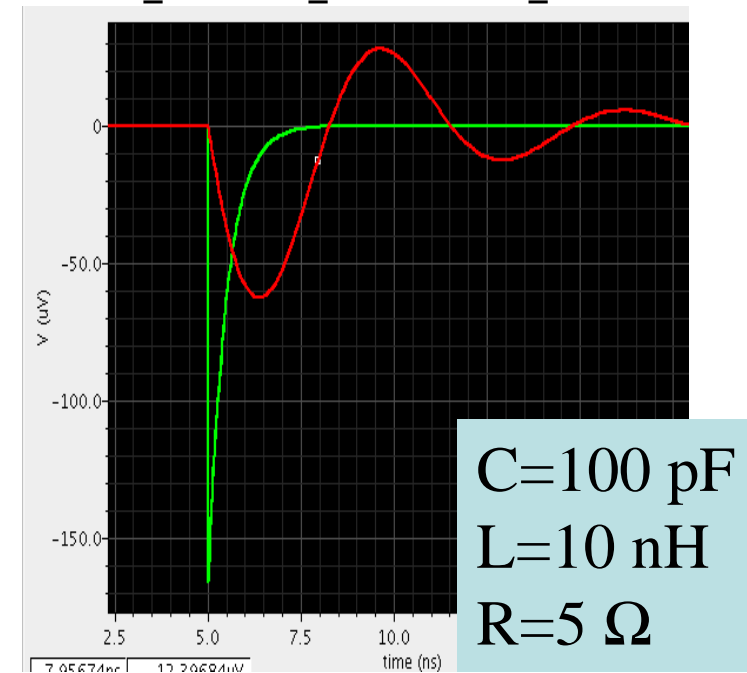
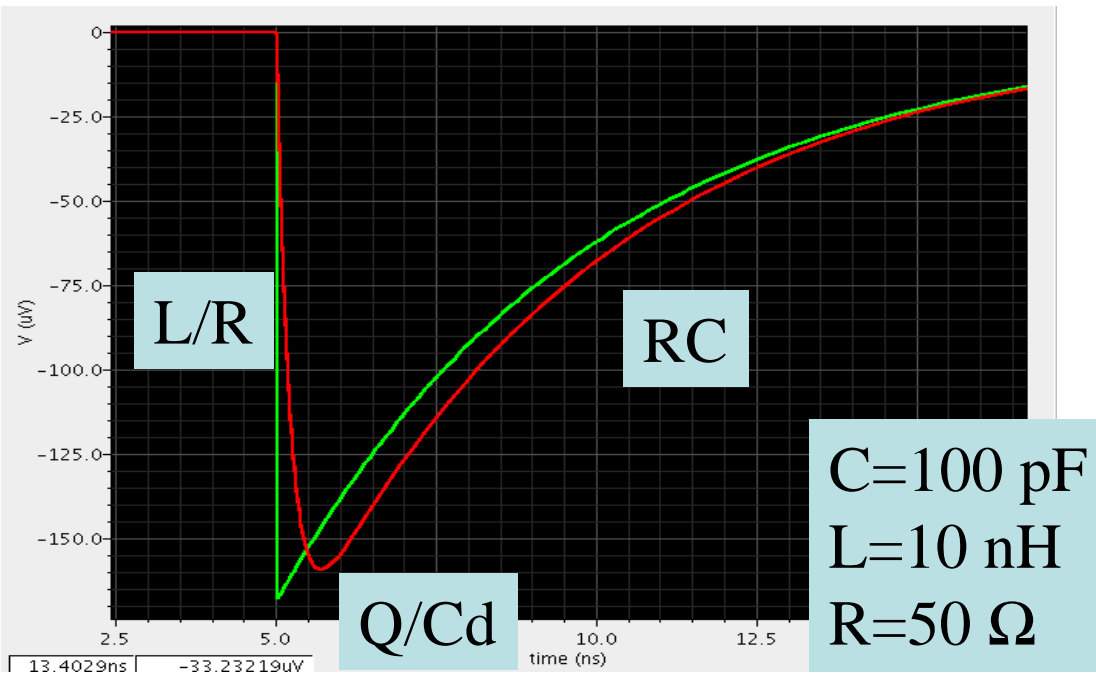
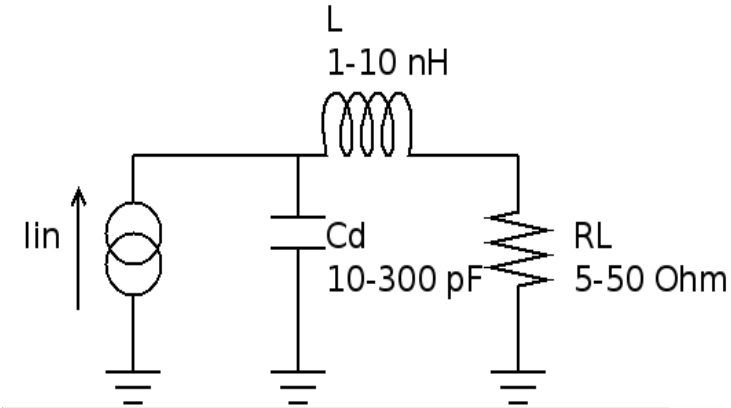


- Example : 10 fC – 1 ns signal from 1-10-100 pF sensors into 50 Ω (current) or 50k (voltage) preamp



Examples of pulse shapes

- SiPM pulse : $Q=160$ fC, $C_d=100$ pF, $L=0-10$ nH, $R_{PA}=5-50$ Ω
- Sensitivity to parasitic inductance
- Choice of R_{PA} : decay time, stability
- Small R_{PA} not necessarily the fastest
- Convolve with current shape... (here delta)



High speed amplifiers

- Response to very short pulse

- Broadband

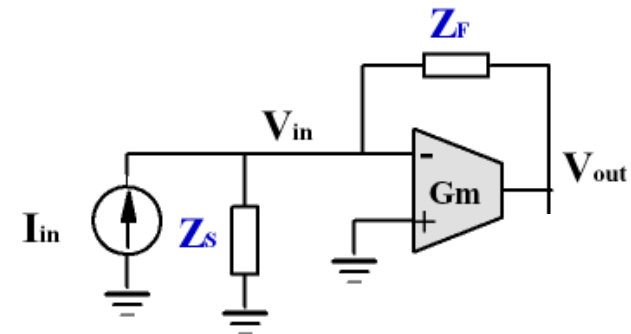
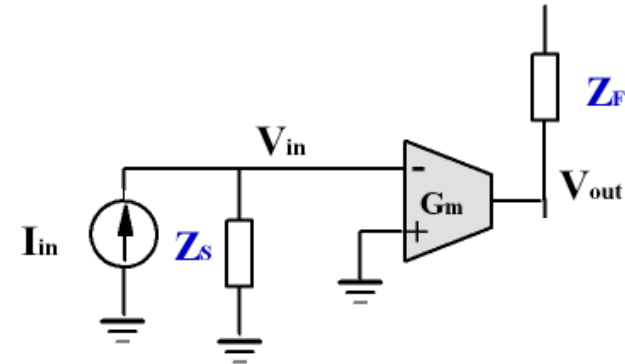
- $Z_{in} = R_s$ (50 Ohm)
- $V_{in} = Q/C_{in}$

$$- V_{OUT} = -G_m R_F \frac{Q_{IN}}{C_d}$$

- Transimpedance

- $Z_{in} \sim Z_f/G \sim 1/g_m$

$$- V_{OUT} = \frac{\frac{1}{G_m} - R_F}{1 + j\omega \frac{C_d}{G_m}} I_{IN} \approx -G_m R_F \frac{Q_{IN}}{C_d}$$



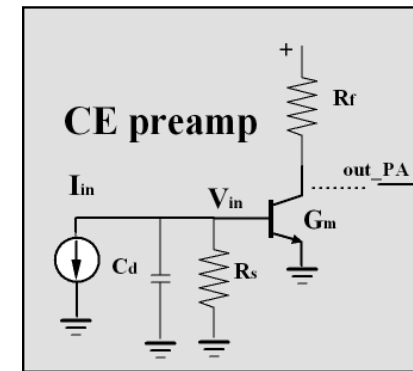
- Same response at High Frequency

- For highest speed : go to broadband. Faster, less stability issues

High speed amplifiers

- Jitter is given by [details in backup] :

$$\sigma_t^J = \frac{N}{dV/dt} = \frac{e_n}{\sqrt{2t_{10-90_PA}}} \frac{C_d \sqrt{t_{10-90_PA}^2 + t_d^2}}{Q_{in}} = \frac{e_n C_d}{Q_{in}} \sqrt{\frac{t_{10-90_PA}^2 + t_d^2}{2t_{10-90_PA}}}$$



- Optimum value: $t_{10-90_PA} = t_d$ (current duration)

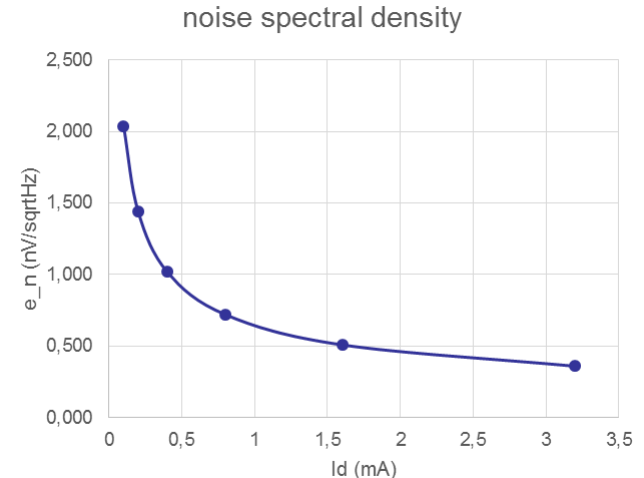
$$\sigma_t^J = \frac{e_n C_d}{Q_{in}} \sqrt{t_d}$$

C_d : detector capacitance
 t_{10-90_PA} : rise time of the PA
 t_d : drift time of the detector
 e_n : preamp noise density

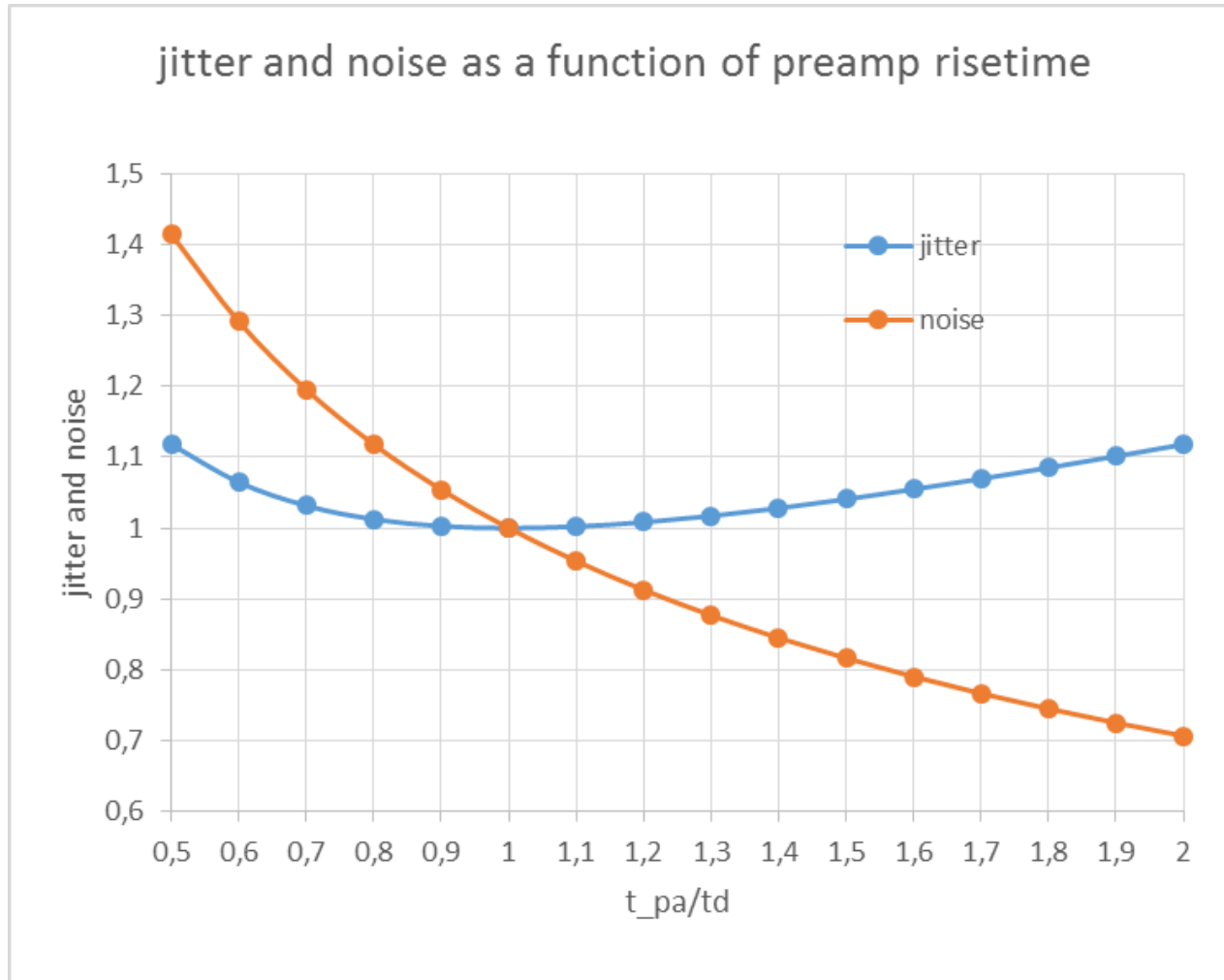
Dominated by sensor
 Electronics only gives
 the spectral density of
 the input transistor e_n

- Gives ps/fC as scales with $1/Q_{in}$
- Electronics noise e_n given by the input transistor transconductance g_m :

$$e_n = \sqrt{\frac{2kT}{g_m}} \approx \frac{2kT}{\sqrt{qI_D}}$$

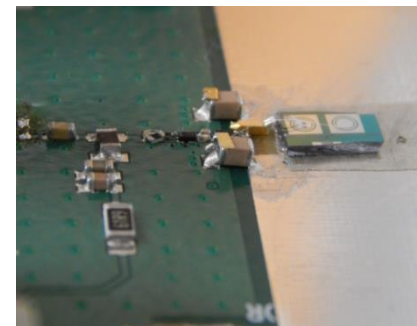


- Jitter optimum is rather shallow with preamp risetime
- But noise and minimum threshold goes up quickly with speed (as sqrt)

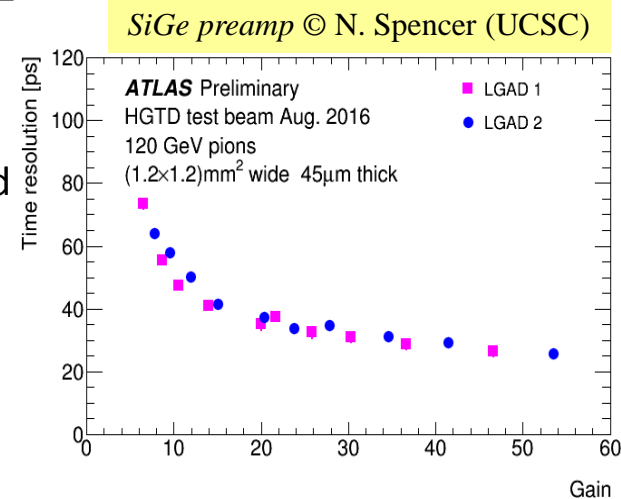


Examples [measurements from testbeam studies]

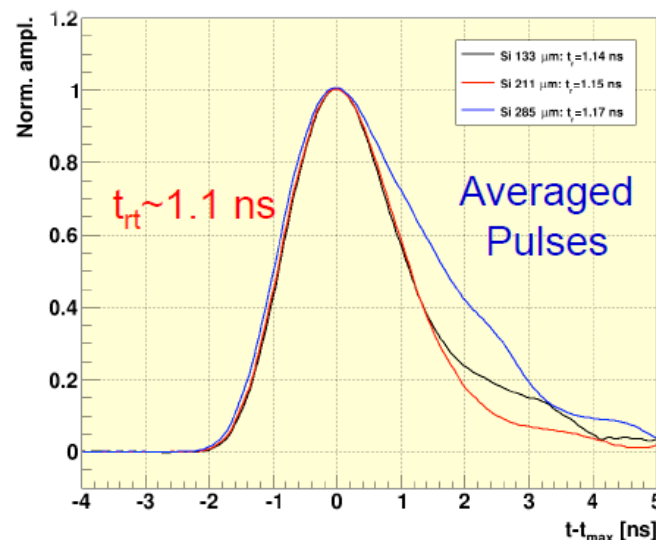
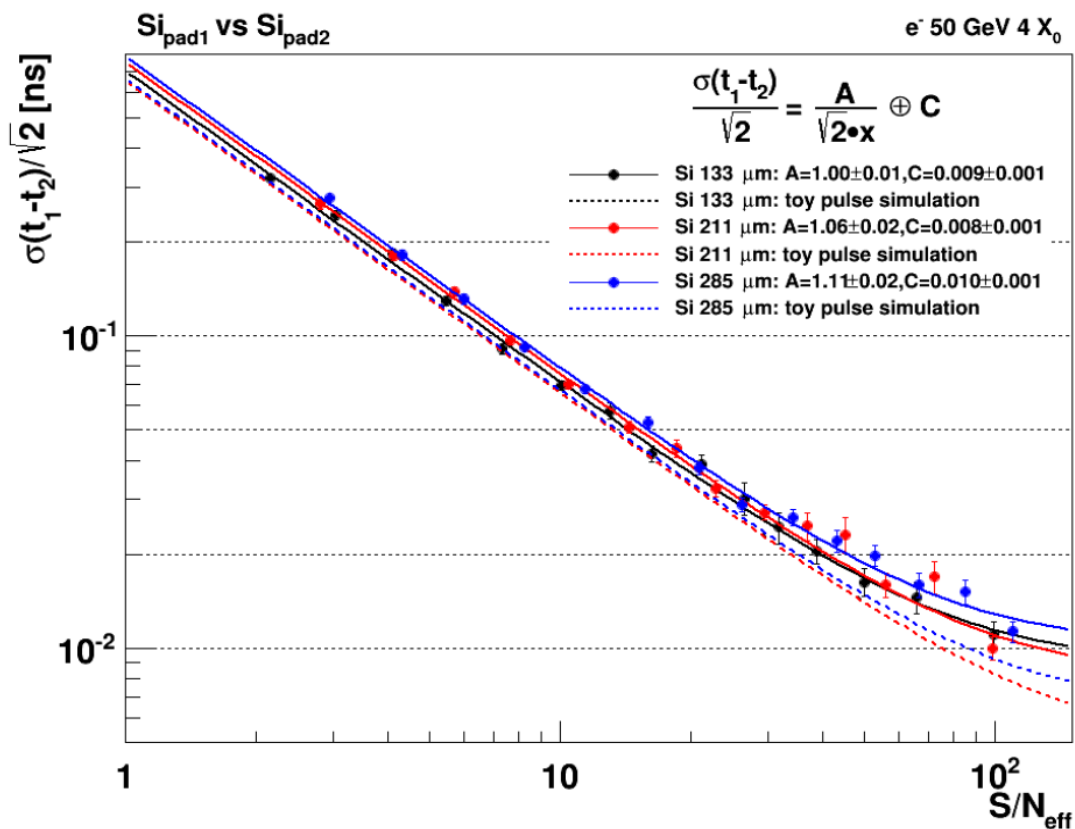
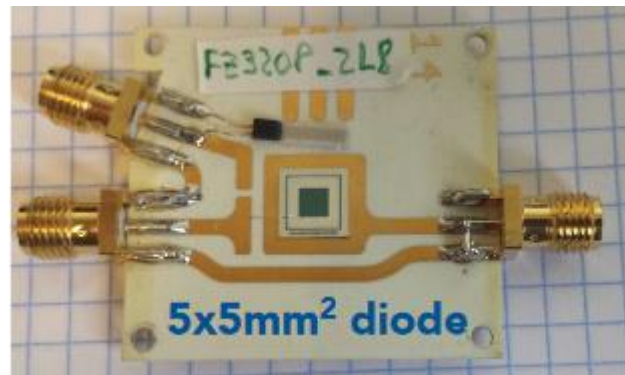
$$\sigma_t^J = \frac{e_n C_d}{Q_{in}} \sqrt{t_d}$$



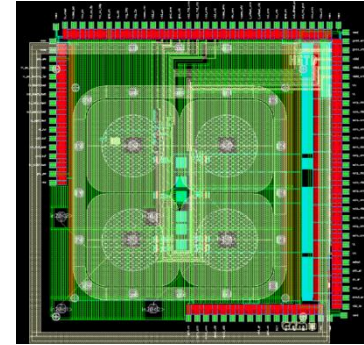
- NA62 tracker : PIN diode thickness 300 μm $A=0.09 \text{ mm}^2$
 - $C_d = 0.1 \text{ pF}$ $e_n = 11 \text{ nV}/\sqrt{\text{Hz}}$ $t_d = 3 \text{ ns}$ $\sigma = 60 \text{ ps}/\text{Q}(\text{fC})$
 - 1 MIP = 3 fC $\Rightarrow \sigma = 20 \text{ ps}/\#\text{MIP}$ ($\sim 60\text{-}200 \text{ ps}$ measured)
- CMS HGCal : PIN diode thickness 300 μm $A=25 \text{ mm}^2$
 - $C_d = 8 \text{ pF}$ $e_n = 1 \text{ nV}/\sqrt{\text{Hz}}$ $t_d = 3 \text{ ns}$ $\sigma = 420 \text{ ps}/\text{Q}(\text{fC})$
 - 1 MIP = 3.8 fC $\Rightarrow \sigma = 110 \text{ ps}/\#\text{MIP}$ ($\sim 200 \text{ ps}$ measured)
- ATLAS HGTD : LGAD diode thickness 50 μm $A= 2 \text{ mm}^2$
 $G = 10$
 - $C_d = 2 \text{ pF}$ $e_n = 2 \text{ nV}/\sqrt{\text{Hz}}$ $t_d = 0.5 \text{ ns}$ $\sigma = 50 \text{ ps}/\text{Q}(\text{fC})$
 - 1 MIP = 5 fC ($G=10$) $\Rightarrow \sigma = 10 \text{ ps}/\#\text{MIP}$ ($\sim 40 \text{ ps}$ measured)
- SiPM $G = 10^6$
 - $C_d = 300 \text{ pF}$ $e_n = 1 \text{ nV}/\sqrt{\text{Hz}}$ $t_d = 100 \text{ ps}$ $\sigma = 3 \text{ ns}/\text{Q}(\text{fC})$
 - 1 pe = 160 fC $\Rightarrow \sigma = 20 \text{ ps}/\#\text{pe}$ ($\sim 60 \text{ ps}$ measured)



- CMS HGCAL testbeam measurements
- Jitter : $j \sim 1 \text{ ns} / \text{S/N}$
 - But S and N depend on BW...
 - Parts come from detector and from electronics

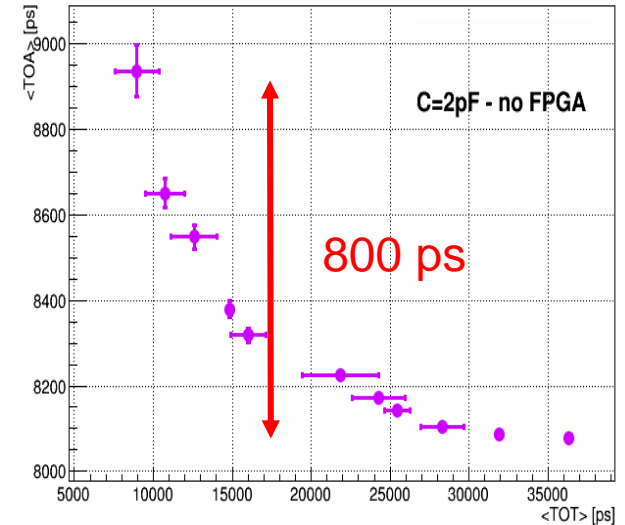
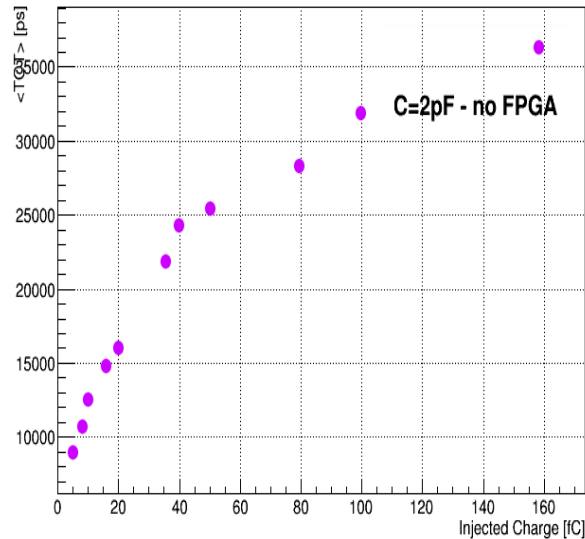
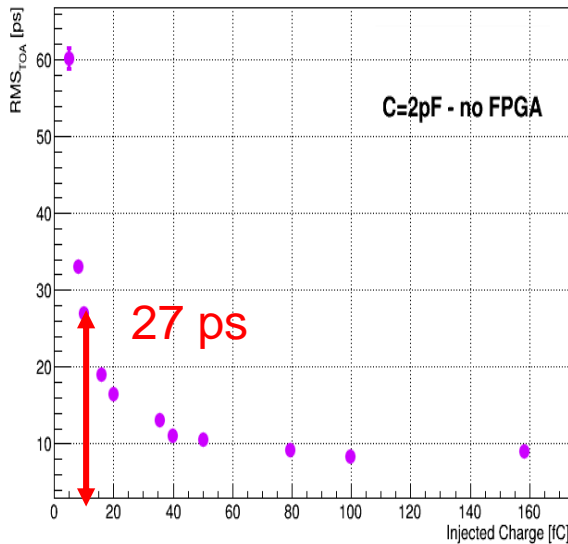


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<https://indico.cern.ch/event/468486>

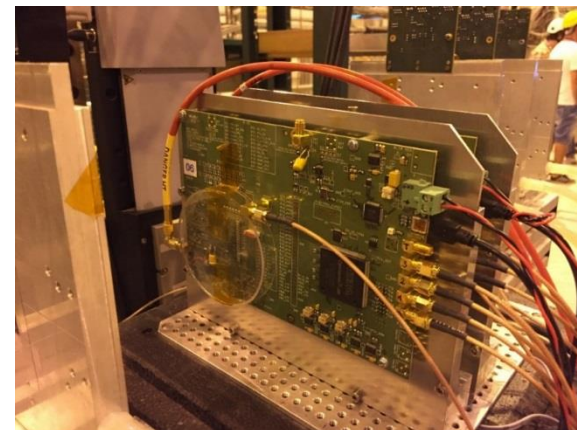


- ALTIROC ASIC designed for HGTD (Atlas LGAD Timing Read-Out Chip)
 - Broadband amplifier + high speed discriminator $P_d = 1 \text{ mW}$
 - Optimized for 1 mm^2 $50 \mu\text{m}$ LGAD ($C_d=2 \text{ pF}$)
- TOA and TOT vs injected charge with additional $C_d= 2 \text{ pF}$
- Preamp and testboard capacitance : $\sim 1.3 \text{ pF}$
- **Jitter = 27 ps @ 10 fC**
- Time walk = 800 ps

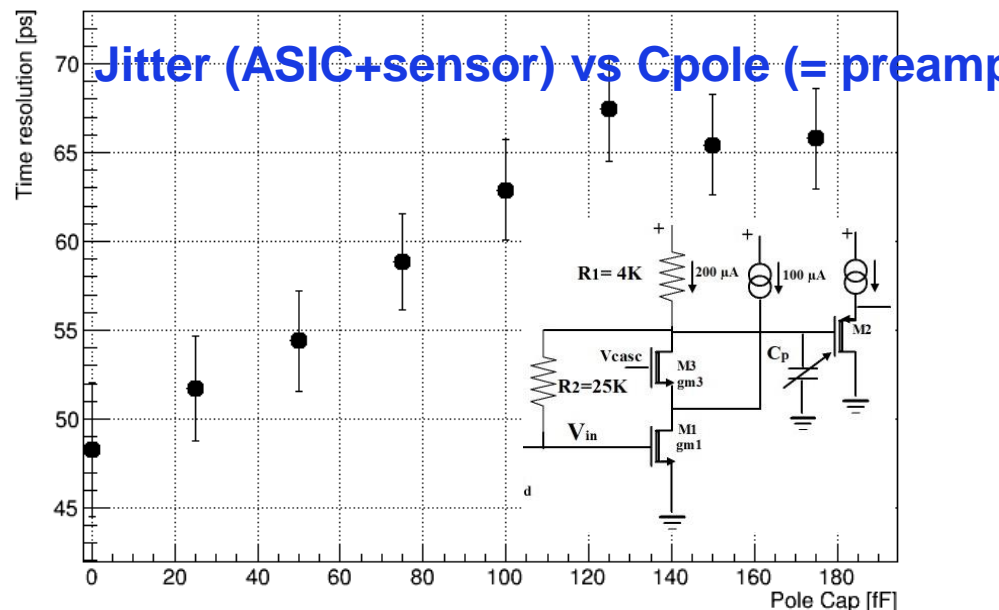
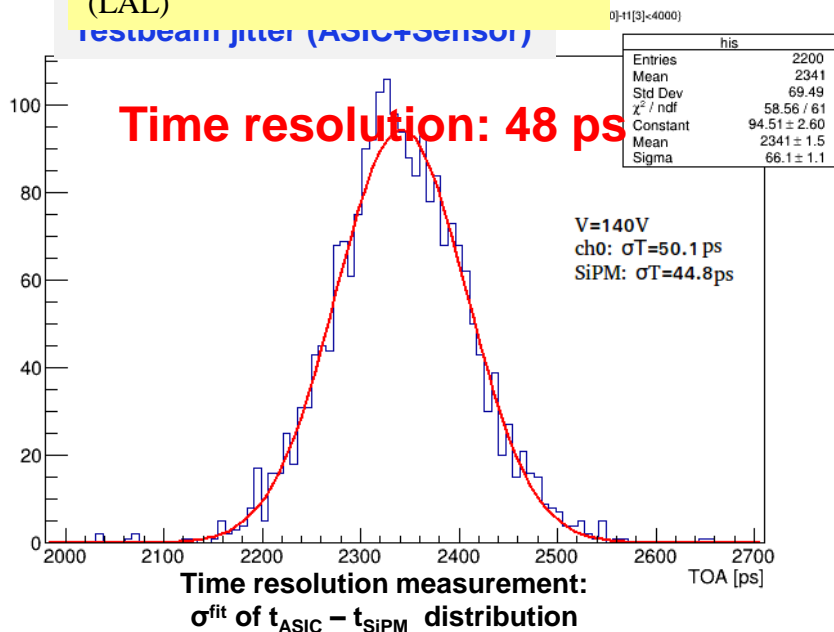
© C. Agapopoulou LAL



- 1x1 mm² sensors fabricated by CNM/IFAE Barcelona
- Bump-bonded to ALTIROC0 at Barcelona
- Sensor biased at - 80 V
- **Testbeam measurement ASIC+Sensor (LGAD signal)= 48 ps**



© C. Agapopoulou N. Makovec (LAL)

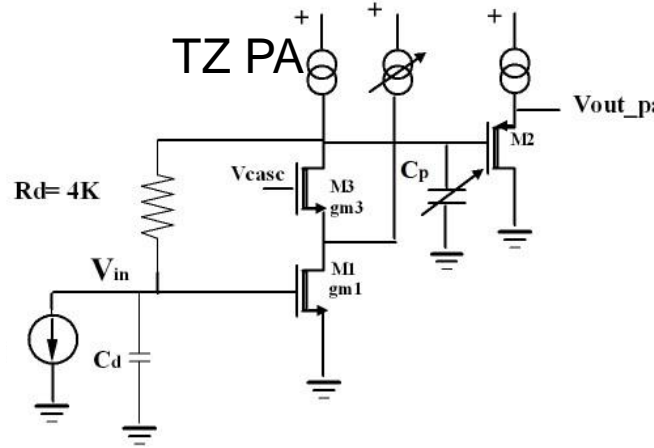
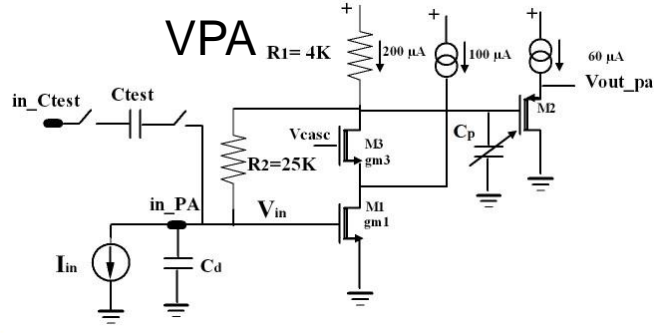
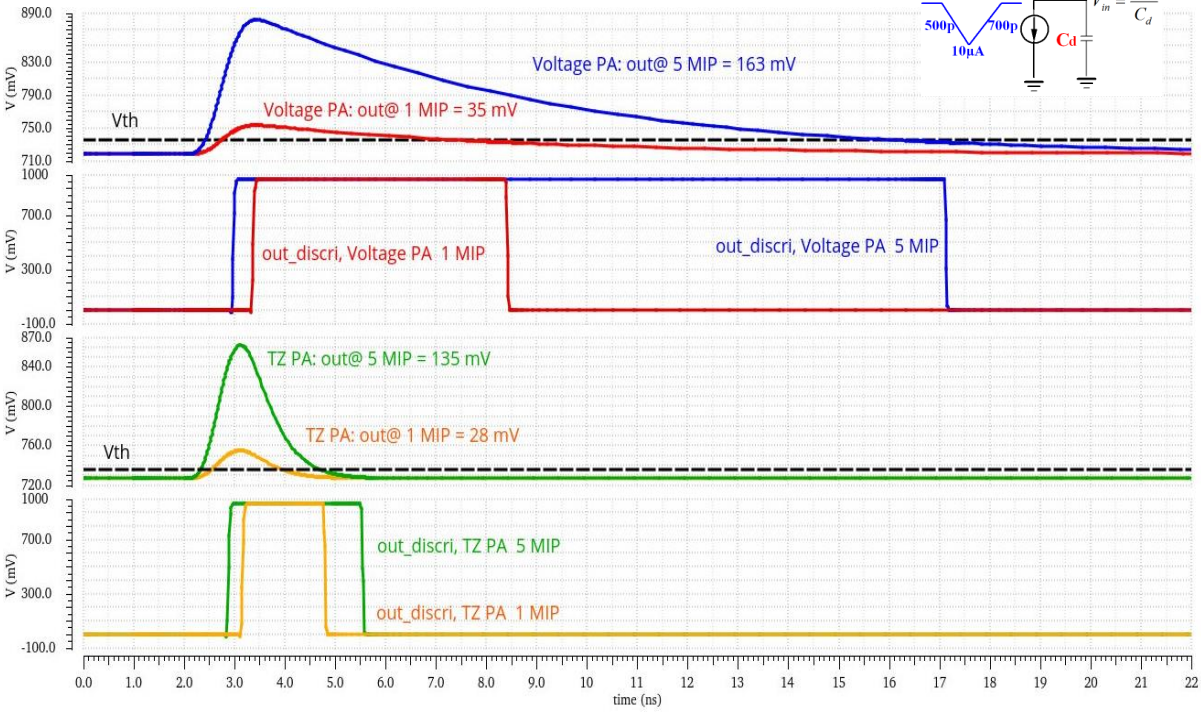
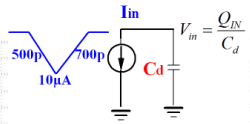


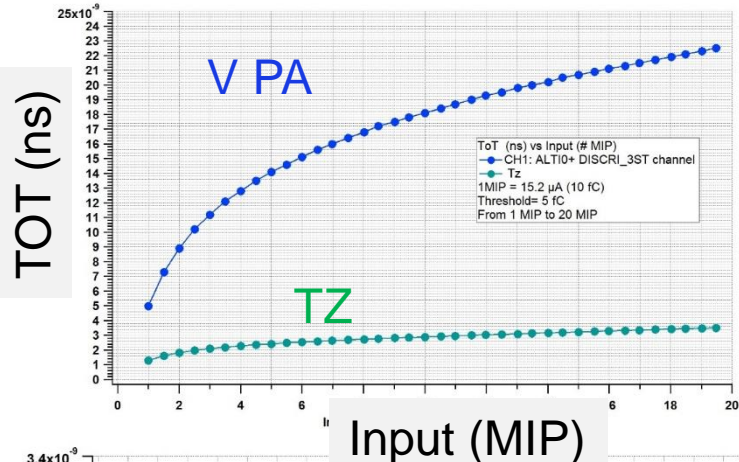
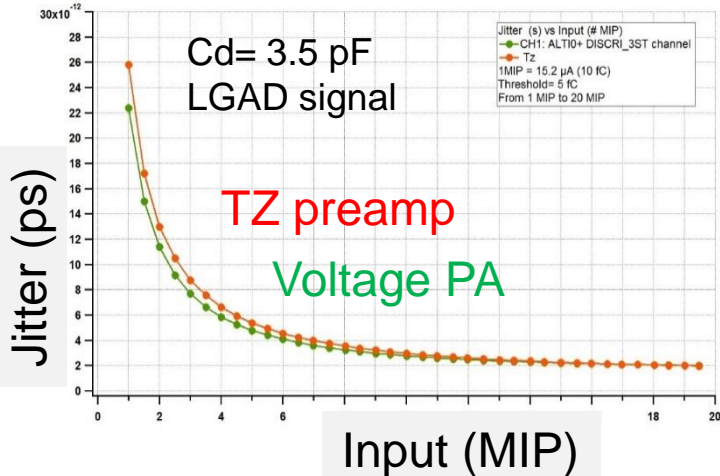
ALTIROC best input preamp: Voltage PA or TZ PA?

- Jitter: calculation gives the same result for VPA and TZ

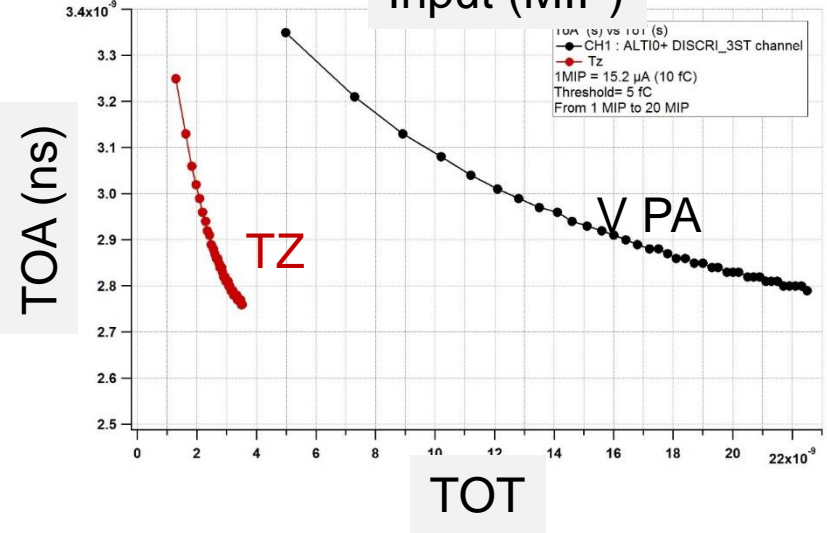
- Fall time given by $2.2 \cdot R_{in_pa} \cdot C_d$
 $R_{in_TZ\ pa} = 150\ \Omega$ whereas $R_{in_Voltage\ PA} \sim 1.5\ K\Omega$
 \Rightarrow **TOT_TZ (few ns) very different from TOT_VPA**

$$\sigma_t^J = \frac{e_n C_d}{Q_{in}} \sqrt{t_d}$$

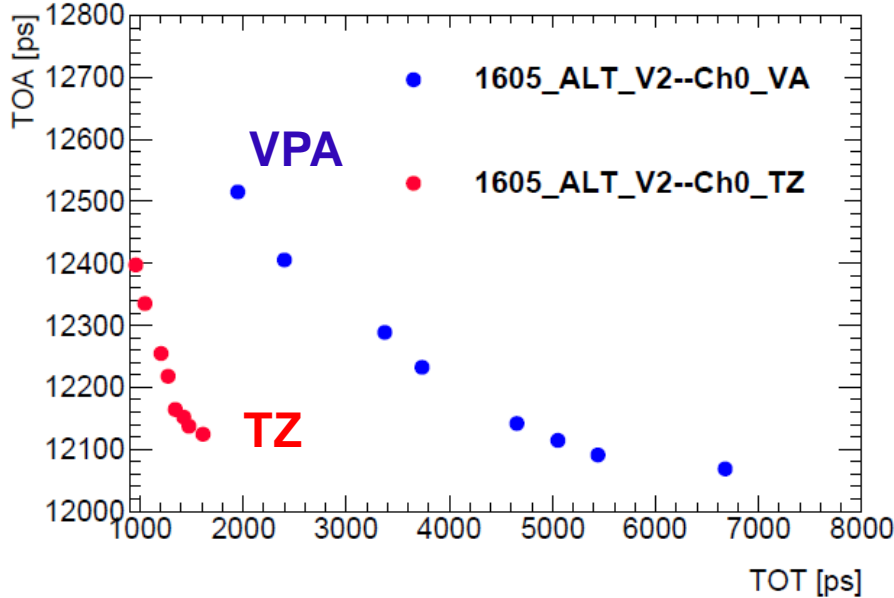
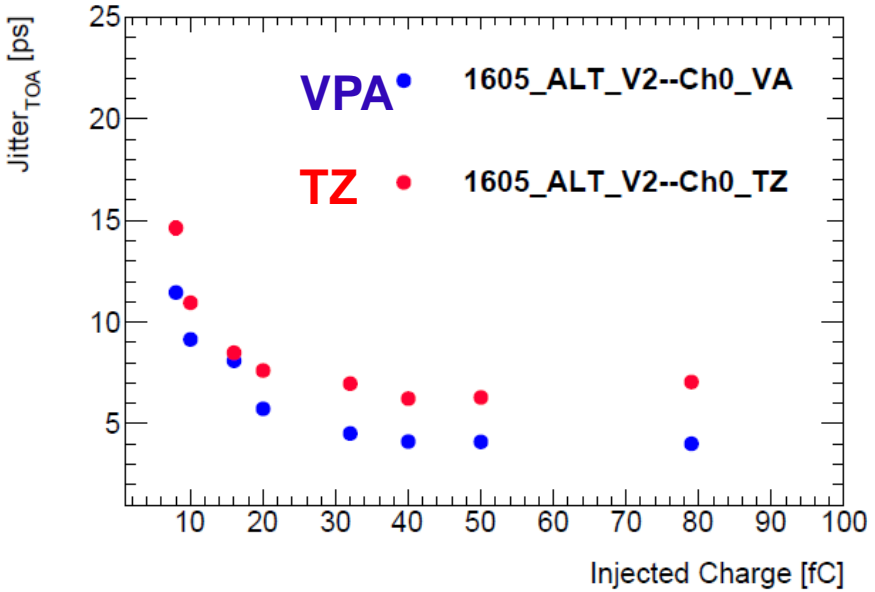




Jitter similar for TZ and VPA architectures but
TOA vs TOT sensitivity very different between these 2 architectures
 ⇒ TDC for TOT meas. different for VPA and TZ_PA
 ⇒ Better resolution needed for TZ



- ALTIROC0_V2 (Submission December 2017) : same as ALTIROC0_V1 but faster VPA and the four 20pF- channels replaced by 4 TZ preamps



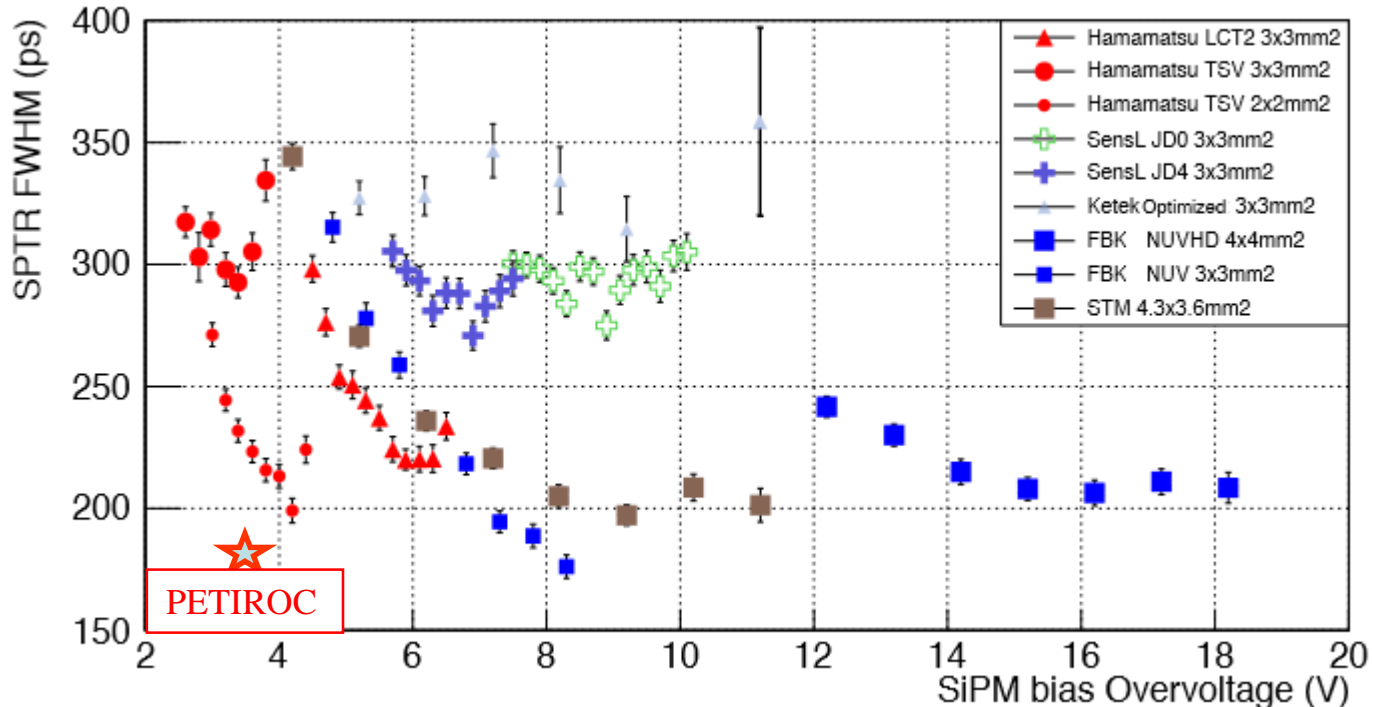
• SPTR

- FWHM ~200 ps
- Rms ~ 80 ps

Single photon time resolution of state of the art SiPMs

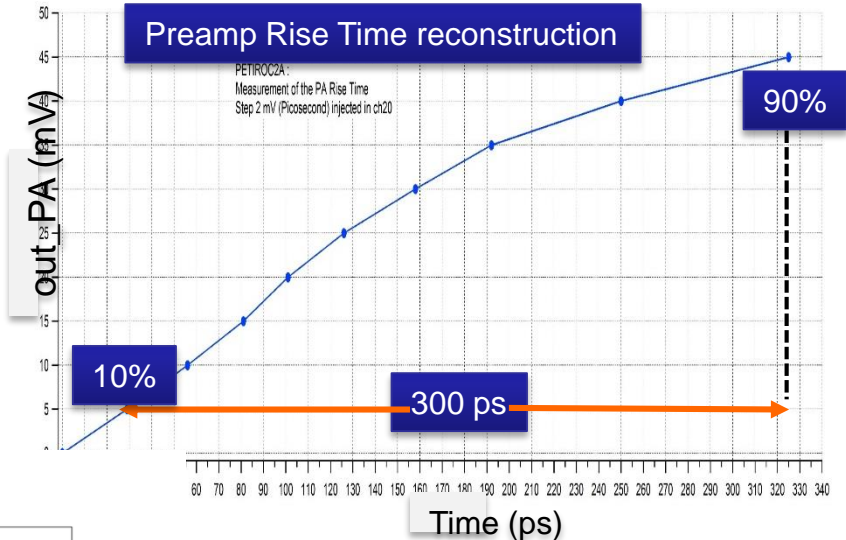
M.V. Nemallapudi,¹ S. Gundacker, P. Lecoq and E. Auffray

CERN,
23 Rue de Meyrin, Geneva, 1211-CH

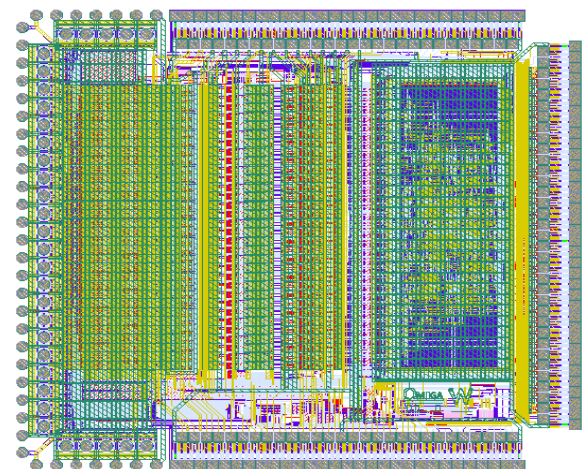
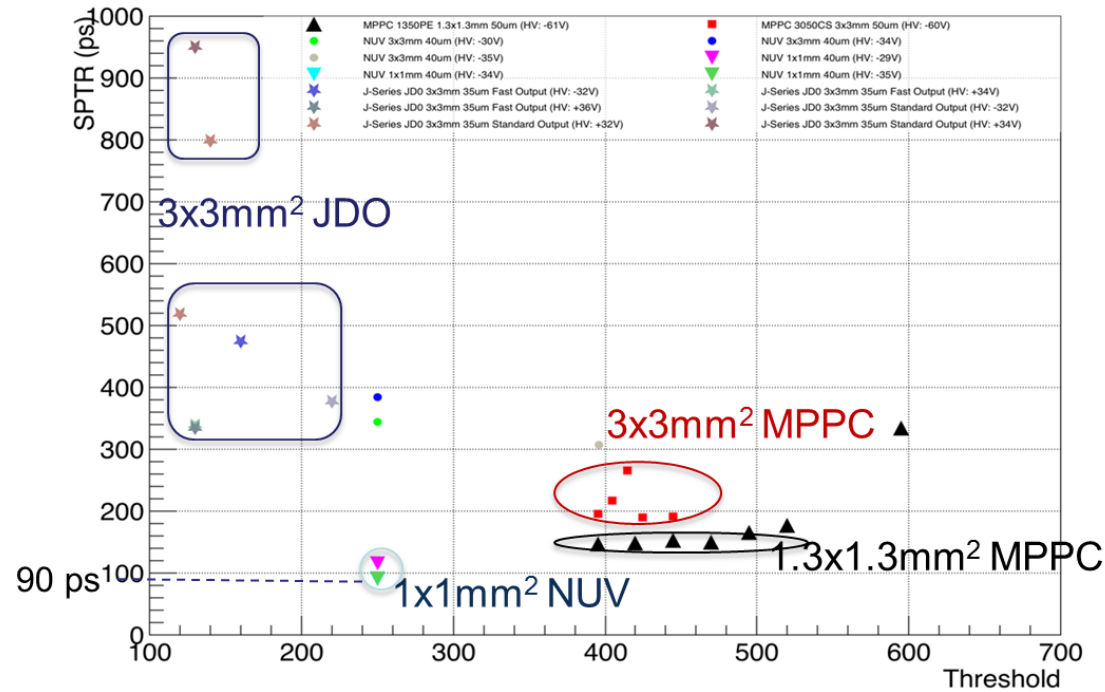


Going to lower SPTR

- Expect ~ 20 ps/pe
- NINO risetime ~1 ns
- Test with PETIROC2 (tr = 300 ps)
 - 1 GHz preamp and discri
 - SPTR = 40 ps rms (90 ps FWHM)
- Possible effect of stray inductance

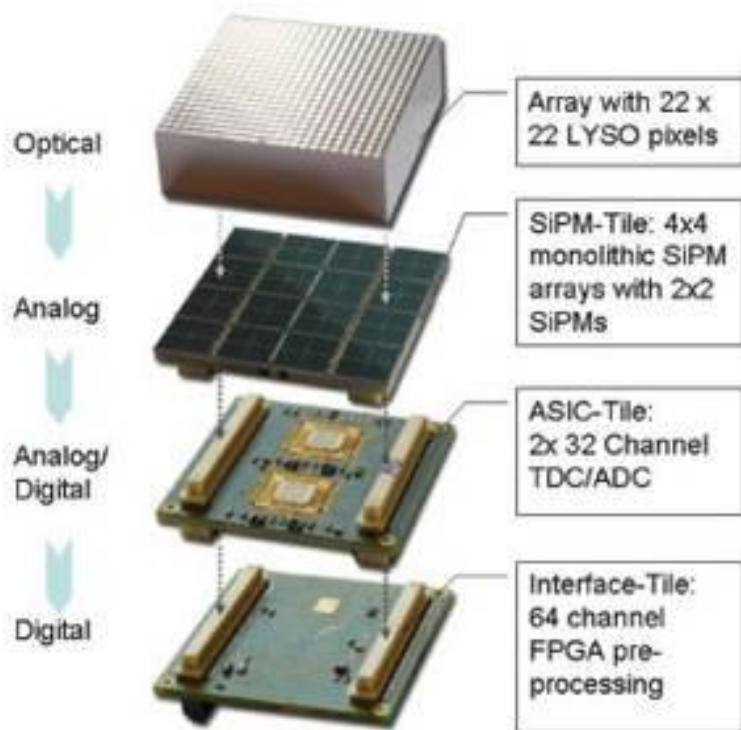


Petiroc2A SPTR

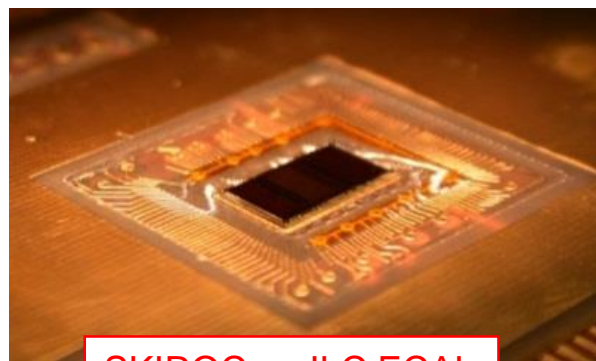


- Imaging calorimeters ramping up !
 - Require highly integrated R/O electronics : System On Chip
 - Low power, low noise, high speed, large dynamic range
 - Timing capability down to a few tens of ps
 - Lots of system issues
- Timing performance dominated by sensor characteristics
 - Capacitance, duration, MIP charge
 - Theory predicts :
 - Electronics affects only $g_m \sim I_d/2U_T$
- Work getting organized towards 10 ps (1 ps ?) timing

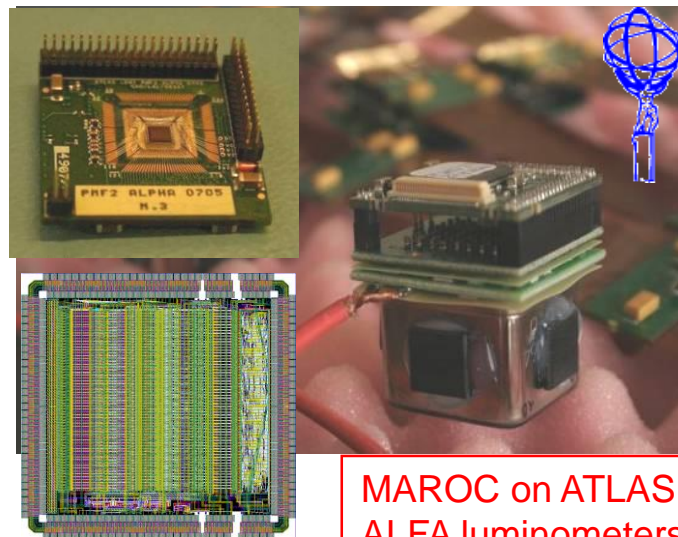
$$\sigma_t^J = \frac{e_n C_d}{Q_{in}} \sqrt{t_d}$$



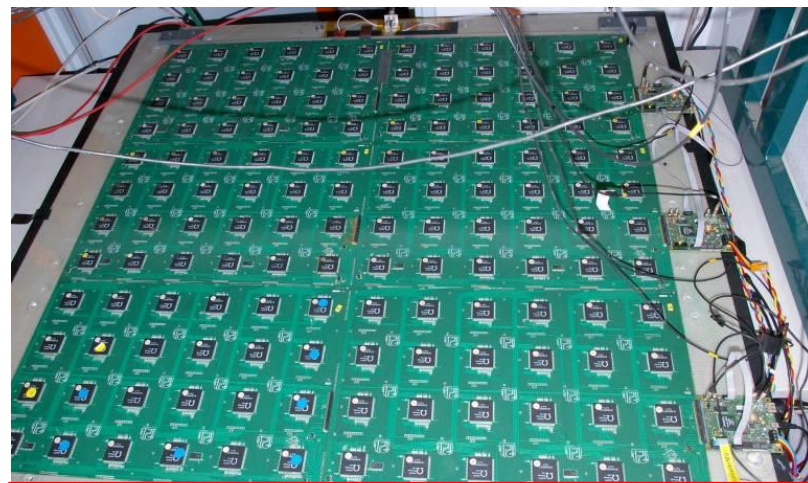
PET hyperimage project [P. Fisher]



SKIROC on ILC ECAL



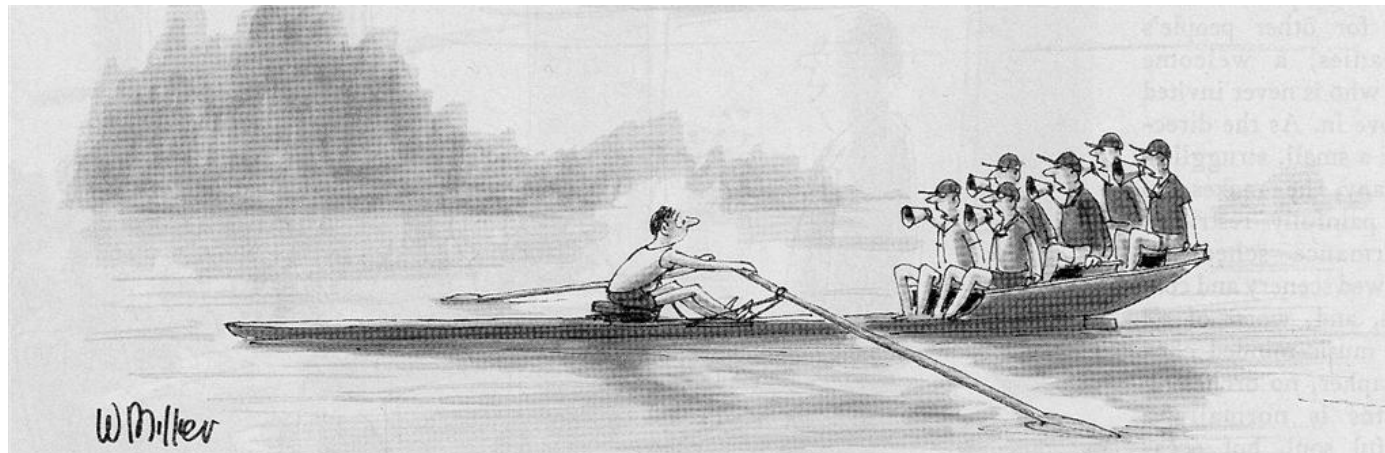
MAROC on ATLAS ALFA luminometers



1m² RPC detector for ILC DHCAL [I. Laktineh]

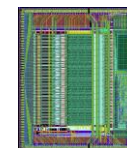
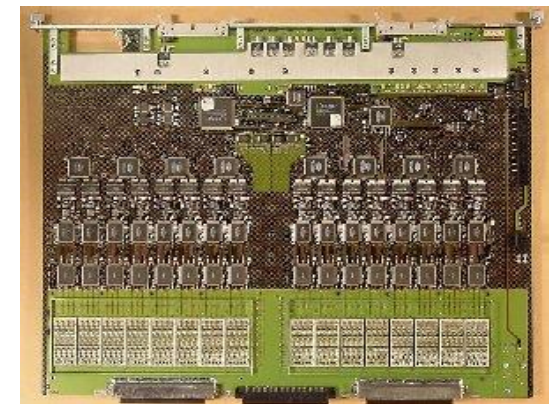
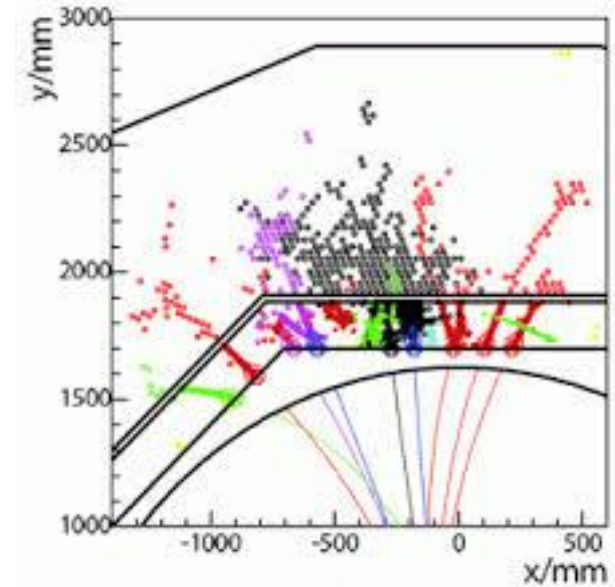
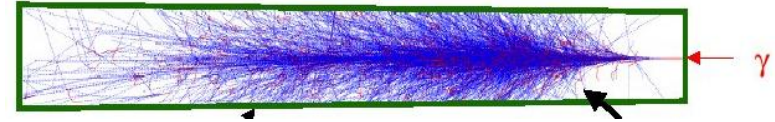
- Importance of electronics in detector performance
- Electronics getting more and more integrated on/in detectors (and vice versa !)
- Importance of team building

- Importance of team building



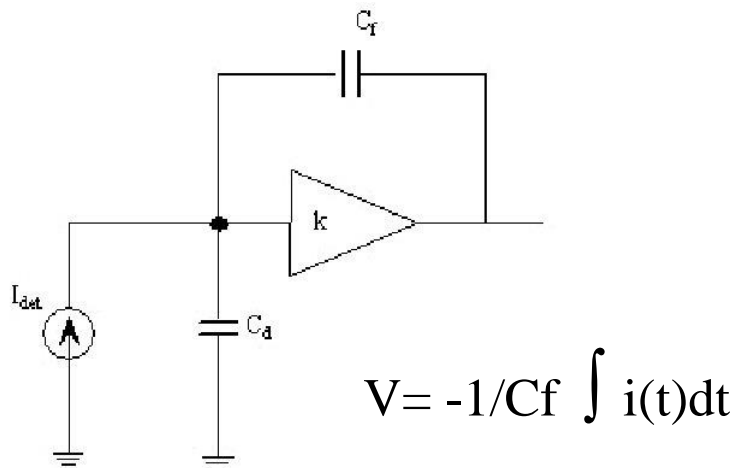
Evolution of calorimetry

- 3D calorimetry : eta, phi, Energy
- 4D calorimetry : x,y,z,E
- 5D calorimetry : **x,y,z,E,t**
 - High granularity=> Millions of channels => **Low power !**
 - Power pulsing ~1% for ILC
 - Low power + CO2 cooling for HL-LHC
 - Energy measurement : Large dynamic range
 - MIP sensitivity => low noise (~0.1 fC)
 - Up to thousands of MIPs (~10 pC)
 - Timing information
 - Nice addition for ILC for PID : few ns is enough
 - Crucial for HL-LHC : pileup mitigation, need **few tens of ps**
 - Embedded electronics vs data out
 - Daisy chain and low power busses for ILC
 - High speed e/optical links for HL-LHC
 - Radiation levels
 - Negligible at an ILC
 - Daunting at HL-LHC : >100 Mrad 1^{E16}N



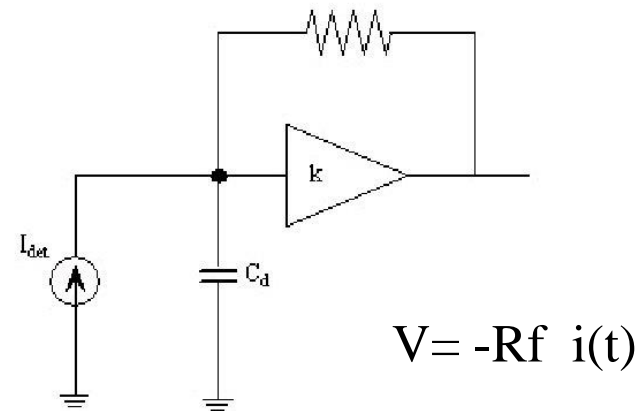
- **Charge preamp**

- Capacitive feedback C_f
- $V_{out}/I_{in} = -1/j\omega C_f$
- Perfect integrator : $v_{out} = -Q/C_f$
- Difficult to accommodate large SiPM signals (200 pC)
- Lowest noise configuration
- Need R_f to empty C_f



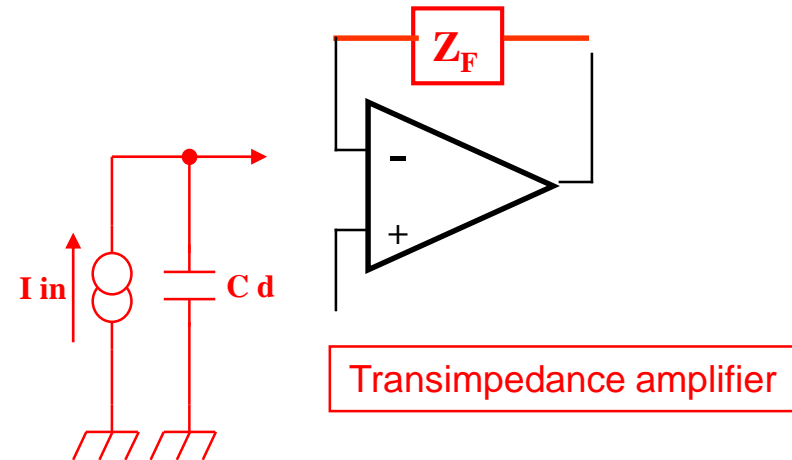
- **Current preamp**

- Resistive feedback R_f
- $V_{out}/I_{in} = -R_f$
- Keeps signal shape
- Need C_f for stability



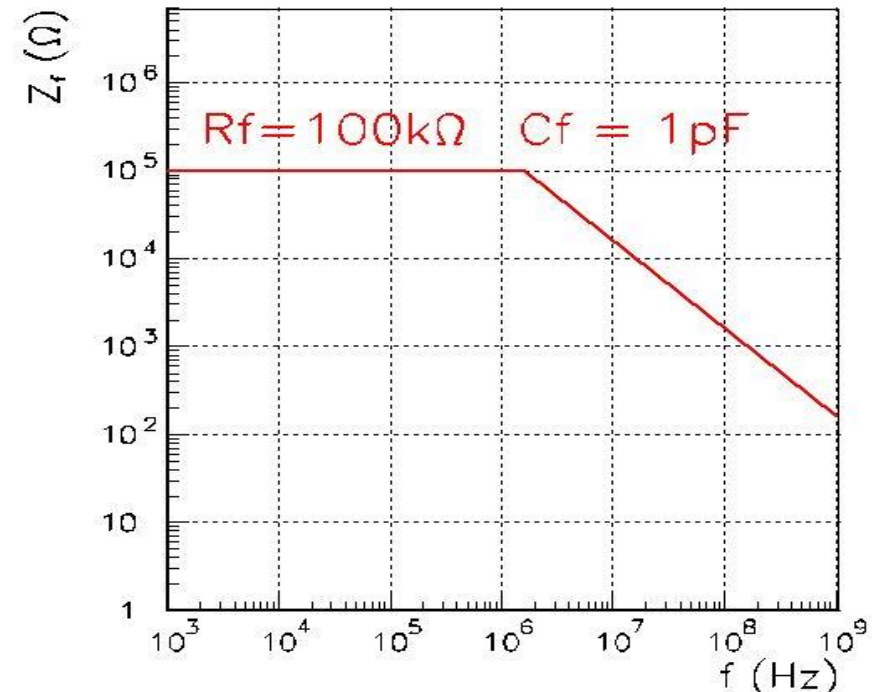
Transimpedance configuration

- Transfer function
 - Using a VFOA with gain G
 - $V_{out} - v_{in} = -Z_f i_f$
 - $V_{in} = Z_d (i_{in} - i_f) = -v_{out}/G$
 - $V_{out}(\omega)/i_{in}(\omega) = -Z_f / (1 + Z_f / GZ_d)$



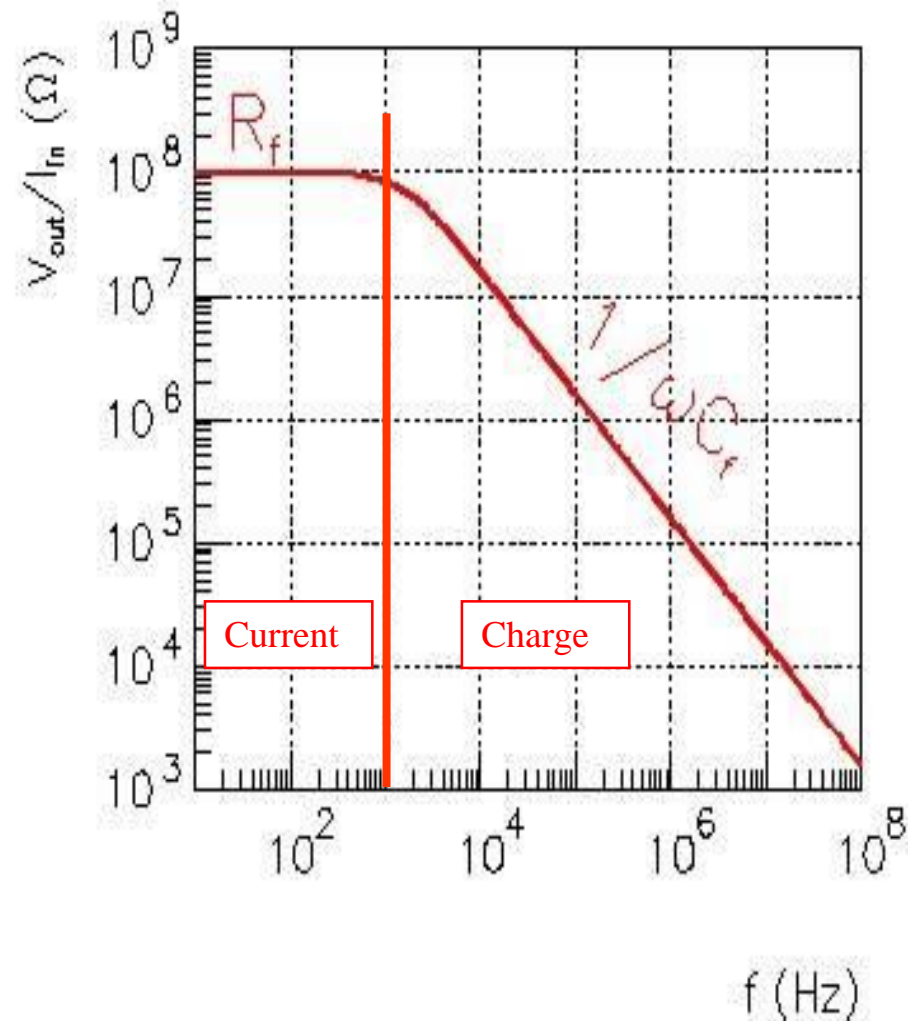
- $Z_f = R_f / (1 + j\omega R_f C_f)$
 - At $f \ll 1/2\pi R_f C_f$:
 $V_{out}(\omega)/i_{in}(\omega) = -R_f$
current preamp
 - At $f \gg 1/2\pi R_f C_f$:
 $V_{out}(\omega)/i_{in}(\omega) = -1/j\omega C_f$
charge preamp

- Ballistic deficit with charge preamp
 - Effect of finite gain : G_0
 - Output voltage «only» $Q C_d / G_0 C_f$



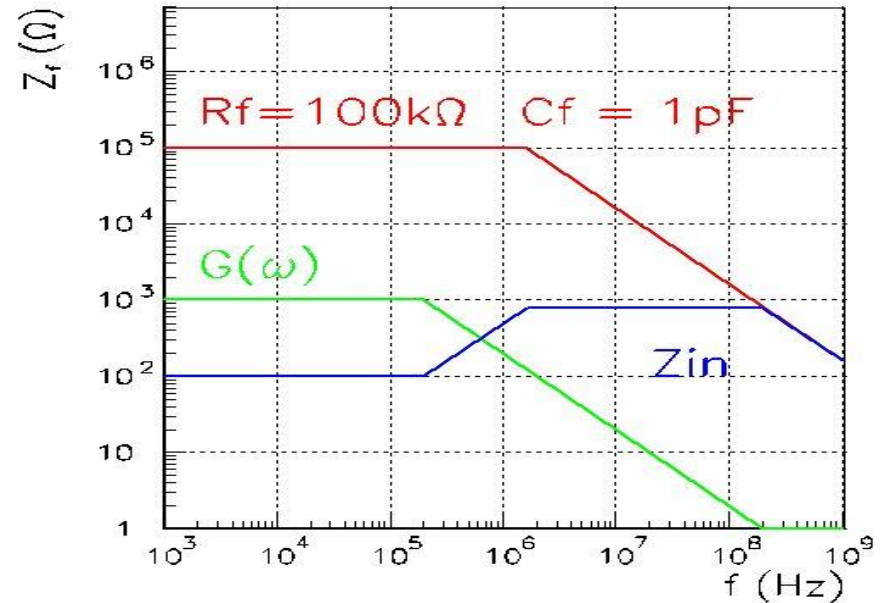
Transfer function

- Charge preamps
 - Best noise performance
 - Best with short signals
 - Best with small capacitance
- Current preamps
 - Best for long signals
 - Best for high counting rate
 - Significant parallel noise
- Charge preamps are not slow, they are long
- Current preamps are not faster, they are shorter (but easily unstable)

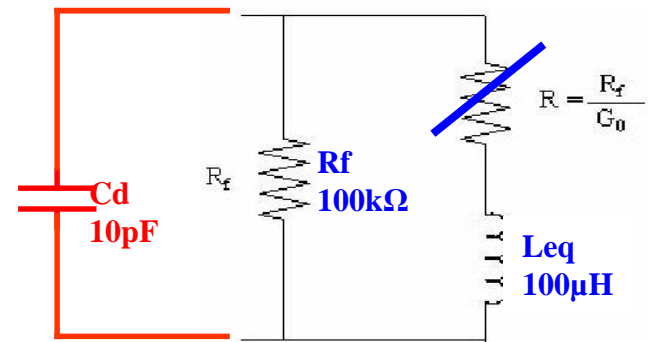


Input impedance

- Input impedance
 - $Z_{in} = Z_f / G+1$
 - $Z_{in} \rightarrow 0$ **virtual ground**
 - Minimizes sensitivity to detector impedance
 - Minimizes crosstalk
- Equivalent model
 - $G(\omega) = G_0 / (1 + j \omega / \omega_0)$
- Terms due to C_f
 - $Z_{in} = 1/j\omega G_0 C_f + 1/ G_0 \omega_0 C_f$
 - **Virtual resistance** : $R_{eq} = 1/ G_0 \omega_0 C_f$
- Terms due to R_f
 - $Z_{in} = R_f / G_0 + j \omega R_f / G_0 \omega_0$
 - **Virtual inductance** : $L_{eq} = R_f / G_0 \omega_0$
- Possible oscillatory behaviour with capacitive source



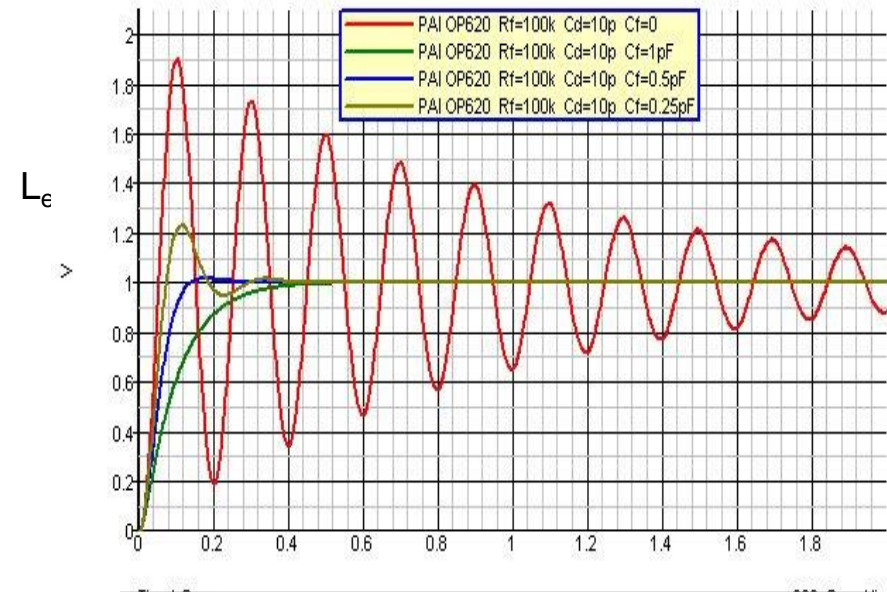
Input impedance or TZA



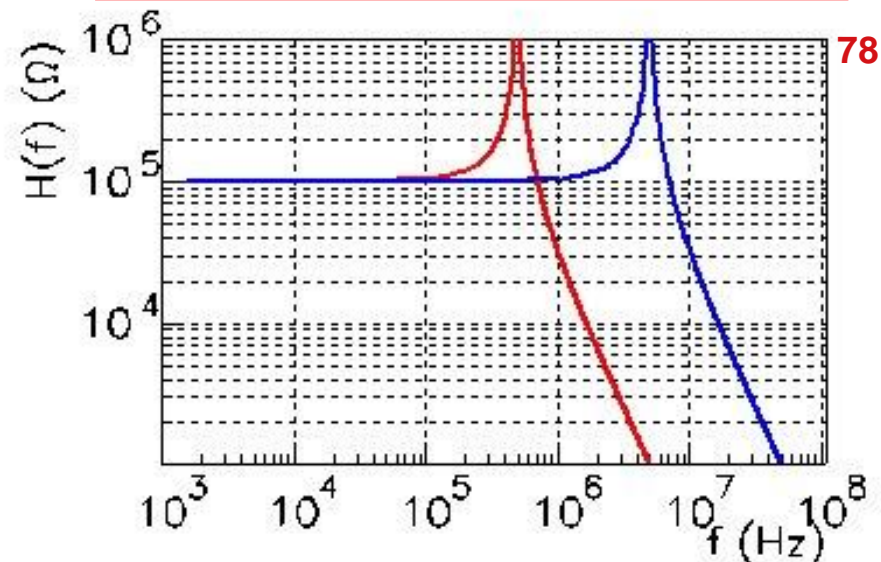
Equivalent circuit at the input

Current preamplifiers :

- Easily oscillatory
 - Unstable with capacitive detector
 - Inductive input impedance :
 $= R_f / \omega C_d$
 - Resonance at : $f_{res} = 1/2\pi \sqrt{L_{eq} C_d}$
 - Quality factor : $Q = R / \sqrt{L_{eq}/C_d}$
 - $Q > 1/2 \rightarrow$ ringing
 - Damping with capacitance C_f
 - $C_f = 2 \sqrt{(C_d/R_f G_0 \omega_0)}$
 - Easier with fast amplifiers
- In frequency domain
 - $H(j\omega) = -R_f / (1 + j\omega R_f C_d)$
 - $G(\omega) = G_0 / (1 + j\omega/\omega_0)$
 - $H = -R_f / (1 + j\omega R_f C_d/G_0 - \omega^2 R_f C_d / G_0 \omega_0)$

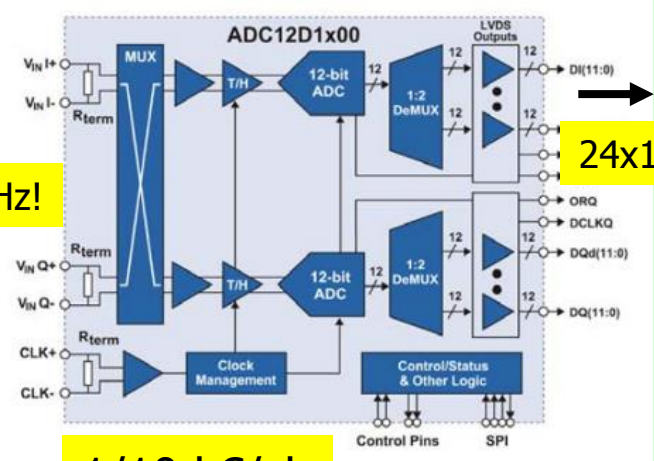


Step response of current sensitive preamp



FADCs

- 8 bits – 3 GS/s – 1.9 W → 24 Gbits/s
- 10 bits – 3 GS/s – 3.6 W → 30 Gbits/s
- 12 bits – 3.6 GS/s – 3.9 W → 43.2 Gbits/s
- 14 bits – 0.4 GS/s – 2.5 W → 5.6 Gbits/s



1.8 GHz!

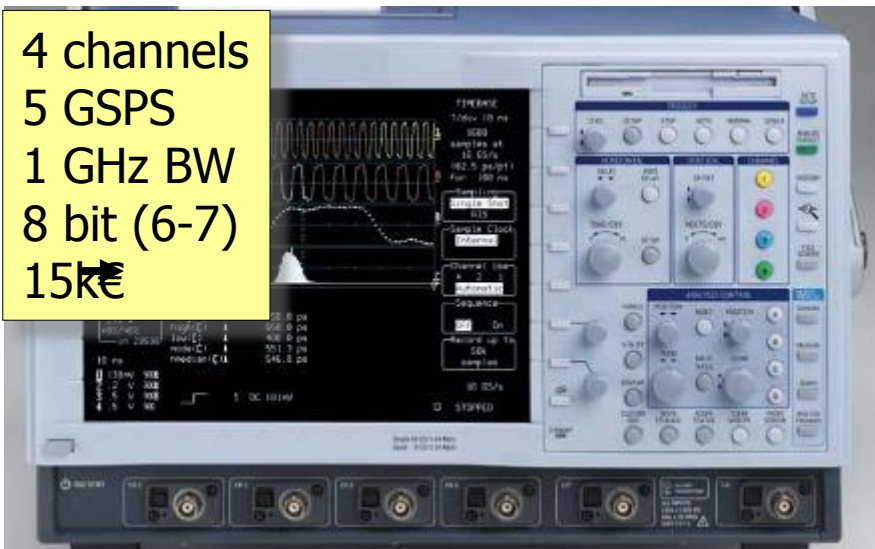
24x1.8 Gbits/s

1/10 k€/ch

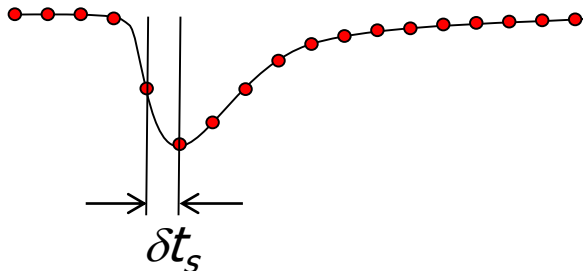
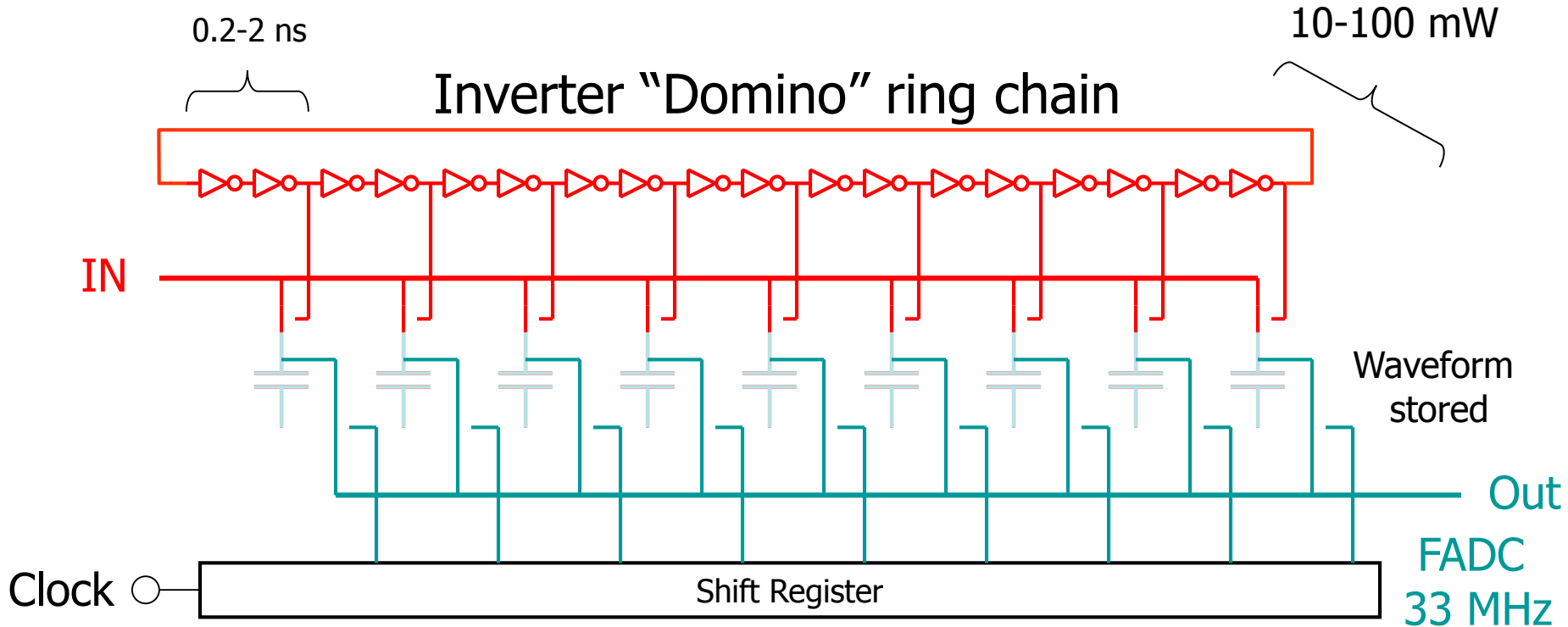
PX1500-4:
2 Channel
3 GS/s
8 bits



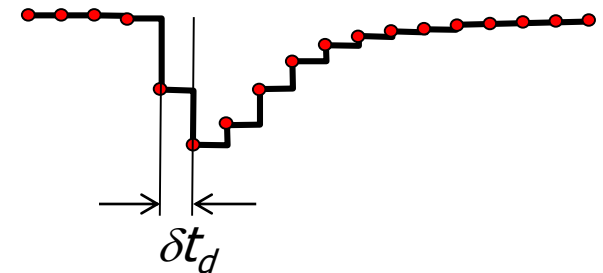
4 channels
5 GSPS
1 GHz BW
8 bit (6-7)
15k€



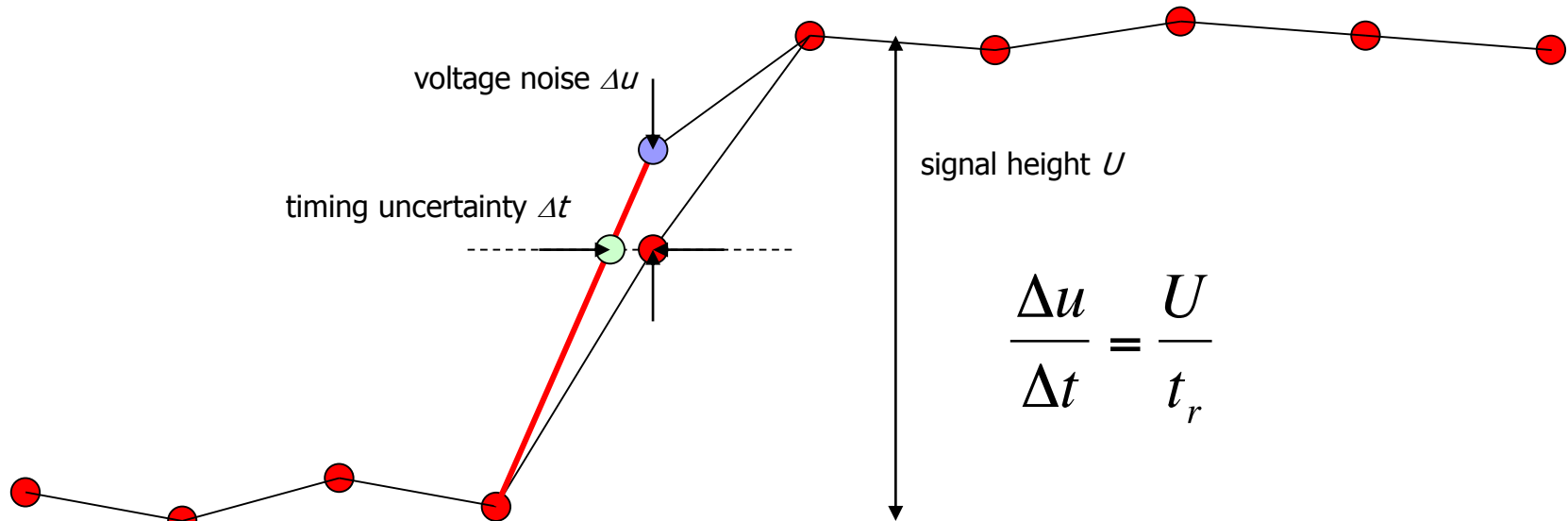
4 channels
5 GSPS
1 GHz BW
11.5 bits
900€
USB Power



"Time stretcher"
GHz \rightarrow MHz



How is timing resolution affected?



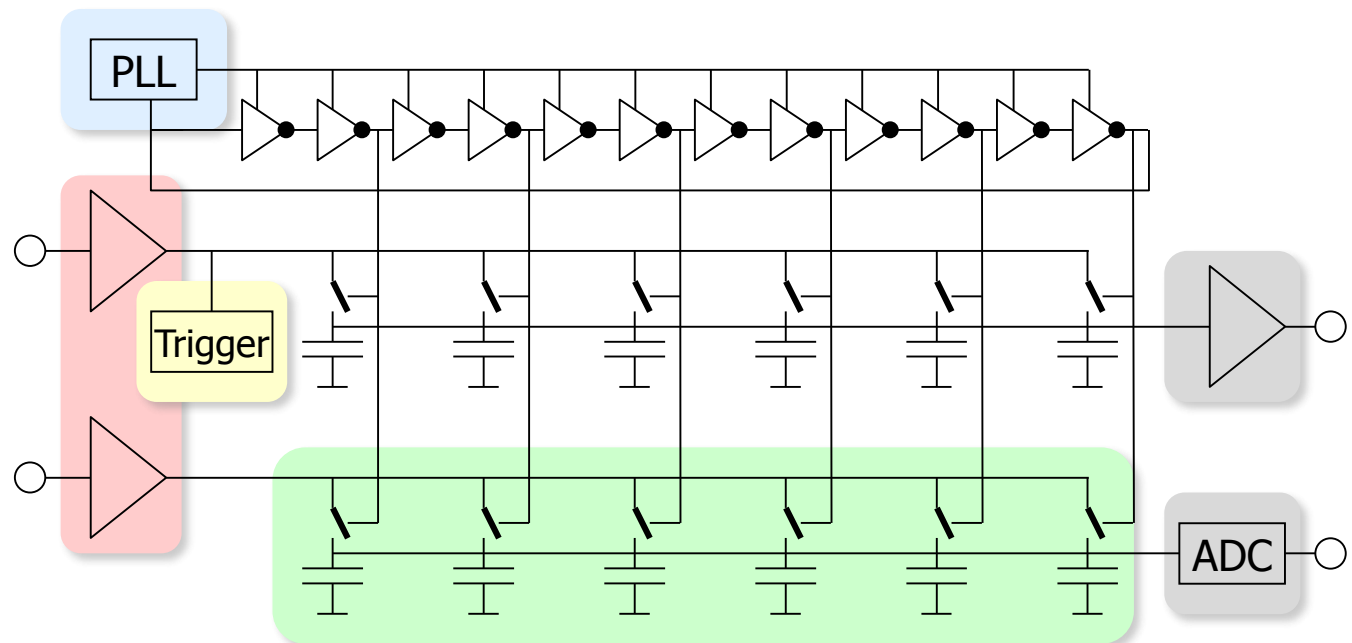
$$\Delta t = \frac{\Delta u}{U} \cdot \frac{1}{\sqrt{3f_s \cdot f_{3dB}}}$$

Assumes zero aperture jitter
↓

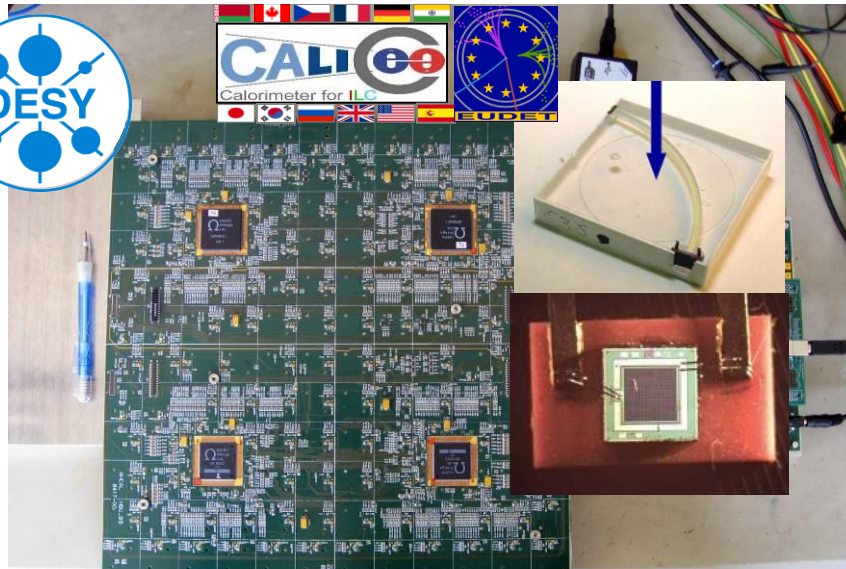
today:
optimized SNR:
next generation:

U	Δu	f_s	f_{3db}	Δt
100 mV	1 mV	2 GSPS	300 MHz	~10 ps
1 V	1 mV	2 GSPS	300 MHz	1 ps
1V	1 mV	10 GSPS	3 GHz	0.1 ps

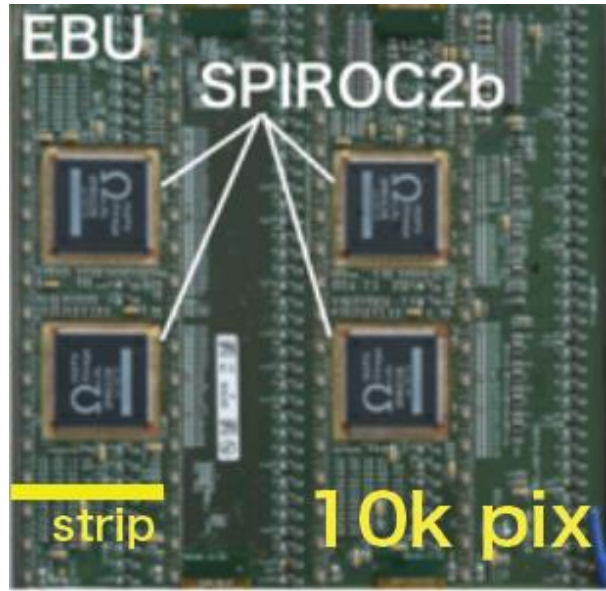
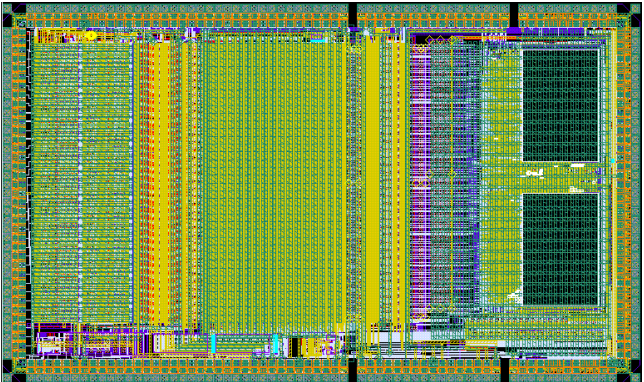
- CMOS process (typically 0.35 ... 0.13 μm) \rightarrow sampling speed
- Number of channels, sampling depth, differential input
- PLL for frequency stabilization
- Input buffer or passive input
- Analog output or (Wilkinson) ADC
- Internal trigger
- Exact design of sampling cell



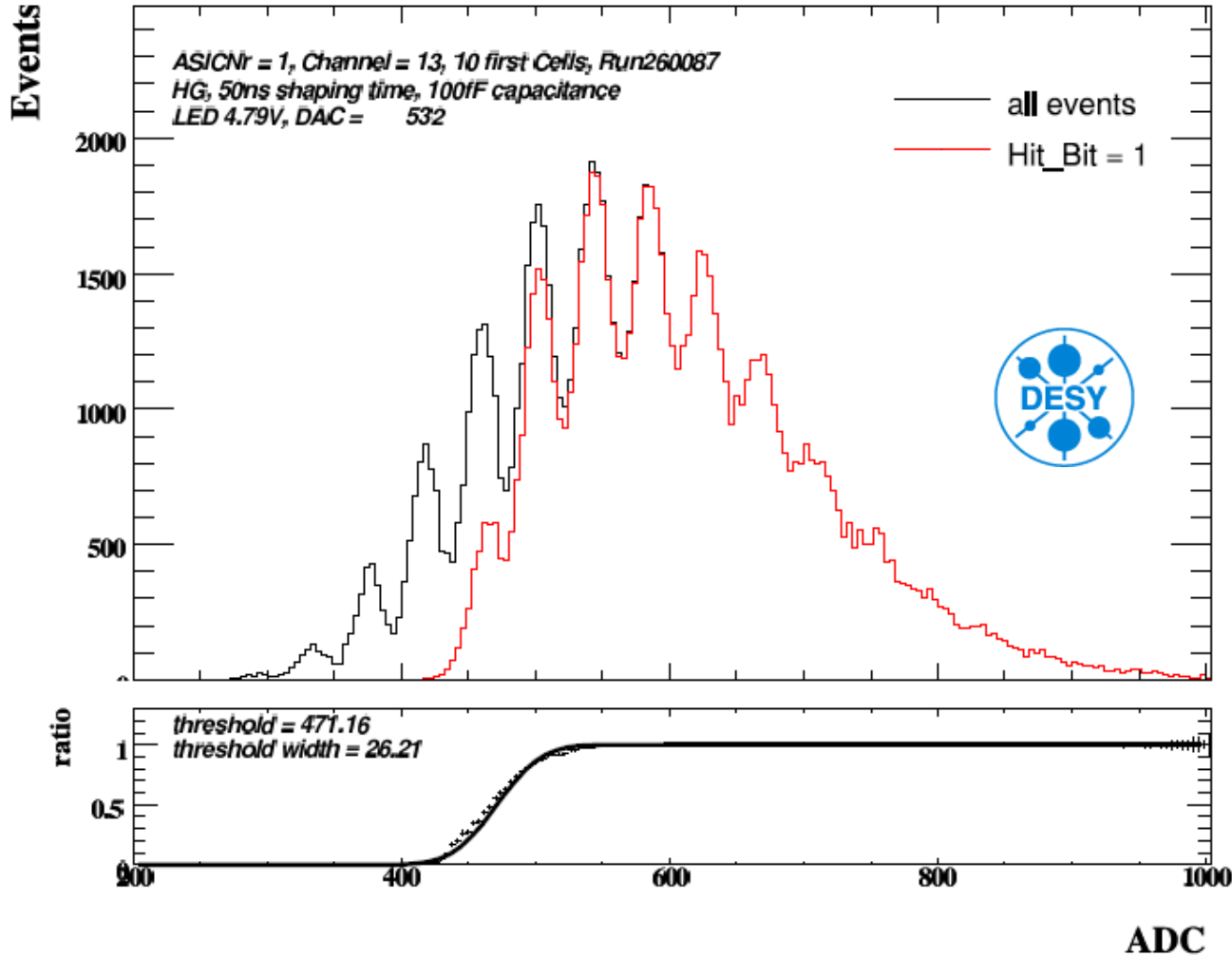
- Scintillating tiles and SiPM
 - Pioneered by DESY (EUDET/AIDA)
 - Chip embedded in detector : **low power !**
- SPIROC : Silicon Photomultiplier Integrated Readout Chip
 - Variant of SKIROC
 - 36 channels autotrigger 15bit readout
 - Energy measurement : 15 bits in 2 gains
 - Autotrigger down to 1/2 p.e. (80 fC for G=1E6)
 - Time measurement to ~1 ns
 - Power dissipation : 25 μ W/ch (power pulsed)



(0.36m)² Tiles + SiPM + SPIROC (144ch)



SiPM SPECTRUM with Autotrigger



- Time of Flight read-out chip with embedded TDC (25 ps bin) and ADC
- Dynamic range: 160 fC up to 400 pC
- 32 channels (negative input)
 - 32 trigger outputs
 - NOR32_chrage
 - NOR32 time
 - Charge measurement over 10 bits
 - Time measurement over 10 bits
 - One multiplexed charge output
- Common trigger threshold adjustment and 6bit-dac/channel for individual adjustment
- Variable shaping time of the charge shaper
- 32 8bit-input dac for SiPM HV adjustment
- Power consumption 6 mW/ch
- Front-end
 - Broad Band SiGe fast amplifier
 - Fast SiGe discriminator
 - 1 GHz overall bandwidth, gain = 25

AMS 0,35 μ m SiGe

